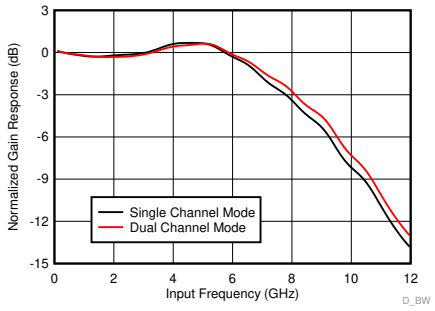
ADC08DJ3200 6.4GSPS 单通道或 3.2GSPS 双通道 8 位射频采样模数转换器 (ADC)

1 特性

- ADC 内核：
  - 8 位分辨率
  - 单通道模式下采样率高达 6.4GSPS
  - 双通道模式下采样率高达 3.2GSPS
- 性能规格 (f_{IN} = 997MHz)：
  - ENOB：7.8 位
  - SFDR：
    - 双通道模式：67dBFS
    - 单通道模式：62dBFS
- V_{CMI} 为 0V 时的缓冲模拟输入：
  - 模拟输入带宽 (-3dB)：8.0GHz
  - 可用输入频率范围：>10GHz
  - 满量程输入电压（V_{FS}，默认值）：0.8V_{PP}
  - 模拟输入共模电压 (V_{ICM})：0V
- 无噪声孔径延迟 (T_{AD}) 调节：
  - 采样精度控制：19fs 步长
  - 简化同步和交错
  - 温度和电压不变延迟
- 简便易用的同步 特性：
  - 自动 SYSREF 计时校准
  - 样片标记时间戳
- JESD204B 串行数据接口：
  - 支持子类 0 和 1
  - 最大通道速率：12.8Gbps
  - 多达 16 个通道可降低通道速率
- 功耗：2.8W
- 电源电压：1.1V、1.9V

ADC08DJ3200 测量的输入带宽



2 应用

- 卫星通信 (SATCOM)
- 合成孔径雷达 (SAR)
- 飞行时间和激光雷达测距
- 示波器和宽带数字转换器
- 微波回程连线
- 射频采样软件定义无线电 (SDR)
- 光谱测量

3 说明

ADC08DJ3200 器件是一款射频采样千兆采样模数转换器 (ADC)，可对从直流到 10GHz 以上的输入频率进行直接采样。在双通道下，ADC08DJ3200 的最大采样率为 3200MSPS，单通道模式下的最大采样率为 6400MSPS。通道数（双通道模式）和奎斯特带宽（单通道模式）的可编程交换功能可用于开发灵活的硬件，以满足高通道数或宽瞬时信号带宽 应用的需求。8.0GHz 的全功率输入带宽 (-3dB)，可用频率在双通道和单通道模式下均超过 -3dB，可对频率捷变系统的 L、S、C 和 X 频带进行直接射频采样。

ADC08DJ3200 采用具有多达 16 个串行通道和子类 1 兼容性的高速 JESD204B 输出接口，可实现确定性延迟和多器件同步。串行输出通道支持高达 12.8Gbps 的速率，并可配置交换位速率和通道数。 速率为 5GSPS 时，总共只需运行 4 个速率为 12.5Gbps 的通道，也可使用 16 个通道将通道速率降低至 3.125Gbps。 创新同步 具有无噪声孔径延迟 (T_{AD}) 调节和 SYSREF 窗口等创新的同步特性，简化了相控阵雷达和 MIMO 通信的系统设计。

器件信息(1)

器件型号	封装	封装尺寸（标称值）
ADC08DJ3200	FCBGA (144)	10.00mm × 10.00mm

(1) 如需了解所有可用封装，请参见数据表末尾的封装选项附录。

本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。 有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。 TI 不保证翻译的准确性和有效性。 在实际设计之前，请务必参考最新版本的英文版本。

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4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

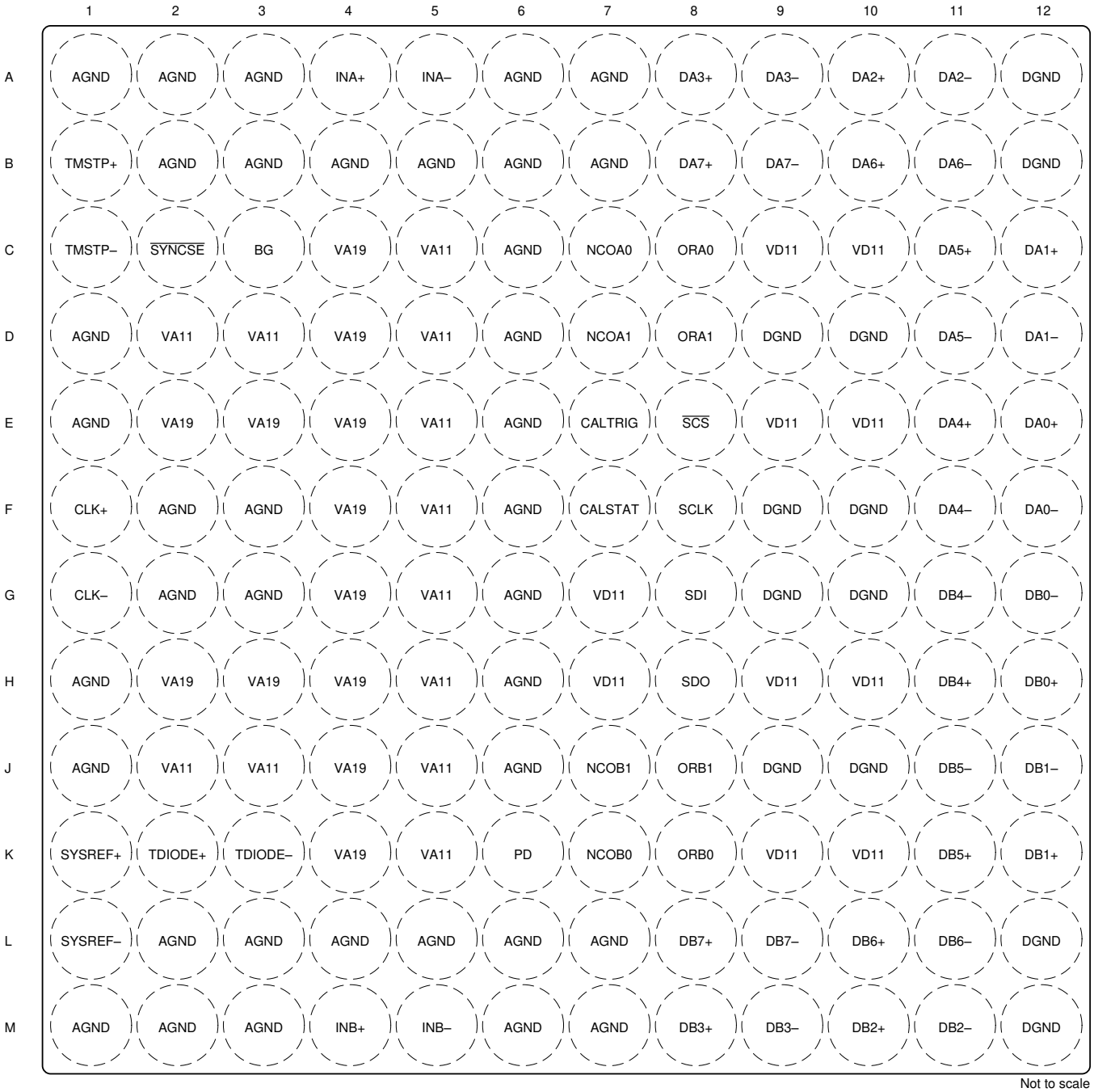
Changes from Original (February 2018) to Revision A **Page**

- Changed *Pin Functions* table listed in alphanumeric order by pin name. ... 4
- Changed FFT plots in Typical Characteristics section to show improved look ... 23
- 已更改 product description in *Overview* section ... 33
- 已更改 *Device Comparison* section to include all devices in the family. ... 34
- 已更改 location of *Analog Reference Voltage* section. ... 36
- 已更改 location of *Temperature Monitoring Diode* section. ... 38
- 已添加 requirement for at least 3 rising edges of SYSREF before SYSREF_POS output is valid. ... 40
- 已更改 note in *Power-Down Modes* section to caution note explaining reliable serializer operation instead of the information being presented under the *Pin Functions* table. ... 54
- 已更改 the *Low-Power Background Calibration (LPBG) Mode* section to provide additional detail of how to operate the device in low-power background calibration mode. ... 58
- 已添加 clarity about offset calibration when both CAL_OS and CAL_BG are enabled. ... 59
- 已更改 *Trimming* section to limit trimming to foreground (FG) calibration mode only to better reflect customer use cases and simplify the explanation. ... 60
- 已更改 additional clarity to *Offset Filtering* section to explain the frequency domain impact of the feature. ... 61

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5 Pin Configuration and Functions

AAV Package
144-Ball Flip Chip BGA
Top View



Not to scale

Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
AGND	A1, A2, A3, A6, A7, B2, B3, B4, B5, B6, B7, C6, D1, D6, E1, E6, F2, F3, F6, G2, G3, G6, H1, H6, J1, J6, L2, L3, L4, L5, L6, L7, M1, M2, M3, M6, M7	—	Analog supply ground. Tie AGND and DGND to a common ground plane (GND) on the circuit board.
BG	C3	O	Band-gap voltage output. This pin is capable of sourcing only small currents and driving limited capacitive loads, as specified in the *Recommended Operating Conditions* table. This pin can be left disconnected if not used.
CALSTAT	F7	O	Foreground calibration status output or device alarm output. Functionality is programmed through CAL_STATUS_SEL. This pin can be left disconnected if not used.
CALTRIG	E7	I	Foreground calibration trigger input. This pin is only used if hardware calibration triggering is selected in CAL_TRIG_EN, otherwise software triggering is performed using CAL_SOFT_TRIG. Tie this pin to GND if not used.
CLK+	F1	I	Device (sampling) clock positive input. The clock signal is strongly recommended to be AC-coupled to this input for best performance. In single-channel mode, the analog input signal is sampled on both the rising and falling edges. In dual-channel mode, the analog signal is sampled on the rising edge. This differential input has an internal untrimmed 100-Ω differential termination and is self-biased to the optimal input common-mode voltage as long as DEVCLK_LVPECL_EN is set to 0.
CLK–	G1	I	Device (sampling) clock negative input. TI strongly recommends using AC-coupling for best performance.
DA0+	E12	O	High-speed serialized data output for channel A, lane 0, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA0–	F12	O	High-speed serialized data output for channel A, lane 0, negative connection. This pin can be left disconnected if not used.
DA1+	C12	O	High-speed serialized data output for channel A, lane 1, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA1–	D12	O	High-speed serialized data output for channel A, lane 1, negative connection. This pin can be left disconnected if not used.
DA2+	A10	O	High-speed serialized-data output for channel A, lane 2, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA2–	A11	O	High-speed serialized-data output for channel A, lane 2, negative connection. This pin can be left disconnected if not used.
DA3+	A8	O	High-speed serialized-data output for channel A, lane 3, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA3–	A9	O	High-speed serialized-data output for channel A, lane 3, negative connection. This pin can be left disconnected if not used.
DA4+	E11	O	High-speed serialized data output for channel A, lane 4, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA4–	F11	O	High-speed serialized data output for channel A, lane 4, negative connection. This pin can be left disconnected if not used.
DA5+	C11	O	High-speed serialized data output for channel A, lane 5, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA5–	D11	O	High-speed serialized data output for channel A, lane 5, negative connection. This pin can be left disconnected if not used.

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Pin Functions (continued)

PIN		I/O	DESCRIPTION
NAME	NO.		
DA6+	B10	O	High-speed serialized data output for channel A, lane 6, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA6–	B11	O	High-speed serialized data output for channel A, lane 6, negative connection. This pin can be left disconnected if not used.
DA7+	B8	O	High-speed serialized data output for channel A, lane 7, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DA7–	B9	O	High-speed serialized data output for channel A, lane 7, negative connection. This pin can be left disconnected if not used.
DB0+	H12	O	High-speed serialized data output for channel B, lane 0, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB0–	G12	O	High-speed serialized data output for channel B, lane 0, negative connection. This pin can be left disconnected if not used.
DB1+	K12	O	High-speed serialized data output for channel B, lane 1, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB1–	J12	O	High-speed serialized data output for channel B, lane 1, negative connection. This pin can be left disconnected if not used.
DB2+	M10	O	High-speed serialized data output for channel B, lane 2, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB2–	M11	O	High-speed serialized data output for channel B, lane 2, negative connection. This pin can be left disconnected if not used.
DB3+	M8	O	High-speed serialized data output for channel B, lane 3, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB3–	M9	O	High-speed serialized data output for channel B, lane 3, negative connection. This pin can be left disconnected if not used.
DB4+	H11	O	High-speed serialized data output for channel B, lane 4, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB4–	G11	O	High-speed serialized data output for channel B, lane 4, negative connection. This pin can be left disconnected if not used.
DB5+	K11	O	High-speed serialized data output for channel B, lane 5, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB5–	J11	O	High-speed serialized data output for channel B, lane 5, negative connection. This pin can be left disconnected if not used.
DB6+	L10	O	High-speed serialized data output for channel B, lane 6, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB6–	L11	O	High-speed serialized data output for channel B, lane 6, negative connection. This pin can be left disconnected if not used.
DB7+	L8	O	High-speed serialized data output for channel B, lane 7, positive connection. This differential output must be AC-coupled and must always be terminated with a 100-Ω differential termination at the receiver. This pin can be left disconnected if not used.
DB7–	L9	O	High-speed serialized data output for channel B, lane 7, negative connection. This pin can be left disconnected if not used.
DGND	A12, B12, D9, D10, F9, F10, G9, G10, J9, J10, L12, M12	—	Digital supply ground. Tie AGND and DGND to a common ground plane (GND) on the circuit board.

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Pin Functions (continued)

PIN		I/O	DESCRIPTION
NAME	NO.		
INA+	A4	I	Channel A analog input positive connection. INA± is recommended for use in single channel mode for optimal performance. The differential full-scale input voltage is determined by the FS_RANGE_A register (see the *Full-Scale Voltage (VFS) Adjustment* section). This input is terminated to ground through a 50-Ω termination resistor. The input common-mode voltage is typically be set to 0 V (GND) and must follow the recommendations in the *Recommended Operating Conditions* table. This pin can be left disconnected if not used.
INA–	A5	I	Channel A analog input negative connection. INA± is recommended for use in single channel mode for optimal performance. See INA+ (pin A4) for detailed description. This input is terminated to ground through a 50-Ω termination resistor. This pin can be left disconnected if not used.
INB+	M4	I	Channel B analog input positive connection. INA± is recommended for use in single channel mode for optimal performance. The differential full-scale input voltage is determined by the FS_RANGE_B register (see the *Full-Scale Voltage (VFS) Adjustment* section). This input is terminated to ground through a 50-Ω termination resistor. The input common-mode voltage is typically be set to 0 V (GND) and must follow the recommendations in the *Recommended Operating Conditions* table. This pin can be left disconnected if not used.
INB–	M5	I	Channel B analog input negative connection. INA± is recommended for use in single channel mode for optimal performance. See INA+ (pin A4) for detailed description. This input is terminated to ground through a 50-Ω termination resistor. This pin can be left disconnected if not used.
NCOA0	C7	I	Tie this pin to GND.
NCOA1	D7	I	Tie this pin to GND.
NCOB0	K7	I	Tie this pin to GND.
NCOB1	J7	I	Tie this pin to GND.
ORA0	C8	O	Fast overrange detection status for channel A for the OVR_T0 threshold. When the analog input exceeds the threshold programmed into OVR_T0, this status indicator goes high. The minimum pulse duration is set by OVR_N. See the *ADC Overrange Detection* section for more information. This pin can be left disconnected if not used.
ORA1	D8	O	Fast overrange detection status for channel A for the OVR_T1 threshold. When the analog input exceeds the threshold programmed into OVR_T1, this status indicator goes high. The minimum pulse duration is set by OVR_N. See the *ADC Overrange Detection* section for more information. This pin can be left disconnected if not used.
ORB0	K8	O	Fast overrange detection status for channel B for the OVR_T0 threshold. When the analog input exceeds the threshold programmed into OVR_T0, this status indicator goes high. The minimum pulse duration is set by OVR_N. See the *ADC Overrange Detection* section for more information. This pin can be left disconnected if not used.
ORB1	J8	O	Fast overrange detection status for channel B for the OVR_T1 threshold. When the analog input exceeds the threshold programmed into OVR_T1, this status indicator goes high. The minimum pulse duration is set by OVR_N. See the *ADC Overrange Detection* section for more information. This pin can be left disconnected if not used.
PD	K6	I	This pin disables all analog circuits and serializer outputs when set high for temperature diode calibration only. Do not use this pin to power down the device for power savings. Tie this pin to GND during normal operation. For information regarding reliable serializer operation, see the *Power-Down Modes* section.
SCLK	F8	I	Serial interface clock. This pin functions as the serial-interface clock input that clocks the serial programming data in and out. The *Using the Serial Interface* section describes the serial interface in more detail. Supports 1.1-V to 1.9-V CMOS levels.
$\overline{\text{SCS}}$	E8	I	Serial interface chip select active low input. The *Using the Serial Interface* section describes the serial interface in more detail. Supports 1.1-V to 1.9-V CMOS levels. This pin has a 82-kΩ pullup resistor to VD11.
SDI	G8	I	Serial interface data input. The *Using the Serial Interface* section describes the serial interface in more detail. Supports 1.1-V to 1.9-V CMOS levels.
SDO	H8	O	Serial interface data output. The *Using the Serial Interface* section describes the serial interface in more detail. This pin is high impedance during normal device operation. This pin outputs 1.9-V CMOS levels during serial interface read operations. This pin can be left disconnected if not used.
$\overline{\text{SYNCSE}}$	C2	I	Single-ended JESD204B SYNC signal. This input is an active low input that is used to initialize the JESD204C serial link in 8B/10B modes when SYNC_SEL is set to 0. When toggled low this input initiates code group synchronization (see the *Code Group Synchronization (CGS)* section). After code group synchronization, this input must be toggled high to start the initial lane alignment sequence (see the *Initial Lane Alignment Sequence (ILAS)* section). A differential $\overline{\text{SYNC}}$ signal can be used instead by setting $\overline{\text{SYNC}}$_SEL to 1 and using TMSTP± as a differential $\overline{\text{SYNC}}$ input. Tie this pin to GND if differential $\overline{\text{SYNC}}$ (TMSTP±) is used as the JESD204B SYNC signal.

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Pin Functions (continued)

PIN		I/O	DESCRIPTION
NAME	NO.		
SYSREF+	K1	I	The SYSREF positive input is used to achieve synchronization and deterministic latency across the JESD204B interface. This differential input (SYSREF+ to SYSREF–) has an internal untrimmed 100-Ω differential termination and can be AC-coupled when SYSREF_LVPECL_EN is set to 0. This input is self-biased when SYSREF_LVPECL_EN is set to 0. The termination changes to 50 Ω to ground on each input pin (SYSREF+ and SYSREF–) and can be DC-coupled when SYSREF_LVPECL_EN is set to 1. This input is not self-biased when SYSREF_LVPECL_EN is set to 1 and must be biased externally to the input common-mode voltage range provided in the *Recommended Operating Conditions* table.
SYSREF–	L1	I	SYSREF negative input
TDIODE+	K2	I	Temperature diode positive (anode) connection. An external temperature sensor can be connected to TDIODE+ and TDIODE– to monitor the junction temperature of the device. This pin can be left disconnected if not used.
TDIODE–	K3	I	Temperature diode negative (cathode) connection. This pin can be left disconnected if not used.
TMSTP+	B1	I	Timestamp input positive connection or differential JESD204B $\overline{\text{SYNC}}$ positive connection. This input is a timestamp input, used to mark a specific sample, when TIMESTAMP_EN is set to 1. This differential input is used as the JESD204B SYNC signal input when SYNC_SEL is set to 1. This input can be used as both a timestamp and differential SYNC input at the same time, allowing feedback of the SYNC signal using the timestamp mechanism. TMSTP± uses active low signaling when used as a JESD204B SYNC. For additional usage information, see the *Timestamp* section. TMSTP_RECV_EN must be set to 1 to use this input. This differential input (TMSTP+ to TMSTP–) has an internal untrimmed 100-Ω differential termination and can be AC-coupled when TMSTP_LVPECL_EN is set to 0. The termination changes to 50 Ω to ground on each input pin (TMSTP+ and TMSTP–) and can be DC coupled when TMSTP_LVPECL_EN is set to 1. This pin is not self-biased and therefore must be externally biased for both AC- and DC-coupled configurations. The common-mode voltage must be within the range provided in the *Recommended Operating Conditions* table when both AC and DC coupled. This pin can be left disconnected and disabled (TMSTP_RECV_EN = 0) if $\overline{\text{SYNCSE}}$ is used for JESD204B SYNC and timestamp is not required.
TMSTP–	C1	I	Timestamp input positive connection or differential JESD204B $\overline{\text{SYNC}}$ negative connection. This pin can be left disconnected and disabled (TMSTP_RECV_EN = 0) if $\overline{\text{SYNCSE}}$ is used for JESD204B SYNC and timestamp is not required.
VA11	C5, D2, D3, D5, E5, F5, G5, H5, J2, J3, J5, K5	I	1.1-V analog supply
VA19	C4, D4, E2, E3, E4, F4, G4, H2, H3, H4, J4, K4	I	1.9-V analog supply
VD11	C9, C10, E9, E10, G7, H7, H9, H10, K9, K10	I	1.1-V digital supply

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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Supply voltage range	VA19(2)	–0.3	2.35	V
	VA11(2)	–0.3	1.32	
	VD11(3)	–0.3	1.32	
	Voltage between VD11 and VA11	–1.32	1.32	
Voltage between AGND and DGND		–0.1	0.1	V
Pin voltage range	DA[7:0]+, DA[7:0]–, DB[7:0]+, DB[7:0]–, TMSTP+, TMSTP–(3)	–0.5	min(1.32, VD11+0.5)	V
	CLK+, CLK–, SYSREF+, SYSREF–(2)	–0.5	min(1.32, VA11+0.5)	
	BG, TDIODE+, TDIODE–(2)	–0.5	min(2.35, VA19+0.5)	
	INA+, INA–, INB+, INB–(2)	–1	1	
	CALSTAT, CALTRIG, NCOA0, NCOA1, NCOB0, NCOB1, $\overline{\text{ORA0}}$, ORA1, ORB0, $\overline{\text{ORB1}}$, PD, SCLK, $\overline{\text{SCS}}$, SDI, SDO, $\overline{\text{SYNCSE}}$(2)	–0.5	VA19+0.5	
Peak input current (any input except INA+, INA–, INB+, INB–)		–25	25	mA
Peak input current (INA+, INA–, INB+, INB–)		–50	50	mA
Peak RF input power (INA+, INA–, INB+, INB–)	Single-ended with $Z_{S\text{-}SE}$ = 50 Ω or differential with $Z_{S\text{-}DIFF}$ = 100 Ω		16.4	dBm
Peak total input current (sum of absolute value of all currents forced in or out, not including power-supply current)			100	mA
Operating free-air temperature, T_A		–40	85	°C
Operating junction temperature, T_J			150	°C
Storage temperature, T_{stg}		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) Measured to AGND.
(3) Measured to DGND.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2500	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

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6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V_{DD}	Supply voltage range	VA19, analog 1.9-V supply(1)	1.8	1.9	2.0	V
		VA11, analog 1.1-V supply(1)	1.05	1.1	1.15	
		VD11, digital 1.1-V supply(2)	1.05	1.1	1.15	
V_{CMI}	Input common-mode voltage	INA+, INA–, INB+, INB–(1)	–50	0	100	mV
		CLK+, CLK–, SYSREF+, SYSREF–(1)(3)	0	0.3	0.55	V
		TMSTP+, TMSTP–(1)(4)	0	0.3	0.55	
V_{ID}	Input voltage, peak-to-peak differential	CLK+ to CLK–, SYSREF+ to SYSREF–, TMSTP+ to TMSTP–	0.4	1.0	2.0	$V_{PP-DIFF}$
		INA+ to INA–, INB+ to INB–(5)			1.0	
V_{IH}	High-level input voltage	CALTRIG, NCOA0, NCOA1, NCOB0, NCOB1, PD, SCLK, $\overline{SCS}$, SDI, $\overline{SYNCSE}$(1)	0.7			V
V_{IL}	Low-level input voltage	CALTRIG, NCOA0, NCOA1, NCOB0, NCOB1, PD, SCLK, $\overline{SCS}$, SDI, $\overline{SYNCSE}$(1)			0.45	V
I_{C_TD}	Temperature diode input current	TDIODE+ to TDIODE–		100		µA
C_L	BG max load capacitance				50	pF
I_O	BG max output current				100	µA
DC	Input clock duty cycle		30%	50%	70%	
T_A	Operating free-air temperature		–40		85	°C
T_J	Operating junction temperature(6)(7)				105	°C

(1) Measured to AGND.
(2) Measured to DGND.
(3) TI strongly recommends that CLK± be AC-coupled with DEVCLK_LVPECL_EN set to 0 to allow CLK± to self-bias to the optimal input common-mode voltage for best performance. TI recommends AC-coupling for SYSREF± unless DC-coupling is required, in which case the LVPECL input mode must be used (SYSREF_LVPECL_EN = 1).
(4) TMSTP± does not have internal biasing that requires TMSTP± to be biased externally whether AC-coupled with TMSTP_LVPECL_EN = 0 or DC-coupled with TMSTP_LVPECL_EN = 1.
(5) The ADC output code saturates when V_{ID} for INA± or INB± exceeds the programmed full-scale voltage (V_{FS}) set by FS_RANGE_A for INA± or FS_RANGE_B for INB±.
(6) Prolonged use above this junction temperature may increase the device failure-in-time (FIT) rate.
(7) Tested up to 1000 hours continuous operation at T_J = 125°C. See the *Absolute Maximum Ratings* table for the absolute maximum operational temperature.

6.4 Thermal Information

THERMAL METRIC(1)		ADC08DJ3200 AAV (FCBGA) 144 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	25.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	1.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	8.2	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.1	°C/W
ψ_{JB}	Junction-to-board characterization parameter	8.2	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

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6.5 Electrical Characteristics: DC Specifications

typical values are at T_A = 25°C, VA19 = 1.9 V , VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DC ACCURACY						
	Resolution	Resolution with no missing codes		8		Bits
DNL	Differential nonlinearity			±0.15		LSB
INL	Integral nonlinearity			±0.3		LSB
ANALOG INPUTS (INA+, INA–, INB+, INB–)						
V_{OFF}	Offset error	Default full-scale voltage, OS_CAL disabled		±0.6		mV
V_{OFF_ADJ}	Input offset voltage adjustment range	Available offset correction range (see OS_CAL or OADJ_x_INx)		±55		mV
V_{OFF_DRIFT}	Offset drift	Foreground calibration at nominal temperature only		23		µV/°C
		Foreground calibration at each temperature		0		
V_{IN_FSR}	Analog differential input full-scale range	Default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000)	750	800	850	mV_{PP}
		Maximum full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xFFFF)	1000	1040		
		Minimum full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0x2000)		480	500	
$V_{IN_FSR_DRIFT}$	Analog differential input full-scale range drift	Default FS_RANGE_A and FS_RANGE_B setting, foreground calibration at nominal temperature only, inputs driven by 50-Ω source, includes effect of R_{IN} drift		–0.01		%/°C
		Default FS_RANGE_A and FS_RANGE_B setting, foreground calibration at each temperature, inputs driven by 50-Ω source, includes effect of R_{IN} drift		0.03		
$V_{IN_FSR_MATCH}$	Analog differential input full-scale range matching	Matching between INA+, INA– and INB+, INB–, default setting, dual-channel mode		0.625%		
R_{IN}	Single-ended input resistance to AGND	Each input pin is terminated to AGND, measured at T_A = 25°C	48	50	52	Ω
R_{IN_TEMPCO}	Input termination linear temperature coefficient			17.6		mΩ/°C
C_{IN}	Single-ended input capacitance	Single-channel mode at DC		0.4		pF
		Dual-channel mode at DC		0.4		
TEMPERATURE DIODE CHARACTERISTICS (TDIODE+, TDIODE–)						
ΔV_{BE}	Temperature diode voltage slope	Forced forward current of 100 µA. Offset voltage (approximately 0.792 V at 0°C) varies with process and must be measured for each part. Offset measurement must be done with the device unpowered or with the PD pin asserted to minimize device self-heating. Assert the PD pin only long enough to take the offset measurement.		–1.6		mV/°C
BAND-GAP VOLTAGE OUTPUT (BG)						
V_{BG}	Reference output voltage	I_L ≤ 100 µA		1.1		V
V_{BG_DRIFT}	Reference output temperature drift	I_L ≤ 100 µA		–64		µV/°C

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Electrical Characteristics: DC Specifications (continued)

typical values are at T_A = 25°C, VA19 = 1.9 V , VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
CLOCK INPUTS (CLK+, CLK–, SYSREF+, SYSREF–, TMSTP+, TMSTP–)						
Z_T	Internal termination	Differential termination with DEVCLK_LVPECL_EN = 0, SYSREF_LVPECL_EN = 0, and TMSTP_LVPECL_EN = 0		110		Ω
		Single-ended termination to GND (per pin) with DEVCLK_LVPECL_EN = 0, SYSREF_LVPECL_EN = 0, and TMSTP_LVPECL_EN = 0		55		
V_{CM}	Input common-mode voltage, self-biased	Self-biasing common-mode voltage for CLK± when AC-coupled (DEVCLK_LVPECL_EN must be set to 0)		0.26		V
		Self-biasing common-mode voltage for SYSREF± when AC-coupled (SYSREF_LVPECL_EN must be set to 0) and with receiver enabled (SYSREF_RECV_EN = 1)		0.29		
		Self-biasing common mode voltage for SYSREF± when AC-coupled (SYSREF_LVPECL_EN must be set to 0) and with receiver disabled (SYSREF_RECV_EN = 0)		VA11		
C_{L_DIFF}	Differential input capacitance	Between positive and negative differential input pins		0.1		pF
C_{L_SE}	Single-ended input capacitance	Each input to ground		0.5		pF
SERDES OUTPUTS (DA[7:0]+, DA[7:0]–, DB[7:0]+, DB[7:0]–)						
V_{OD}	Differential output voltage, peak-to-peak	100-Ω load	550	600	650	$mV_{PP-DIFF}$
V_{CM}	Output common mode voltage	AC coupled		VD11 / 2		V
Z_{DIFF}	Differential output impedance			100		Ω
CMOS INTERFACE (SCLK, SDI, SDO, $\overline{SCS}$, PD, NCOA0, NCOA1, NCOB0, NCOB1, CALSTAT, CALTRIG, ORA0, ORA1, ORB0, ORB1, $\overline{SYNCSE}$)						
I_{IH}	High-level input current		–40		40	µA
I_{IL}	Low-level input current		–40		40	µA
C_I	Input capacitance			2		pF
V_{OH}	High-level output voltage	I_{LOAD} = –400 µA	1.65			V
V_{OL}	Low-level output voltage	I_{LOAD} = 400 µA			150	mV

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6.6 Electrical Characteristics: Power Consumption

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{VA19}	1.9-V analog supply current	Power mode 1: single-channel mode, JMODE 5 (8 lanes), foreground calibration		899	950	mA
I_{VA11}	1.1-V analog supply current			501	620	mA
I_{VD11}	1.1-V digital supply current			451	650	mA
P_{DIS}	Power dissipation			2.8	3.2	W
I_{VA19}	1.9-V analog supply current	Power mode 2: dual-channel mode, JMODE 7 (8 lanes), foreground calibration		981		mA
I_{VA11}	1.1-V analog supply current			501		mA
I_{VD11}	1.1-V digital supply current			463		mA
P_{DIS}	Power dissipation			2.9		W
I_{VA19}	1.9-V analog supply current	Power mode 3: single-channel mode, JMODE 5 (8 lanes), background calibration		1179		mA
I_{VA11}	1.1-V analog supply current			602		mA
I_{VD11}	1.1-V digital supply current			467		mA
P_{DIS}	Power dissipation			3.4		W
I_{VA19}	1.9-V analog supply current	Power mode 4: dual-channel mode, JMODE 18 (16 lanes), foreground calibration		981		mA
I_{VA11}	1.1-V analog supply current			501		mA
I_{VD11}	1.1-V digital supply current			447		mA
P_{DIS}	Power dissipation			2.9		W
I_{VA19}	1.9-V analog supply current	Power mode 5: single-channel mode, JMODE 4 (4 lanes), foreground calibration, f_{CLK} = 2.5 GHz		899		mA
I_{VA11}	1.1-V analog supply current			519		mA
I_{VD11}	1.1-V digital supply current			363		mA
P_{DIS}	Power dissipation			2.6		W

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6.7 Electrical Characteristics: AC Specifications (Dual-Channel Mode)

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 18, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
FPBW	Full-power input bandwidth (–3 dB)(1)	Foreground calibration		8.1		GHz
		Background calibration		8.1		
XTALK	Channel-to-channel crosstalk	Dual-channel mode, aggressor = 400 MHz, –1 dBFS		–92		dB
		Dual-channel mode, aggressor = 3 GHz, –1 dBFS		–67		
		Dual-channel mode, aggressor = 6 GHz, –1 dBFS		–61		
CER	Code error rate	Maximum CER, does not include SerDes bit-error rate (BER)		10^{-18}		Errors/ sample
$NOISE_{DC}$	DC input noise standard deviation	No input, foreground calibration, excludes DC offset, includes fixed interleaving spur (f_S / 2 spur)		0.45		LSB
SNR	Signal-to-noise ratio, large signal, excluding DC, HD2 to HD9 and interleaving spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		49.1		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		49.3		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		49.0		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	47.0	48.8		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		49.0		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		48.3		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		47.8		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		47.2		
SNR	Signal-to-noise ratio, small signal, excluding DC, HD2 to HD9 and interleaving spurs	f_{IN} = 347 MHz, A_{IN} = –16 dBFS		49.1		dBFS
		f_{IN} = 997 MHz, A_{IN} = –16 dBFS		49.1		
		f_{IN} = 2397 MHz, A_{IN} = –16 dBFS		49.1		
		f_{IN} = 4997 MHz, A_{IN} = –16 dBFS		49.4		
		f_{IN} = 6397 MHz, A_{IN} = –16 dBFS		49.2		
		f_{IN} = 8197 MHz, A_{IN} = –16 dBFS		49.4		
SINAD	Signal-to-noise and distortion ratio, large signal, excluding DC and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		48.8		dBFS
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		48.7		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	46.3	48.5		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		47.0		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		46.2		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		44.8		
ENOB	Effective number of bits, large signal, excluding DC and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		7.8		Bits
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		7.8		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	7.4	7.8		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		7.5		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		7.4		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		7.1		

(1) Full-power input bandwidth (FPBW) is defined as the input frequency where the reconstructed output of the ADC drops 3 dB below the power of a full-scale input signal at a low input frequency. Useable bandwidth may exceed the –3-dB full-power input bandwidth.

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Electrical Characteristics: AC Specifications (Dual-Channel Mode) (continued)

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 18, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SFDR	Spurious-free dynamic range, large signal, excluding DC and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		69		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		68		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		67		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	55	66		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		62		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		57		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		55		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		52		
SFDR	Spurious-free dynamic range, small signal, excluding DC and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –16 dBFS		67		dBFS
		f_{IN} = 997 MHz, A_{IN} = –16 dBFS		67		
		f_{IN} = 2397 MHz, A_{IN} = –16 dBFS		67		
		f_{IN} = 4997 MHz, A_{IN} = –16 dBFS		67		
		f_{IN} = 6397 MHz, A_{IN} = –16 dBFS		67		
		f_{IN} = 8197 MHz, A_{IN} = –16 dBFS		67		
f_S / 2	f_S / 2 fixed interleaving spur, independent of input signal	No input		–70	–55	dBFS
HD2	Second-order harmonic distortion	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–75		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		–73		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–75		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–73	–60	
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		–72		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–68		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–67		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–61		
HD3	Third-order harmonic distortion	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–71		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		–69		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–69		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–67	–60	
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A and FS_RANGE_B setting, foreground calibration		–62		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–57		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–55		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–52		

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Electrical Characteristics: AC Specifications (Dual-Channel Mode) (continued)

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 18, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_S / 2 – f_{IN}$	$f_S / 2 – f_{IN}$ interleaving spur, signal dependent	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–72		dBFS
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–70		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–69	–55	
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–66		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–64		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–63		
SPUR	Worst harmonic, fourth-order distortion or higher	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–74		dBFS
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–71		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–73	–60	
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–78		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–78		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–78		
IMD3	Third-order intermodulation distortion	f_{IN} = 347 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–92		dBFS
		f_{IN} = 997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–80		
		f_{IN} = 2485 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–71		
		f_{IN} = 4997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–63		
		f_{IN} = 5997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–60		
		f_{IN} = 7997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–49		

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6.8 Electrical Characteristics: AC Specifications (Single-Channel Mode)

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = 0xA000), input signal applied to INA±, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
FPBW	Full-power input bandwidth (–3 dB)(1)	Foreground calibration		7.9		GHz
		Background calibration		7.9		
CER	Code error rate	Maximum CER, does not include SerDes bit-error rate (BER)		10^{-18}		Errors/ sample
$NOISE_{DC}$	DC input noise standard deviation	No input, foreground calibration, excludes DC offset, includes fixed interleaving spurs (f_S / 2 and f_S / 4 spurs)		0.35		LSB
SNR	Signal-to-noise ratio, large signal, excluding DC, HD2 to HD9 and interleaving spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		49.0		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		49.2		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		49.0		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	47.0	48.8		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		49.0		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		48.2		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		47.9		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		47.1		
SNR	Signal-to-noise ratio, small signal, excluding DC, HD2 to HD9 and interleaving spurs	f_{IN} = 347 MHz, A_{IN} = –16 dBFS		49.2		dBFS
		f_{IN} = 997 MHz, A_{IN} = –16 dBFS		49.2		
		f_{IN} = 2397 MHz, A_{IN} = –16 dBFS		49.2		
		f_{IN} = 4997 MHz, A_{IN} = –16 dBFS		49.2		
		f_{IN} = 6397 MHz, A_{IN} = –16 dBFS		49.2		
		f_{IN} = 8197 MHz, A_{IN} = –16 dBFS		49.2		
SINAD	Signal-to-noise and distortion ratio, large signal, excluding DC and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		48.7		dBFS
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		48.4		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	45.1	48.0		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		47.2		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		46.6		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		44.8		
ENOB	Effective number of bits, large signal, excluding DC and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		7.8		~~!~~ ~~dBFS~~!~Bits
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		7.8		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	7.2	7.7		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		7.6		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		7.5		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		7.1		

(1) Full-power input bandwidth (FPBW) is defined as the input frequency where the reconstructed output of the ADC drops 3 dB below the power of a full-scale input signal at a low input frequency. Useable bandwidth may exceed the –3-dB full-power input bandwidth.

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Electrical Characteristics: AC Specifications (Single-Channel Mode) (continued)

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = 0xA000), input signal applied to INA±, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SFDR	Spurious free dynamic range, large signal, excluding DC, f_S / 4 and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		66		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		64		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		62		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS	45	58		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		54		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		59		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		57		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		52		
SFDR	Spurious free dynamic range, small signal, excluding DC, f_S / 4 and f_S / 2 fixed spurs	f_{IN} = 347 MHz, A_{IN} = –16 dBFS		68		dBFS
		f_{IN} = 997 MHz, A_{IN} = –16 dBFS		68		
		f_{IN} = 2397 MHz, A_{IN} = –16 dBFS		68		
		f_{IN} = 4997 MHz, A_{IN} = –16 dBFS		68		
		f_{IN} = 6397 MHz, A_{IN} = –16 dBFS		68		
		f_{IN} = 8197 MHz, A_{IN} = –16 dBFS		67		
f_S / 2	f_S / 2 fixed interleaving spur, independent of input signal	No input, foreground calibration, OS_CAL disabled, spur can be improved by running OS_CAL		–65		dBFS
f_S / 4	f_S / 4 fixed interleaving spur, independent of input signal	No input		–64	–55	dBFS
HD2	Second-order harmonic distortion	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–74		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		–71		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–72		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–75	–60	
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		–72		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–72		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–68		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–68		
HD3	Third-order harmonic distortion	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–71		dBFS
		f_{IN} = 347 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		–69		
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–68		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–68	–60	
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS, maximum FS_RANGE_A setting, foreground calibration		–63		
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–59		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–58		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–55		

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Electrical Characteristics: AC Specifications (Single-Channel Mode) (continued)

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = 0xA000), input signal applied to INA±, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_S / 2 – f_{IN}	f_S / 2 – f_{IN} interleaving spur, signal dependent	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–68		dBFS
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–62		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–58	–45	
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–62		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–63		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–53		
f_S / 4 ± f_{IN}	f_S / 4 ± f_{IN} interleaving spurs, signal dependent	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–72		dBFS
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–72		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–72	–60	
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–68		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–65		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–63		
SPUR	Worst harmonic, fourth-order distortion or higher	f_{IN} = 347 MHz, A_{IN} = –1 dBFS		–73		dBFS
		f_{IN} = 997 MHz, A_{IN} = –1 dBFS		–72		
		f_{IN} = 2397 MHz, A_{IN} = –1 dBFS		–73	–60	
		f_{IN} = 4997 MHz, A_{IN} = –1 dBFS		–80		
		f_{IN} = 6397 MHz, A_{IN} = –1 dBFS		–82		
		f_{IN} = 8197 MHz, A_{IN} = –1 dBFS		–79		
IMD3	Third-order intermodulation distortion	f_{IN} = 347 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–83		dBFS
		f_{IN} = 997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–79		
		f_{IN} = 2485 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–70		
		f_{IN} = 4997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–64		
		f_{IN} = 5997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–62		
		f_{IN} = 7997 MHz ± 2.5 MHz, A_{IN} = –7 dBFS per tone		–52		

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6.9 Timing Requirements

			MIN	NOM	MAX	UNIT
DEVICE (Sampling) CLOCK (CLK+, CLK–)						
f_{CLK}	Input clock frequency (CLK+, CLK–), both single-channel and dual-channel modes(1)		800		3200	MHz
SYSREF (SYSREF+, SYSREF–)						
$t_{INV(SYSREF)}$	Width of invalid SYSREF capture region of CLK± period, indicating setup or hold time violation, as measured by the SYSREF_POS status register(2)			48		ps
$t_{INV(TEMP)}$	Drift of invalid SYSREF capture region over temperature, positive number indicates a shift toward the MSB of the SYSREF_POS register			0		ps/°C
$t_{INV(VA11)}$	Drift of invalid SYSREF capture region over the VA11 supply voltage, positive number indicates a shift toward the MSB of the SYSREF_POS register			0.36		ps/mV
$t_{STEP(SP)}$	Delay of the SYSREF_POS LSB	SYSREF_ZOOM = 0		77		ps
		SYSREF_ZOOM = 1		24		
$t_{(PH_SYS)}$	Minimum SYSREF± assertion duration after a SYSREF± rising edge event			4		ns
$t_{(PL_SYS)}$	Minimum SYSREF± de-assertion duration after a SYSREF± falling edge event			1		ns
JESD204B SYNC TIMING ($\overline{SYNCSE}$ or TMSTP±)						
$t_{H(\overline{SYNCSE})}$	Minimum hold time from a multiframe boundary (SYSREF rising edge captured high) to de-assertion of the JESD204B SYNC signal ($\overline{SYNCSE}$ if SYNC_SEL = 0 or TMSTP± if SYNC_SEL = 1) for NCO synchronization (NCO_SYNC_ILA = 1)	JMODE = 4 or 6		21		t_{CLK} cycles
		JMODE = 5 or 7		17		
		JMODE = 17 or 18		9		
$t_{SU(\overline{SYNCSE})}$	Minimum setup time from de-assertion of the JESD204B SYNC signal ($\overline{SYNCSE}$ if SYNC_SEL = 0 or TMSTP± if SYNC_SEL = 1) to multiframe boundary (SYSREF rising edge captured high) for NCO synchronization (NCO_SYNC_ILA = 1)	JMODE = 4 or 6		–2		t_{CLK} cycles
		JMODE = 5 or 7		2		
		JMODE = 17 or 18		10		
$t_{(\overline{SYNCSE})}$	$\overline{SYNCSE}$ minimum assertion time to trigger link resynchronization			4		Frames
SERIAL PROGRAMMING INTERFACE (SCLK, SDI, $\overline{SCS}$)						
$f_{CLK(SCLK)}$	Maximum serial clock frequency			15.625		MHz
$t_{(PH)}$	Minimum serial clock high value pulse duration			32		ns
$t_{(PL)}$	Minimum serial clock low value pulse duration			32		ns
$t_{SU(\overline{SCS})}$	Minimum setup time from $\overline{SCS}$ to rising edge of SCLK			30		ns
$t_{H(\overline{SCS})}$	Minimum hold time from rising edge of SCLK to $\overline{SCS}$			3		ns
$t_{SU(SDI)}$	Minimum setup time from SDI to rising edge of SCLK			30		ns
$t_{H(SDI)}$	Minimum hold time from rising edge of SCLK to SDI			3		ns

(1) Unless functionally limited to a smaller range in 表 10 based on the programmed JMODE.
(2) Use SYSREF_POS to select an optimal SYSREF_SEL value for SYSREF capture, see the *SYSREF Position Detector and Sampling Position Selection (SYSREF Windowing)* section for more information on SYSREF windowing. The invalid region, specified by $t_{INV(SYSREF)}$, indicates the portion of the CLK± period (t_{CLK}), as measured by SYSREF_SEL, that may result in a setup and hold violation. Verify that the timing skew between SYSREF± and CLK± over system operating conditions from the nominal conditions (that used to find optimal SYSREF_SEL) does not result in the invalid region occurring at the selected SYSREF_SEL position in SYSREF_POS, otherwise a temperature-dependent SYSREF_SEL selection may be needed to track the skew between CLK± and SYSREF±.

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6.10 Switching Characteristics

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DEVICE (Sampling) CLOCK (CLK+, CLK–)						
t_{AD}	Sampling (aperture) delay from CLK± rising edge (dual-channel mode) or rising and falling edge (single-channel mode) to sampling instant	TAD_COARSE = 0x00, TAD_FINE = 0x00, and TAD_INV = 0		360		ps
$t_{TAD(MAX)}$	Maximum t_{AD} adjust programmable delay, not including clock inversion (TAD_INV = 0)	Coarse adjustment (TAD_COARSE = 0xFF)		289		ps
		Fine adjustment (TAD_FINE = 0xFF)		4.9		
$t_{TAD(STEP)}$	t_{AD} adjust programmable delay step size	Coarse adjustment (TAD_COARSE)		1.13		ps
		Fine adjustment (TAD_FINE)		19		fs
t_{AJ}	Aperture jitter, rms	Minimum t_{AD} adjust coarse setting (TAD_COARSE = 0x00, TAD_INV = 0)		50		fs
		Maximum t_{AD} adjust coarse setting (TAD_COARSE = 0xFF) excluding TAD_INV (TAD_INV = 0)		70 (1)		
SERIAL DATA OUTPUTS (DA[7:0]+, DA[7:0]–, DB[7:0]+, DB[7:0]–)						
f_{SERDES}	Serialized output bit rate		1		12.8	Gbps
UI	Serialized output unit interval		78.125		1000	ps
t_{TLH}	Low-to-high transition time (differential)	20% to 80%, PRBS-7 test pattern, 12.8 Gbps, SER_PE = 0x04		37		ps
t_{THL}	High-to-low transition time (differential)	20% to 80%, PRBS-7 test pattern, 12.8 Gbps, SER_PE = 0x04		37		ps
DDJ	Data dependent jitter, peak-to-peak	PRBS-7 test pattern, 12.8 Gbps, SER_PE = 0x04, JMODE = 2		7.8		ps
RJ	Random jitter, RMS	PRBS-7 test pattern, 12.8 Gbps, SER_PE = 0x04, JMODE = 2		1.1		ps
TJ	Total jitter, peak-to-peak, with Gaussian portion defined with respect to a BER = 1e-15 (Q = 7.94)	PRBS-7 test pattern, 8 Gbps, SER_PE = 0x04, JMODE = 4, 5, 6, 7		28		ps

(1) t_{AJ} increases because of additional attenuation on the internal clock path.

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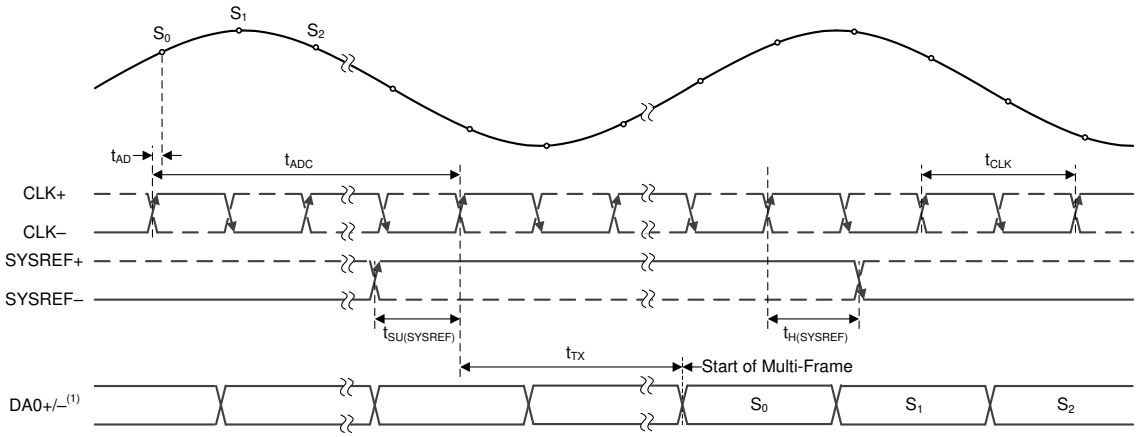
Switching Characteristics (continued)

typical values are at T_A = 25°C, VA19 = 1.9 V, VA11 = 1.1 V, VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 248 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); minimum and maximum values are at nominal supply voltages and over the operating free-air temperature range provided in the *Recommended Operating Conditions* table

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ADC CORE LATENCY						
t_{ADC}	Deterministic delay from the CLK± edge that samples the reference sample to the CLK± edge that samples SYSREF going high(2)	JMODE = 4		–4.5		t_{CLK} cycles
		JMODE = 5		–24.5		
		JMODE = 6		–5		
		JMODE = 7		–25		
		JMODE = 17		–48.5		
		JMODE = 18		–49		
JESD204B AND SERIALIZER LATENCY						
t_{TX}	Delay from the CLK± rising edge that samples SYSREF high to the first bit of the multiframe on the JESD204B serial output lane corresponding to the reference sample of t_{ADC}(3)	JMODE = 4	67		80	t_{CLK} cycles
		JMODE = 5	106		119	
		JMODE = 6	67		80	
		JMODE = 7	106		119	
		JMODE = 17	195		208	
		JMODE = 18	195		208	
SERIAL PROGRAMMING INTERFACE (SDO)						
$t_{(OZD)}$	Maximum delay from the falling edge of the 16th SCLK cycle during read operation for SDO transition from tri-state to valid data			7		ns
$t_{(ODZ)}$	Maximum delay from the $\overline{SCS}$ rising edge for SDO transition from valid data to tri-state			7		ns
$t_{(OD)}$	Maximum delay from the falling edge of the 16th SCLK cycle during read operation to SDO valid			12		ns

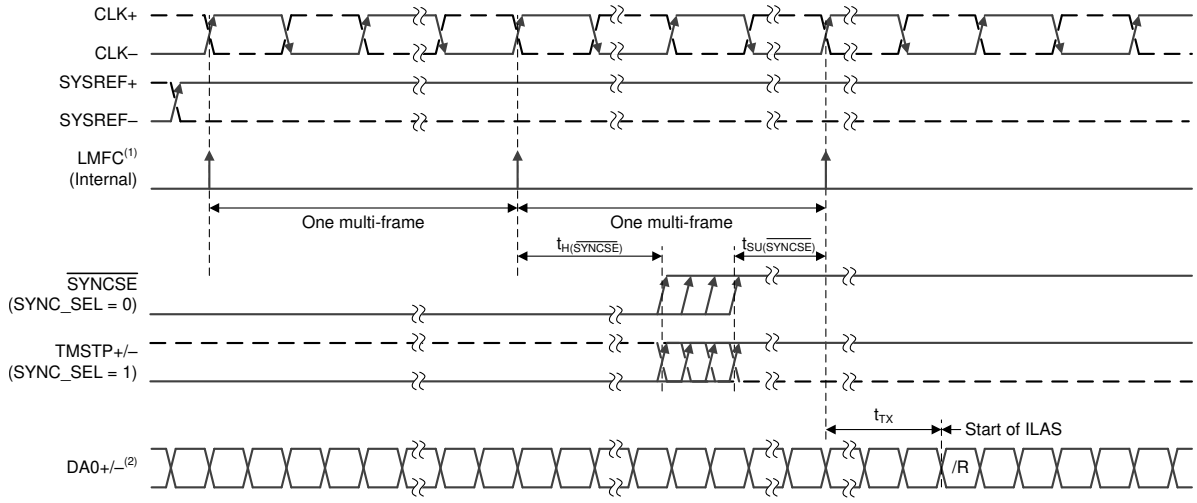
(2) t_{ADC} is an exact, unrounded, deterministic delay. The delay can be negative if the reference sample is sampled after the SYSREF high capture point, in which case the total latency is smaller than the delay given by t_{TX}.
(3) The values given for t_{TX} include deterministic and non-deterministic delays. The delay varies over process, temperature, and voltage. JESD204B accounts for these variations when operating in subclass-1 mode in order to achieve deterministic latency. Proper receiver RBD values must be chosen such that the elastic buffer release point does not occur within the invalid region of the local multiframe clock (LMFC) cycle.

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(1) Only the SerDes lane DA0± is shown, but DA0± is representative of all lanes. The number of output lanes used and bit-packing format is dependent on the programmed JMODE value.

图 1. ADC Timing Diagram



(2) The internal LMFC is assumed to be aligned with the CLK± rising edge that captures the SYSREF± high value.

(3) Only SerDes lane DA0± is shown, but DA0± is representative of all lanes. All lanes output /R at approximately the same point in time. The number of lanes is dependent on the programmed JMODE value.

图 2. SYNCSE and TMSTP± Timing Diagram for NCO Synchronization

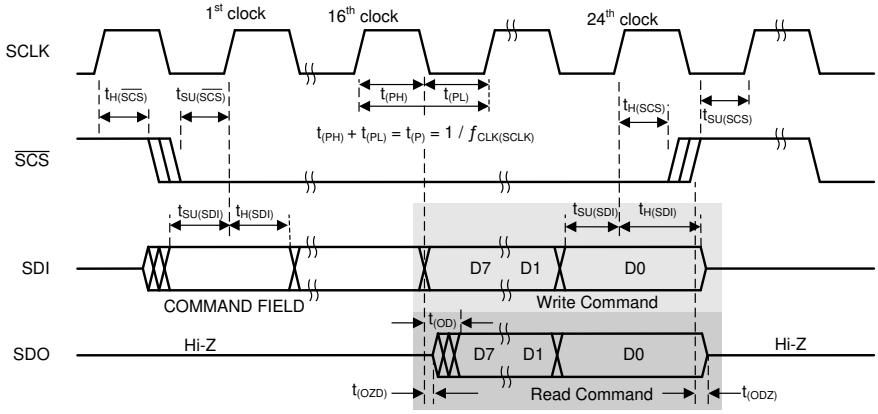
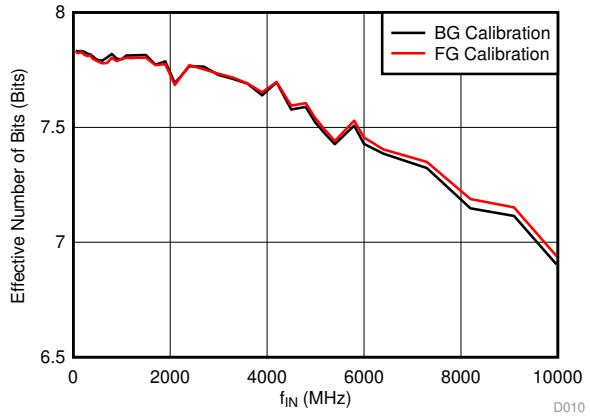


图 3. Serial Interface Timing

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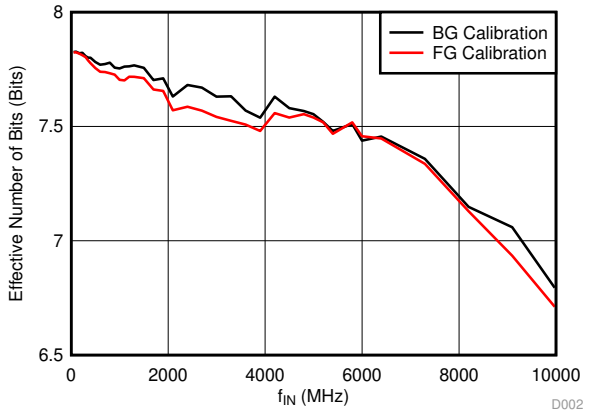
6.11 Typical Characteristics

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



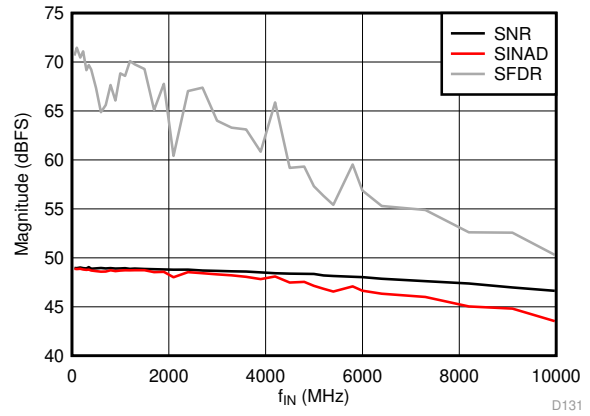
JMODE7, f_S = 3200 MSPS, foreground (FG) and background (BG) calibration

Figure 4. ENOB vs Input Frequency



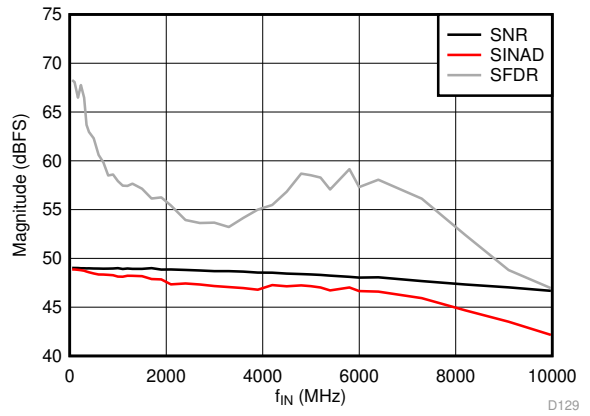
JMODE5, f_S = 6400 MSPS, FG and BG calibration

Figure 5. ENOB vs Input Frequency



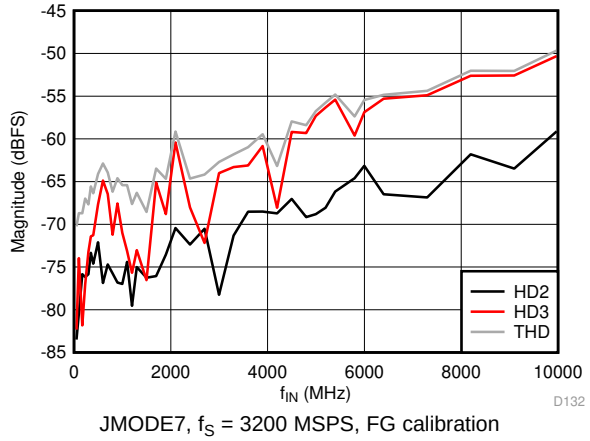
JMODE7, f_S = 3200 MSPS, FG calibration

Figure 6. SNR, SINAD, SFDR vs Input Frequency



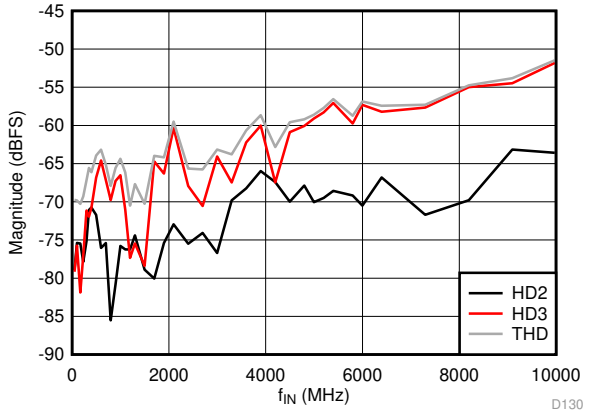
JMODE5, f_S = 6400 MSPS, FG calibration

Figure 7. SNR, SINAD, SFDR vs Input Frequency



JMODE7, f_S = 3200 MSPS, FG calibration

Figure 8. HD2, HD3, THD vs Input Frequency



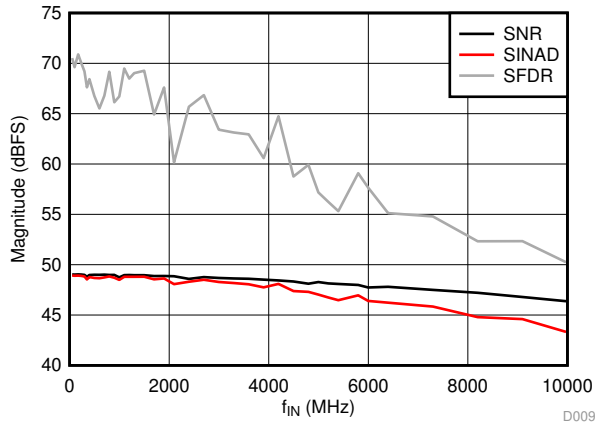
JMODE5, f_S = 6400 MSPS, FG calibration

Figure 9. HD2, HD3, THD vs Input Frequency

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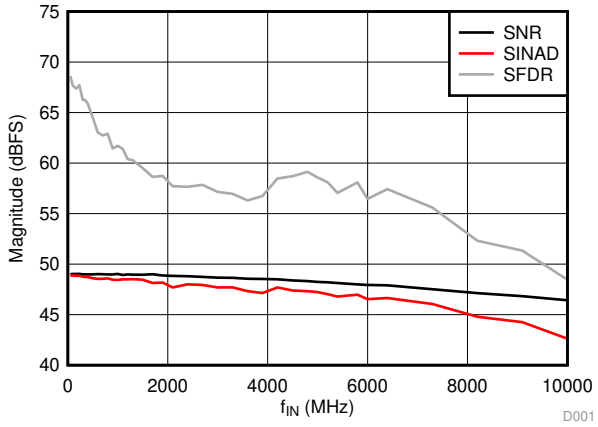
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



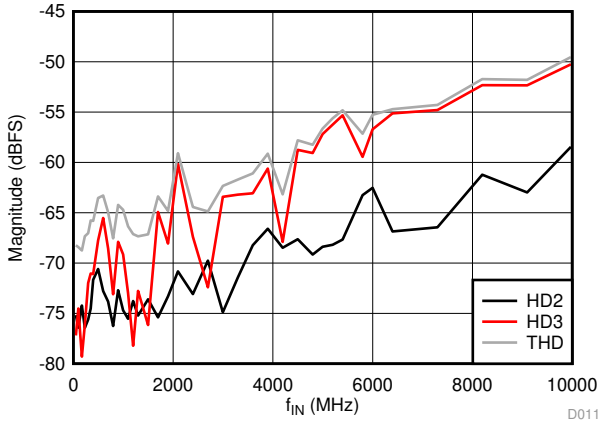
JMODE7, f_S = 3200 MSPS, BG calibration

Figure 10. SNR, SINAD, SFDR vs Input Frequency



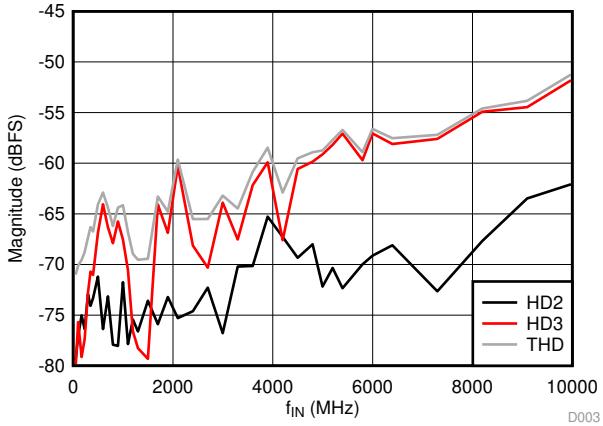
JMODE5, f_S = 6400 MSPS, BG calibration

Figure 11. SNR, SINAD, SFDR vs Input Frequency



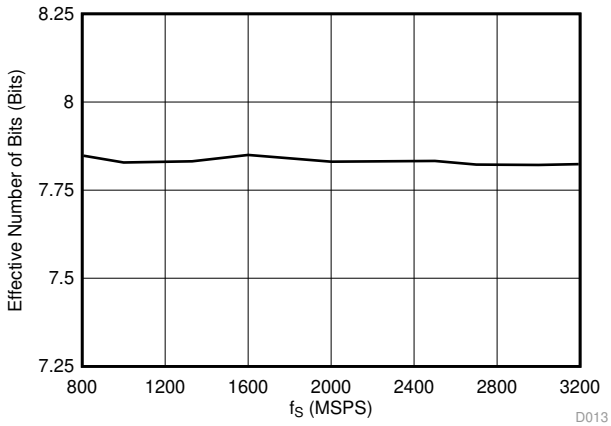
JMODE7, f_S = 3200 MSPS, BG calibration

Figure 12. HD2, HD3, THD vs Input Frequency



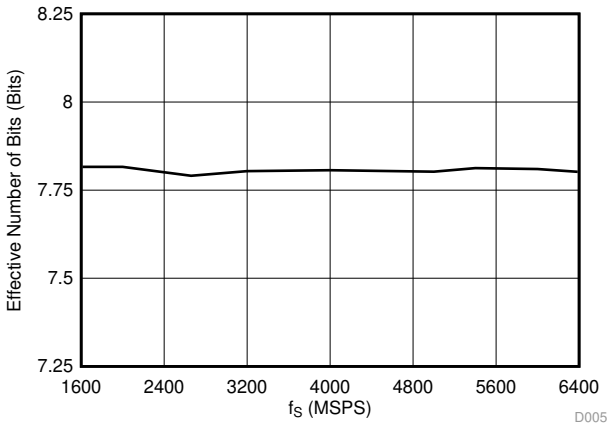
JMODE5, f_S = 6400 MSPS, BG calibration

Figure 13. HD2, HD3, THD vs Input Frequency



JMODE7, f_{IN} = 347 MHz, BG calibration

Figure 14. ENOB vs Sampling Rate



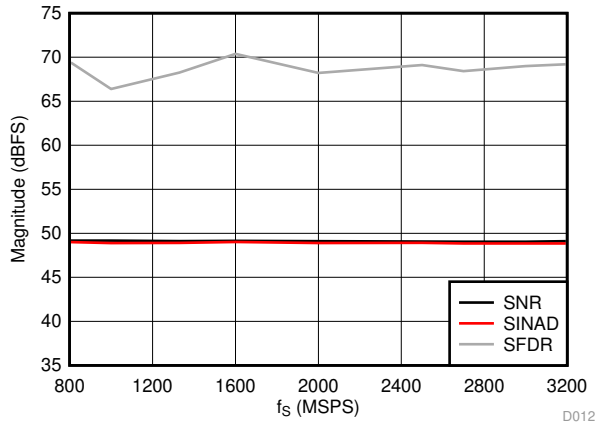
JMODE5, f_{IN} = 347 MHz, BG calibration

Figure 15. ENOB vs Sampling Rate

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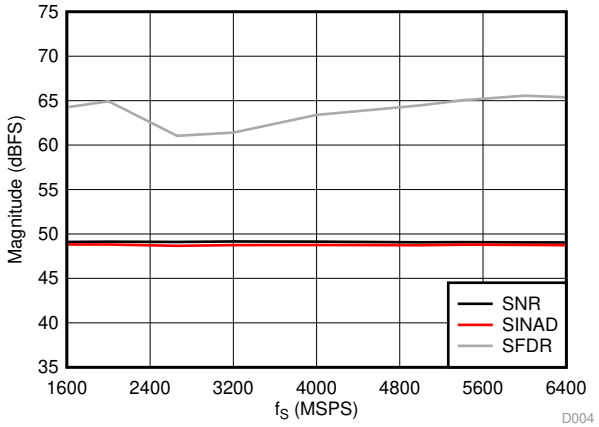
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



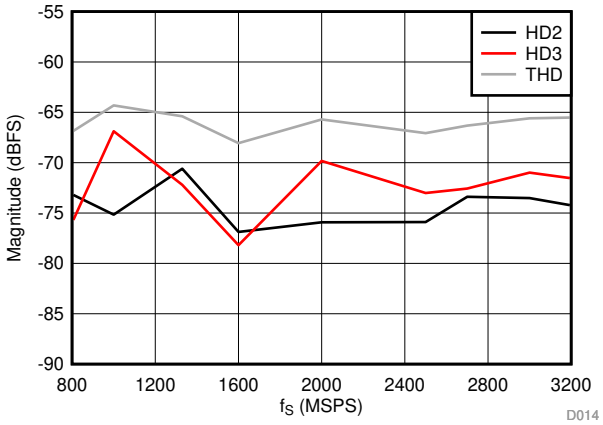
JMODE7, f_{IN} = 347 MHz, BG calibration

Figure 16. SNR, SINAD, SFDR vs Sampling Rate



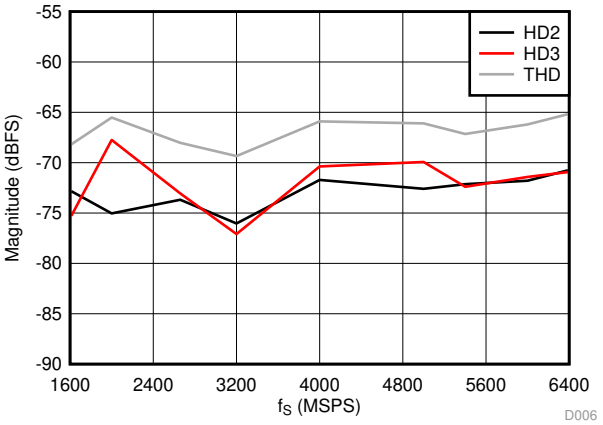
JMODE5, f_{IN} = 347 MHz, BG calibration

Figure 17. SNR, SINAD, SFDR vs Sampling Rate



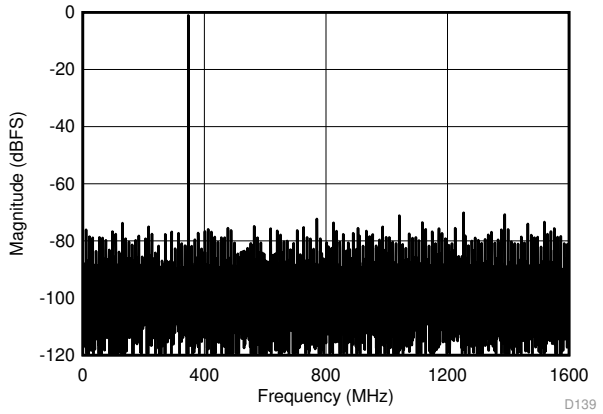
JMODE7, f_{IN} = 347 MHz, BG calibration

Figure 18. HD2, HD3, THD vs Sampling Rate



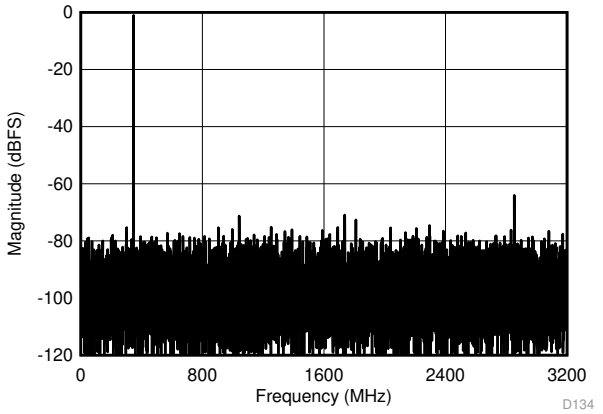
JMODE5, f_{IN} = 347 MHz, BG calibration

Figure 19. HD2, HD3, THD vs Sampling Rate



JMODE7, f_{IN} = 350 MHz, FG calibration, SNR = 49.1 dBFS, SFDR = 70.1 dBFS, ENOB = 7.80 bits

Figure 20. Single-Tone FFT at A_{IN} = –1 dBFS



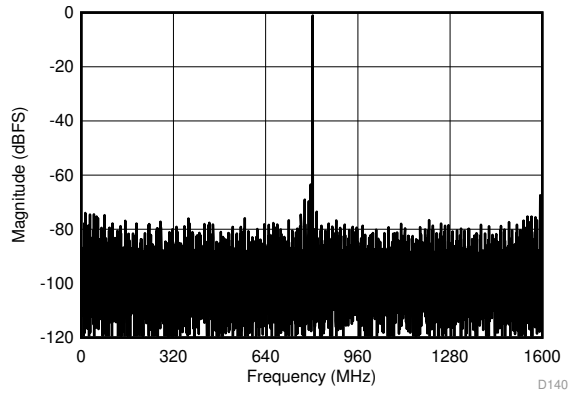
JMODE5, f_{IN} = 350 MHz, FG calibration, SNR = 49.0 dBFS, SFDR = 64.0 dBFS, ENOB = 7.80 bits

Figure 21. Single-Tone FFT at A_{IN} = –1 dBFS

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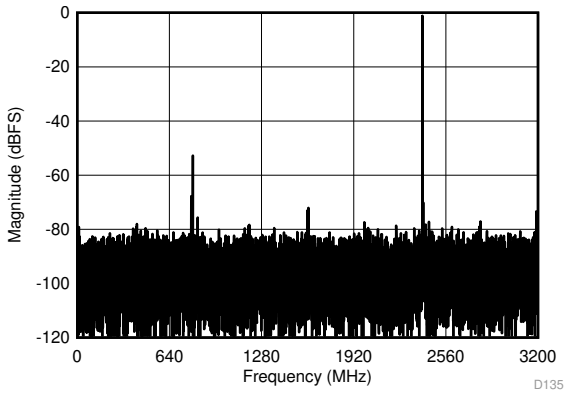
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



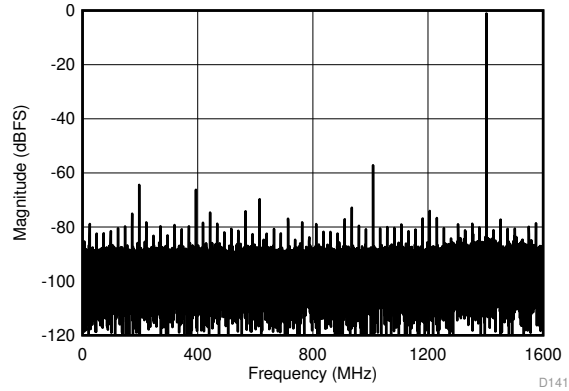
JMODE7, f_{IN} = 2400 MHz, FG calibration, SNR = 48.8 dBFS, SFDR = 63.7 dBFS, ENOB = 7.74 bits

Figure 22. Single-Tone FFT at A_{IN} = –1 dBFS



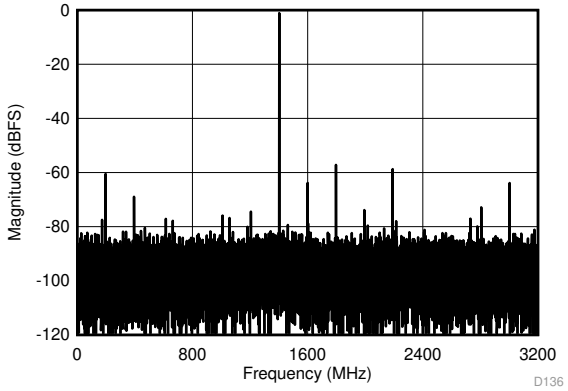
JMODE5, f_{IN} = 2400 MHz, FG calibration, SNR = 48.8 dBFS, SFDR = 52.4 dBFS, ENOB = 7.53 bits

Figure 23. Single-Tone FFT at A_{IN} = –1 dBFS



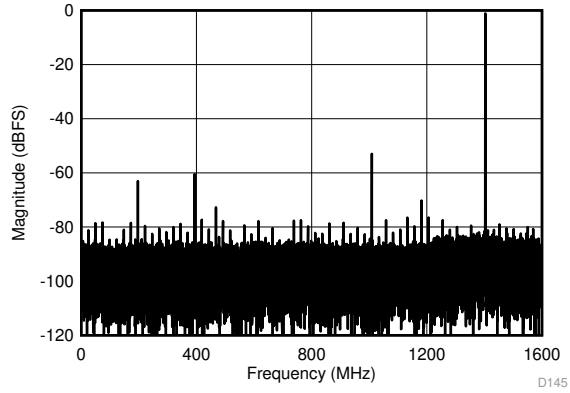
JMODE7, f_{IN} = 5000 MHz, FG calibration, SNR = 48.4 dBFS, SFDR = 57.1 dBFS, ENOB = 7.52 bits

Figure 24. Single-Tone FFT at A_{IN} = –1 dBFS



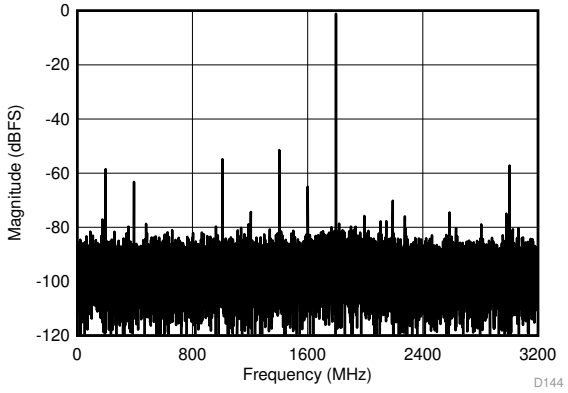
JMODE5, f_{IN} = 5000 MHz, FG calibration, SNR = 48.3 dBFS, SFDR = 57.2 dBFS, ENOB = 7.48 bits

Figure 25. Single-Tone FFT at A_{IN} = –1 dBFS



JMODE7, f_{IN} = 8200 MHz, FG calibration, SNR = 47.4 dBFS, SFDR = 52.4 dBFS, ENOB = 7.19 bits

Figure 26. Single-Tone FFT at A_{IN} = –1 dBFS



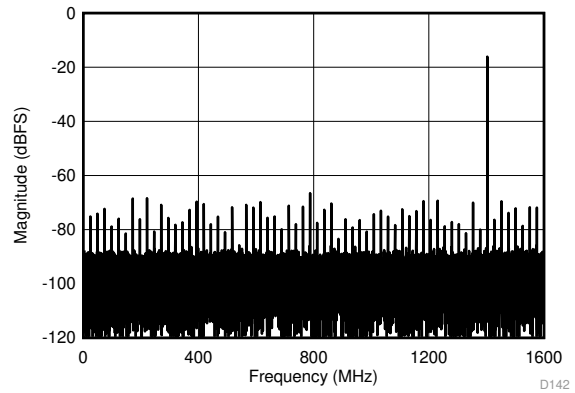
JMODE5, f_{IN} = 8200 MHz, FG calibration, SNR = 47.4 dBFS, SFDR = 51.4 dBFS, ENOB = 7.10 bits

Figure 27. Single-Tone FFT at A_{IN} = –1 dBFS

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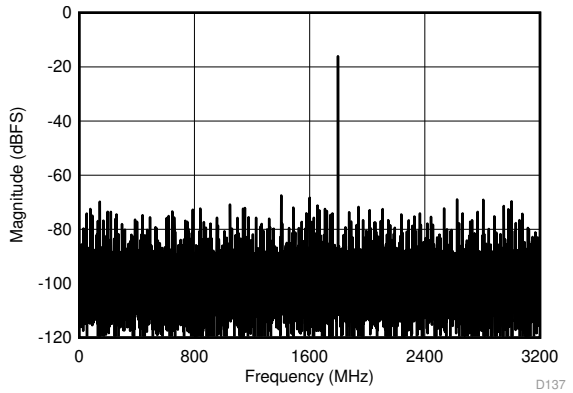
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



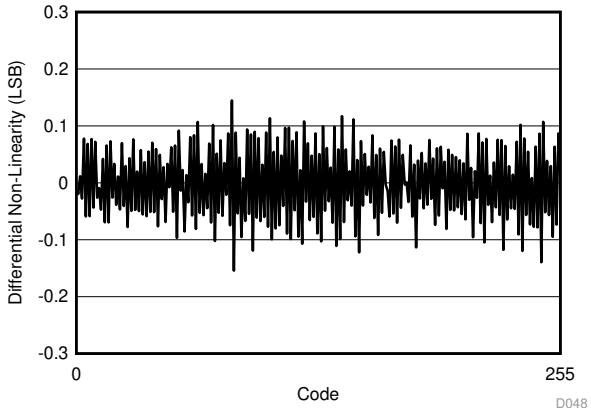
JMODE7, f_{IN} = 8200 MHz, FG calibration, SNR = 49.2 dBFS, SFDR = 65.9 dBFS, ENOB = 7.80 bits

Figure 28. Single-Tone FFT at A_{IN} = –16 dBFS



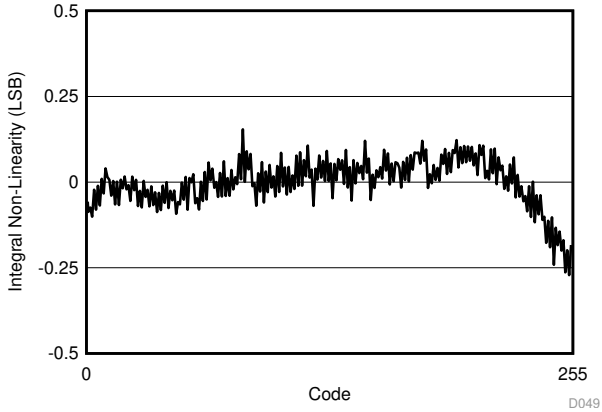
JMODE5, f_{IN} = 8200 MHz, FG calibration, SNR = 49.0 dBFS, SFDR = 67.5 dBFS, ENOB = 7.79 bits

Figure 29. Single-Tone FFT at A_{IN} = –16 dBFS



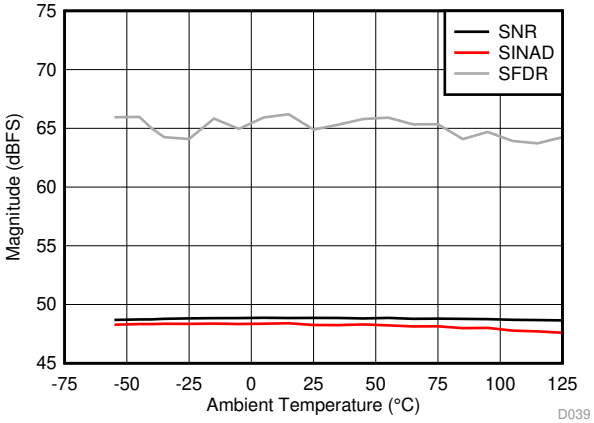
JMODE5, f_S = 6400 MSPS, FG calibration

Figure 30. DNL vs Code



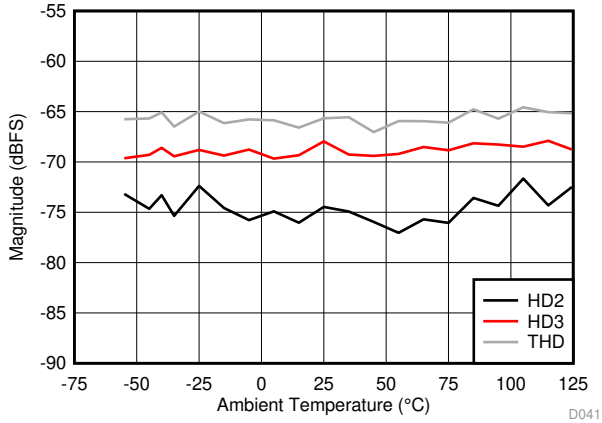
JMODE5, f_S = 6400 MSPS, FG calibration

Figure 31. INL vs Code



JMODE5, f_S = 6400 MSPS, f_{IN} = 2400 MHz, BG calibration

Figure 32. SNR, SINAD, SFDR vs Temperature

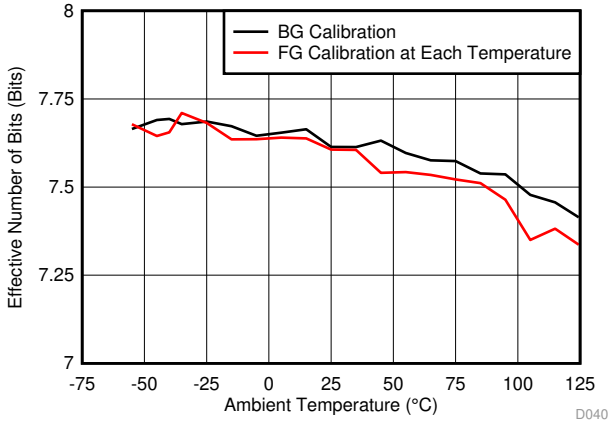


JMODE5, f_S = 6400 MSPS, f_{IN} = 2400 MHz, BG calibration

Figure 33. HD2, HD3, THD vs Temperature

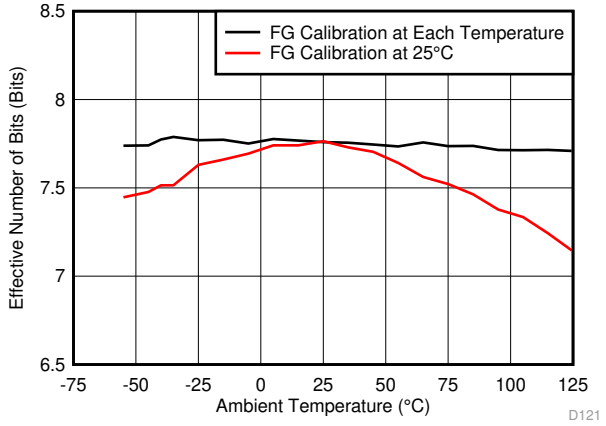
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



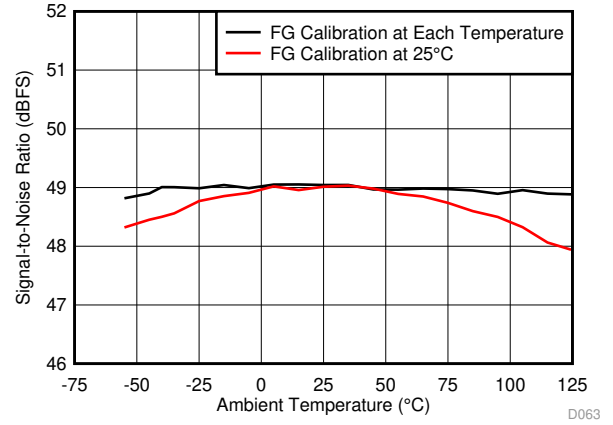
JMODE5, f_{IN} = 2400 MHz, f_S = 6400 MSPS

Figure 34. ENOB vs Temperature and Calibration Type



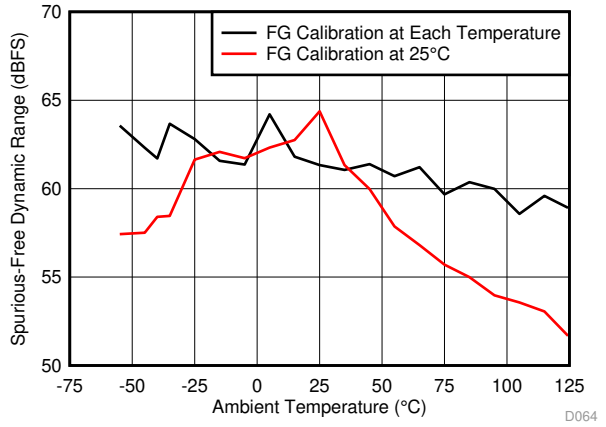
JMODE5, f_{IN} = 600 MHz, f_S = 6400 MSPS

Figure 35. ENOB vs Temperature and Calibration Type



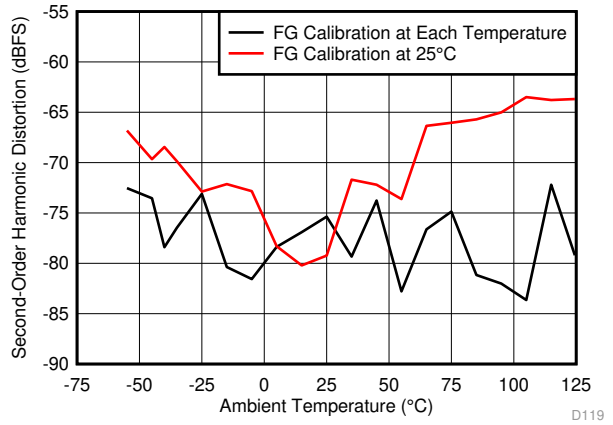
JMODE5, f_{IN} = 600 MHz, f_S = 6400 MSPS

Figure 36. SNR vs Temperature and Calibration Type



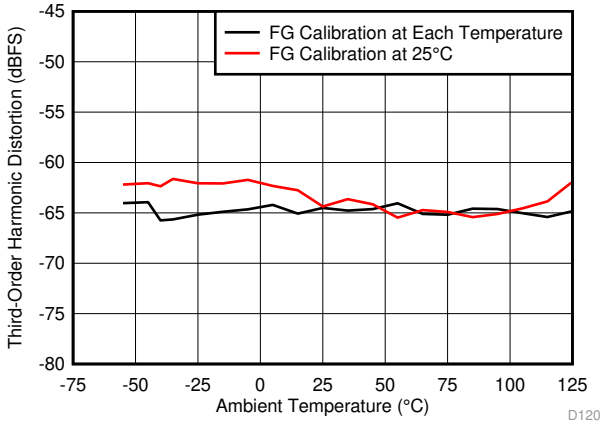
JMODE5, f_{IN} = 600 MHz, f_S = 6400 MSPS

Figure 37. SFDR vs Temperature and Calibration Type



JMODE5, f_{IN} = 600 MHz, f_S = 6400 MSPS

Figure 38. HD2 vs Temperature and Calibration Type



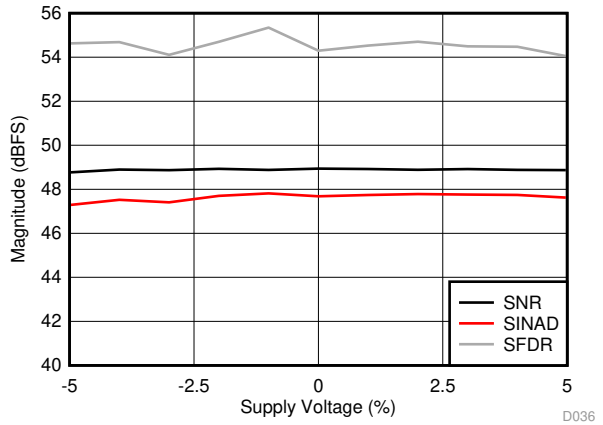
JMODE5, f_{IN} = 600 MHz, f_S = 6400 MSPS

Figure 39. HD3 vs Temperature and Calibration Type

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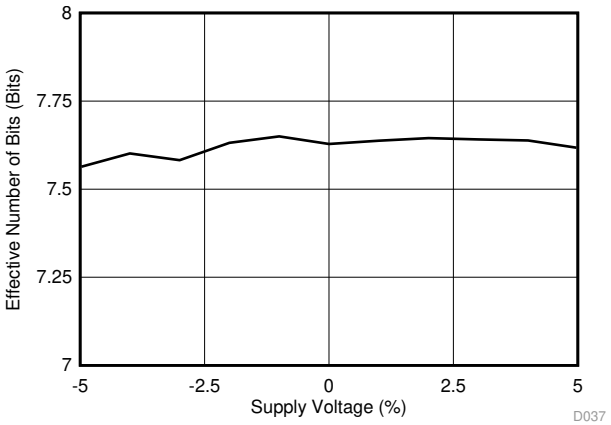
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



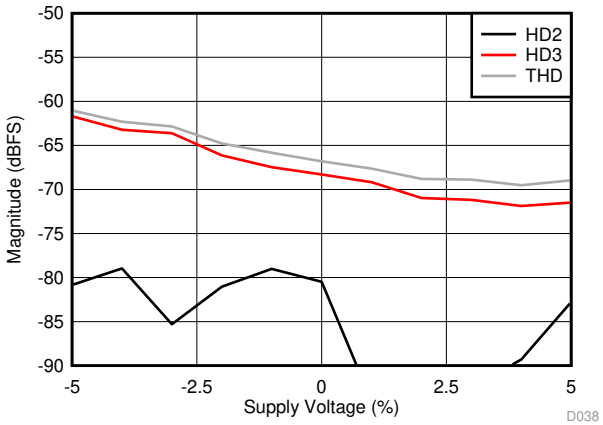
JMODE5, f_S = 6400 MSPS, f_{IN} = 2400 MHz, FG calibration

Figure 40. SNR, SINAD, SFDR vs Supply Voltage



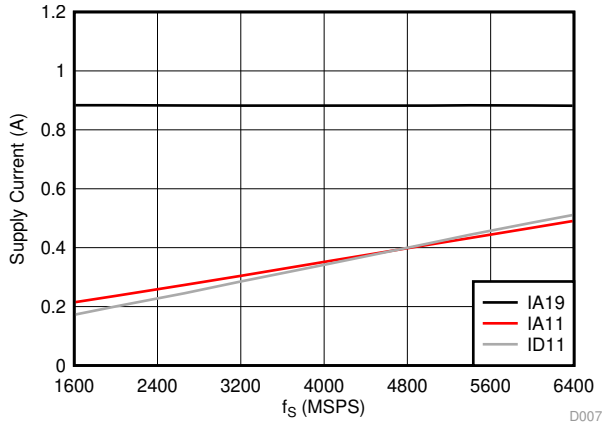
JMODE5, f_S = 6400 MSPS, f_{IN} = 2400 MHz, FG calibration

Figure 41. ENOB vs Supply Voltage



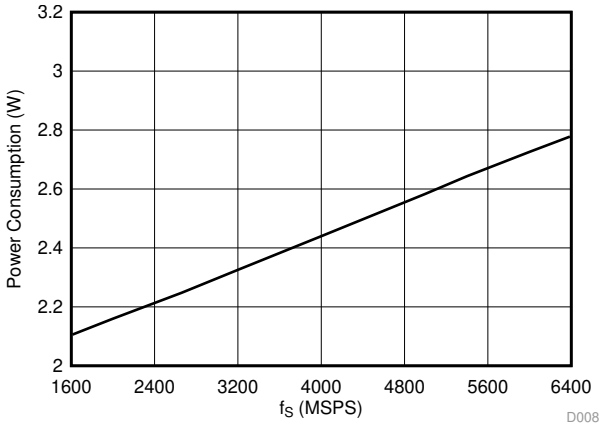
JMODE5, f_S = 6400 MSPS, f_{IN} = 2400 MHz, FG calibration

Figure 42. HD2, HD3, THD vs Supply Voltage



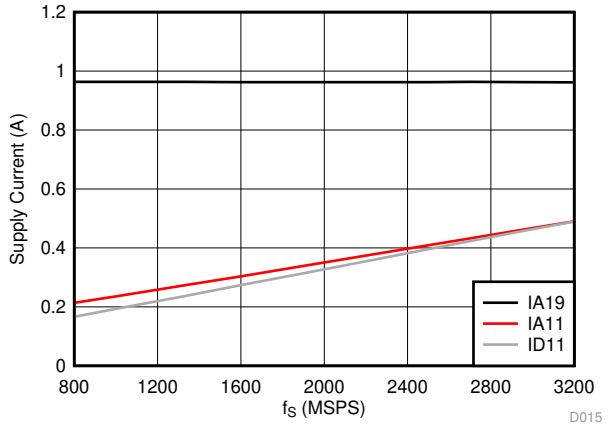
JMODE5, f_{IN} = 347 MHz, FG calibration

Figure 43. Supply Current vs Sampling Rate



JMODE5, f_{IN} = 347 MHz, FG calibration

Figure 44. Power Consumption vs Sampling Rate



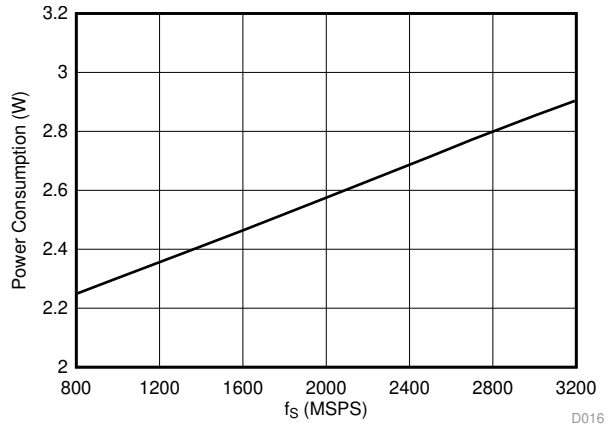
JMODE7, f_{IN} = 347 MHz, FG calibration

Figure 45. Supply Current vs Sampling Rate

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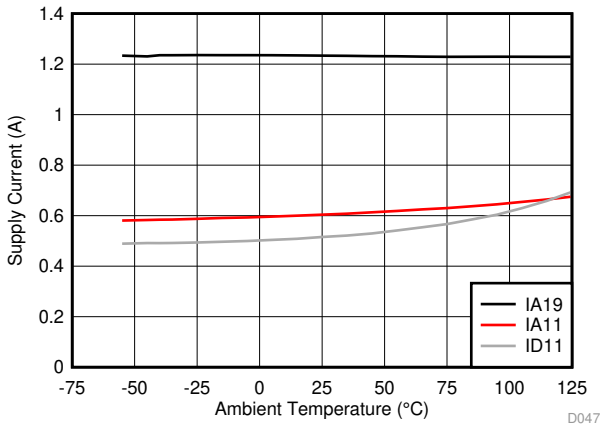
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



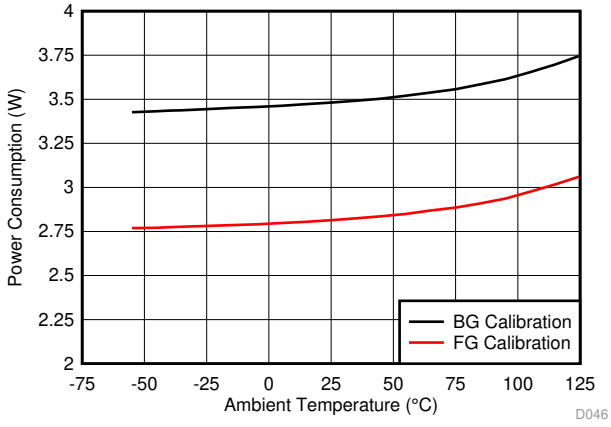
JMODE7, f_{IN} = 347 MHz, FG calibration

Figure 46. Power Consumption vs Sampling Rate



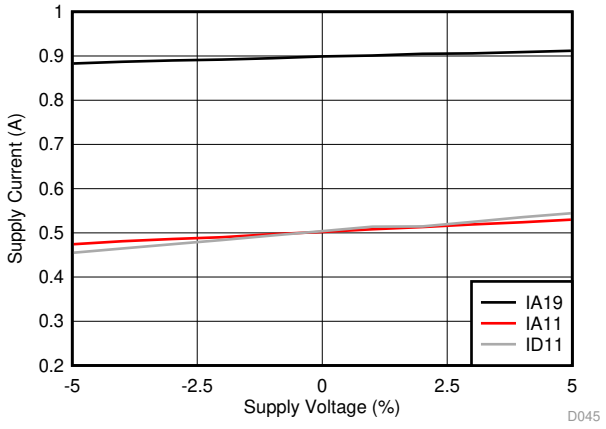
JMODE5, f_S = 6400 MSPS, f_{IN} = 2400 MHz, BG calibration

Figure 47. Supply Current vs Temperature



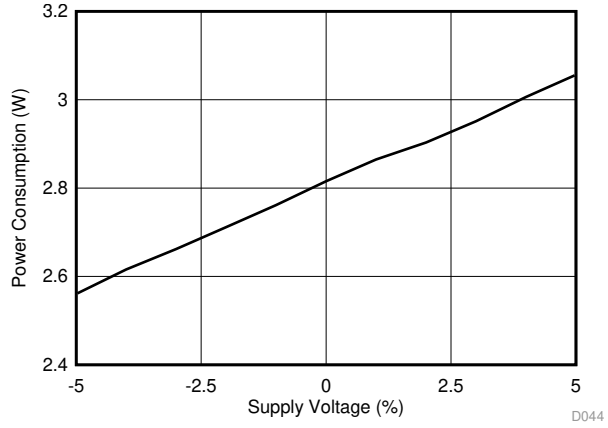
JMODE5, f_S = 6400 MSPS, f_{IN} = 2400 MHz, BG calibration

Figure 48. Power Consumption vs Temperature



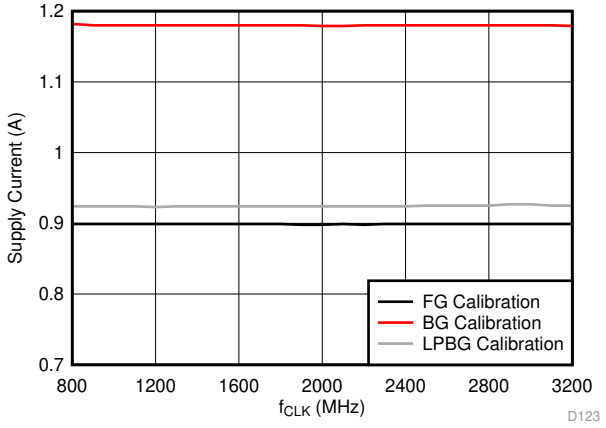
JMODE5, f_S = 6400 MSPS, FG calibration

Figure 49. Supply Current vs Supply Voltage



JMODE5, f_S = 6400 MSPS, FG calibration

Figure 50. Power Consumption vs Supply Voltage



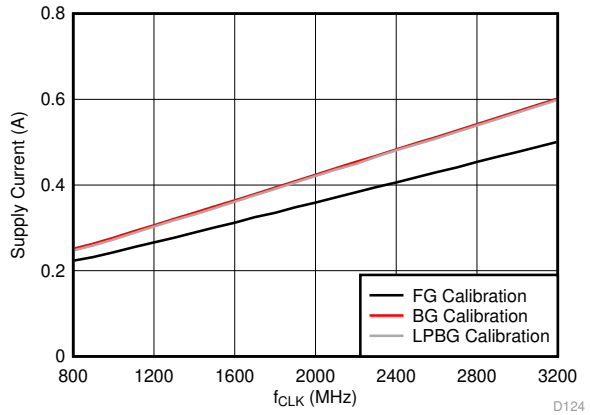
JMODE5, f_{IN} = 607 MHz

Figure 51. IA19 Supply Current vs Clock Frequency

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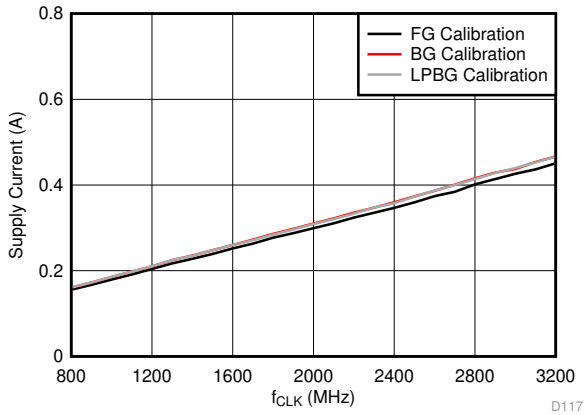
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



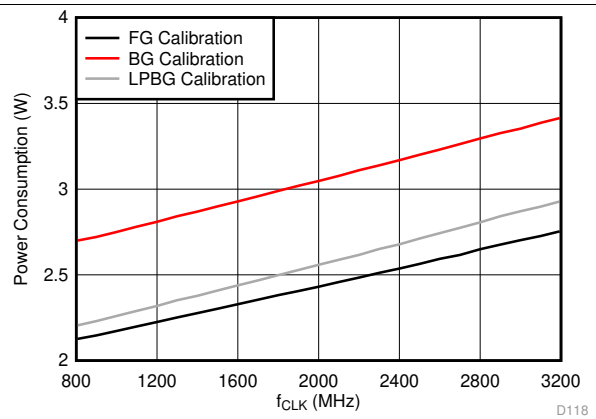
JMODE5, f_{IN} = 607 MHz

Figure 52. IA11 Supply Current vs Clock Frequency



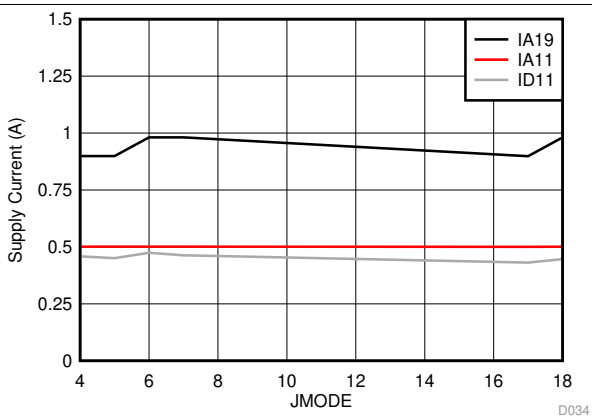
JMODE5, f_{IN} = 607 MHz

Figure 53. ID11 Supply Current vs Clock Frequency



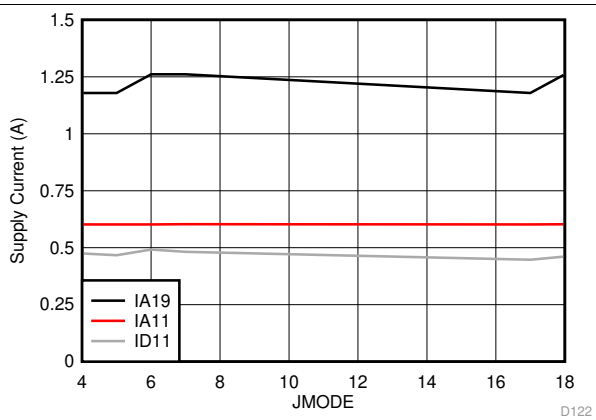
JMODE5, f_{IN} = 607 MHz

Figure 54. Power Consumption vs Clock Frequency



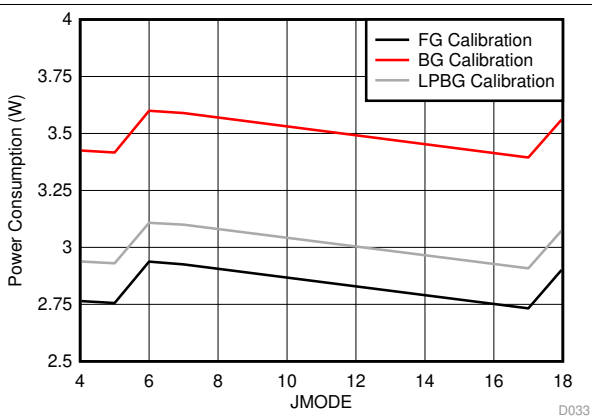
f_{IN} = 2400 MHz, f_{CLK} = 3200 MHz, FG calibration

Figure 55. Supply Current vs JMODE



f_{IN} = 2400 MHz, f_{CLK} = 3200 MHz, BG calibration

Figure 56. Supply Current vs JMODE



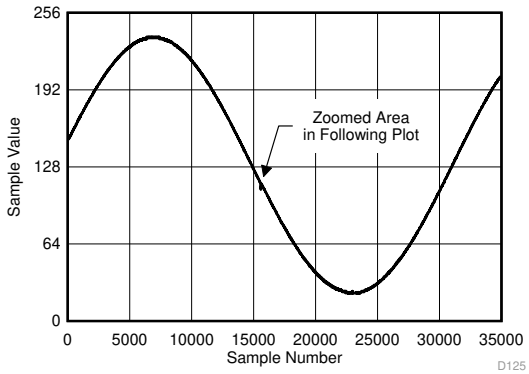
f_{IN} = 2400 MHz, f_{CLK} = 3200 MHz

Figure 57. Power Consumption vs JMODE

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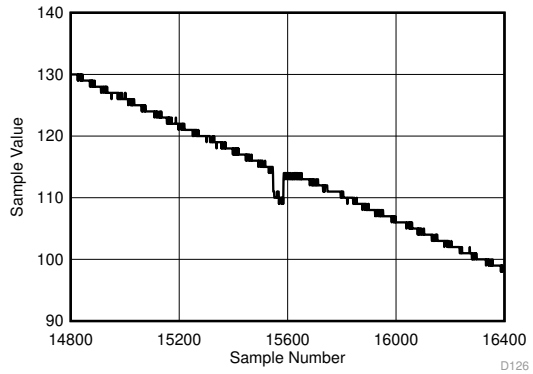
Typical Characteristics (continued)

typical values at T_A = 25°C, VA19 = 1.9 V, VA11 = VD11 = 1.1 V, default full-scale voltage (FS_RANGE_A = FS_RANGE_B = 0xA000), input signal applied to INA± in single-channel modes, f_{IN} = 347 MHz, A_{IN} = –1 dBFS, f_{CLK} = maximum-rated clock frequency, filtered, 1-V_{PP} sine-wave clock, JMODE = 17, and background calibration (unless otherwise noted); SNR results exclude DC, HD2 to HD9 and interleaving spurs; SINAD, ENOB, and SFDR results exclude DC and fixed-frequency interleaving spurs



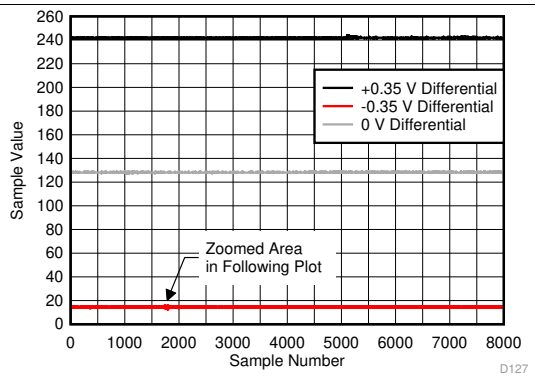
JMODE4, f_{CLK} = 3200 MHz, f_{IN} = 3199.9 MHz

Figure 58. Background Calibration Core Transition (AC Signal)



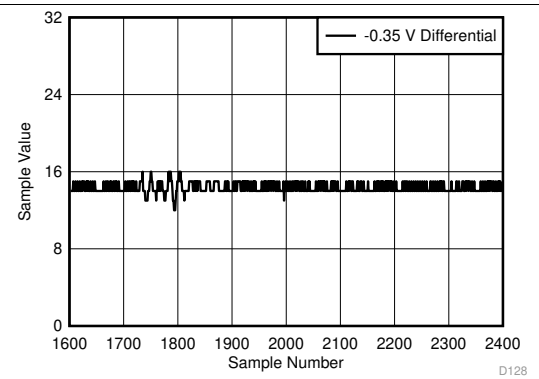
JMODE4, f_{CLK} = 3200 MHz, f_{IN} = 3199.9 MHz

Figure 59. Background Calibration Core Transition (AC Signal Zoomed)



JMODE4, f_{CLK} = 3200 MHz, DC input

Figure 60. Background Calibration Core Transition (DC Signal)



JMODE4, f_{CLK} = 3200 MHz, DC input

Figure 61. Background Calibration Core Transition (DC Signal Zoomed)

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7 Detailed Description

7.1 Overview

ADC08DJ3200 device is an RF-sampling, giga-sample, analog-to-digital converter (ADC) that can directly sample input frequencies from DC to above 10 GHz. In dual-channel mode, the ADC08DJ3200 can sample up to 3200 GSPS and up to 6400 GSPS in single-channel mode. Programmable tradeoffs in channel count (dual-channel mode) and Nyquist bandwidth (single-channel mode) allow development of flexible hardware that meets the needs of both high channel count or wide instantaneous signal bandwidth applications. Full-power input bandwidth (–3 dB) of 8.0 GHz, with usable frequencies exceeding the –3-dB point in both dual- and single-channel modes, allows direct RF sampling of L-band, S-band, C-band, and X-band for frequency agile systems.

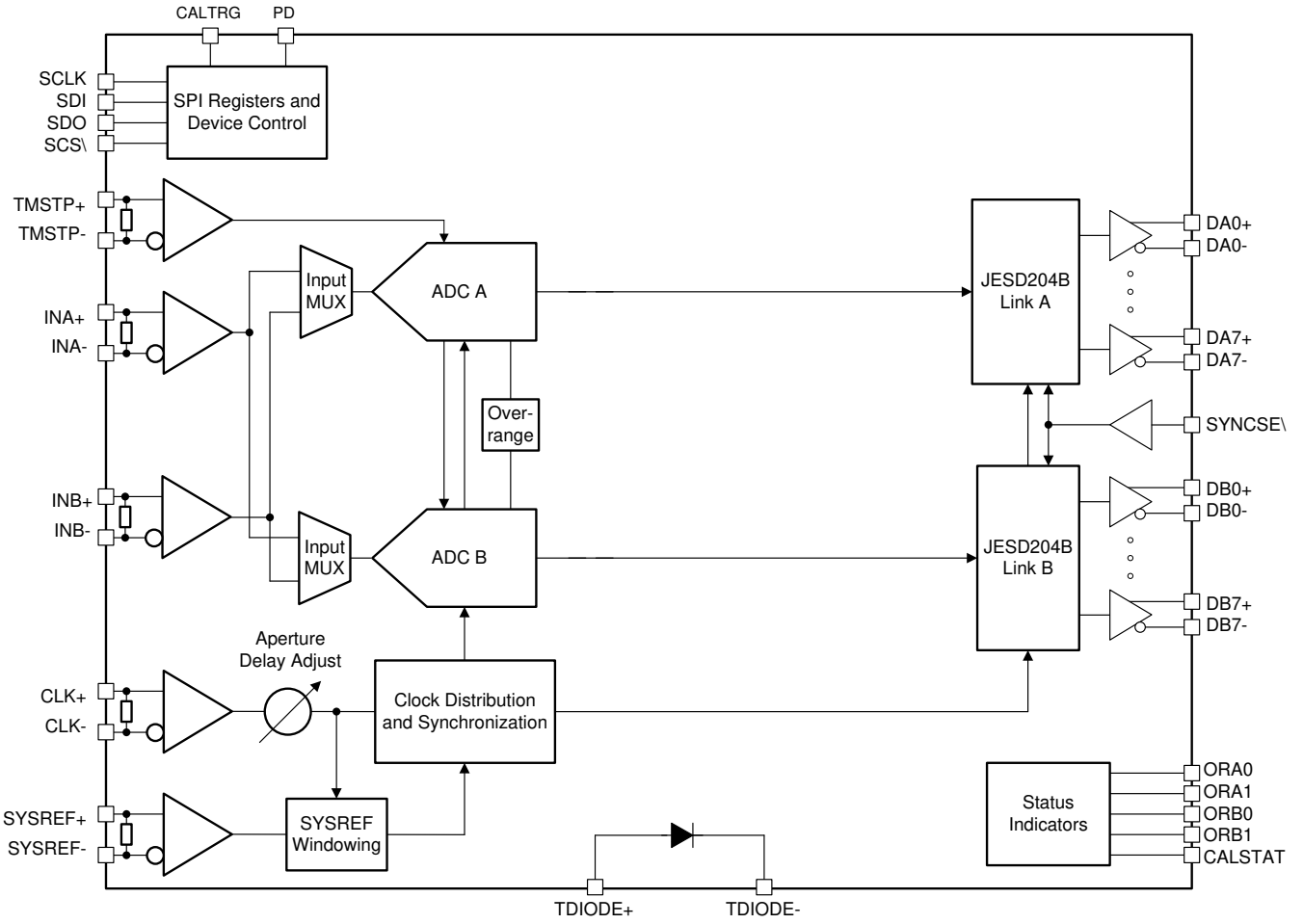
ADC08DJ3200 uses a high-speed JESD204B output interface with up to 16 serialized lanes and subclass-1 compliance for deterministic latency and multi-device synchronization. The serial output lanes support up to 12.8 Gbps and can be configured to trade-off bit rate and number of lanes. At 5 Gsps, only four total lanes are required running at 12.5 Gbps or 16 lanes can be used to reduce the lane rate to 3.125 Gbps.

A number of synchronization features, including noiseless aperture delay (t_{AD}) adjustment and SYSREF windowing, simplify system design for multi-channel systems. Aperture delay adjustment can be used to simplify SYSREF capture, to align the sampling instance between multiple ADCs or to sample an ideal location of a front-end track and hold (T&H) amplifier output. SYSREF windowing offers a simplistic way to measure invalid timing regions of SYSREF relative to the device clock and then choose an optimal sampling location. Dual-edge sampling (DES) is implemented in single-channel mode to reduce the maximum clock rate applied to the ADC to support a wide range of clock sources and relax setup and hold timing for SYSREF capture.

ADC08DJ3200 provides foreground and background calibration options for gain, offset and static linearity errors. Foreground calibration is run at system startup or at specified times during which the ADC is offline and not sending data to the logic device. Background calibration allows the ADC to run continually while the cores are calibrated in the background so that the system does not experience downtime. The calibration routine is also used to match the gain and offset between sub-ADC cores to minimize spurious artifacts from time interleaving.

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7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Device Comparison

The devices listed in 表 1 are part of a pin-to-pin compatible, high-speed, wide-bandwidth ADC family. The family is offered to provide a scalable family of devices for varying resolution, sampling rate and signal bandwidth.

表 1. Device Family Comparison

PART NUMBER	MAXIMUM SAMPLING RATE	RESOLUTION	DUAL CHANNEL DECIMATION	SINGLE CHANNEL DECIMATION	INTERFACE (MAX LINERATE)
ADC12DJ5200RF	Single 10.4 GSPS Dual 5.2 GSPS	12-bit	Complex: 4x, 8x	Complex: 4x, 8x	JESD204B / JESD204C (17.16 Gbps)
ADC12DJ3200	Single 6.4 GSPS Dual 3.2 GSPS	12-bit	Real: 2x Complex: 4x, 8x, 16x	None	JESD204B (12.8 Gbps)
ADC08DJ3200	Single 6.4 GSPS Dual 3.2 GSPS	8-bit	None	None	JESD204B (12.8 Gbps)
ADC12DJ2700	Single 5.4 GSPS Dual 2.7 GSPS	12-bit	Real: 2x Complex: 4x, 8x, 16x	None	JESD204B (12.8 Gbps)

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7.3.2 Analog Inputs

The analog inputs of the ADC08DJ3200 have internal buffers to enable high input bandwidth and to isolate sampling capacitor glitch noise from the input circuit. Analog inputs must be driven differentially because operation with a single-ended signal results in degraded performance. Both AC-coupling and DC-coupling of the analog inputs is supported. The analog inputs are designed for an input common-mode voltage (V_{CMI}) of 0 V, which is terminated internally through single-ended, 50-Ω resistors to ground (GND) on each input pin. DC-coupled input signals must have a common-mode voltage that meets the device input common-mode requirements specified as V_{CMI} in the *Recommended Operating Conditions* table. The 0-V input common-mode voltage simplifies the interface to split-supply, fully-differential amplifiers and to a variety of transformers and baluns. The ADC08DJ3200 includes internal analog input protection to protect the ADC inputs during overranged input conditions; see the *Analog Input Protection* section. 图 62 provides a simplified analog input model.

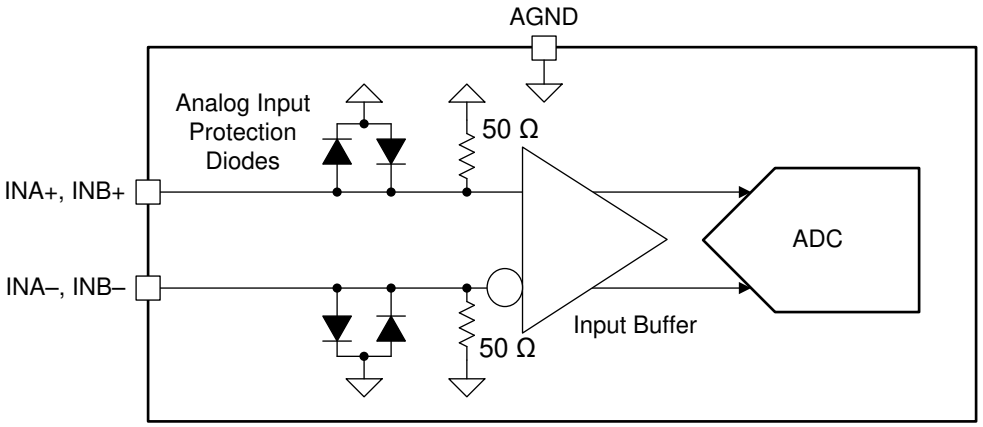


图 62. ADC08DJ3200 Analog Input Internal Termination and Protection Diagram

There is minimal degradation in analog input bandwidth when using single-channel mode versus dual-channel mode. In single-channel mode, INA± is strongly recommended to be used as the input to the ADC because ADC performance is optimized for INA±. However, either analog input (INA+ and INA– or INB+ and INB–) can be used. Using INB± results in degraded performance unless custom trim routines are used to optimize performance for INB± in each device. The desired input can be chosen using SINGLE_INPUT in the input mux control register.

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INA± is strongly recommended to be used as the input to the ADC in single-channel mode for optimized performance.

7.3.2.1 Analog Input Protection

The analog inputs are protected against overdrive conditions by internal clamping diodes that are capable of sourcing or sinking input currents during overrange conditions, see the voltage and current limits in the *Absolute Maximum Ratings* table. The overrange protection is also defined for a peak RF input power in the *Absolute Maximum Ratings* table, which is frequency independent. Operation above the maximum conditions listed in the *Recommended Operating Conditions* table results in an increase in failure-in-time (FIT) rate, so the system must correct the overdrive condition as quickly as possible. 图 62 shows the analog input protection diodes.

7.3.2.2 Full-Scale Voltage (V_{FS}) Adjustment

Input full-scale voltage (V_{FS}) adjustment is available, in fine increments, for each analog input through the FS_RANGE_A register setting (see the INA full-scale range adjust register) and FS_RANGE_B register setting (see the INB full-scale range adjust register) for INA± and INB±, respectively. The available adjustment range is specified in the *Electrical Characteristics: DC Specifications* table. Larger full-scale voltages improve SNR and noise floor (in dBFS/Hz) performance, but may degrade harmonic distortion. The full-scale voltage adjustment is useful for matching the full-scale range of multiple ADCs when developing a multi-converter system or for external interleaving of multiple ADC08DJ3200s to achieve higher sampling rates.

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7.3.2.3 Analog Input Offset Adjust

The input offset voltage for each input can be adjusted through the SPI register. The OADJ_A_INx registers (registers 0x08A and 0x08D) are used to adjust ADC core A's offset voltage when sampling analog input x (where x is A for INA± or B for INB±). OADJ_B_INx is used to adjust ADC core B's offset voltage when sampling input x. These registers apply to both dual channel mode and single channel mode. To adjust the offset voltage in dual channel mode simply adjust the offset to the ADC core sampling the desired input. In single channel mode, both ADC core A's and ADC core B's offset must be adjusted together. The difference in the two core's offsets in single channel mode results in a spur at $f_S/2$ that is independent of the input. These registers can be used to compensate the $f_S/2$ spur in single channel mode. See the *Calibration Modes and Trimming* section for more information.

7.3.3 ADC Core

The ADC08DJ3200 consists of a total of six ADC cores. The cores are interleaved for higher sampling rates and swapped on-the-fly for calibration as required by the operating mode. This section highlights the theory and key features of the ADC cores.

7.3.3.1 ADC Theory of Operation

The differential voltages at the analog inputs are captured by the rising edge of CLK± in dual-channel mode or by the rising and falling edges of CLK± in single-channel mode. After capturing the input signal, the ADC converts the analog voltage to a digital value by comparing the voltage to the internal reference voltage. If the voltage on INA– or INB– is higher than the voltage on INA+ or INB+, respectively, then the digital output is a negative 2's complement value. If the voltage on INA+ or INB+ is higher than the voltage on INA– or INB–, respectively, then the digital output is a positive 2's complement value. 公式 1 can calculate the differential voltage at the input pins from the digital output.

$$V_{IN} = \frac{Code}{2^N} V_{FS} \quad (1)$$

where

- Code is the signed decimation output code (for example, –2048 to +2047)
- N is the ADC resolution
- and V_{FS} is the full-scale input voltage of the ADC as specified in the *Recommended Operating Conditions* table, including any adjustment performed by programming FS_RANGE_A or FS_RANGE_B

7.3.3.2 ADC Core Calibration

ADC core calibration is required to optimize the analog performance of the ADC cores. Calibration must be repeated when operating conditions change significantly, namely temperature, in order to maintain optimal performance. The ADC08DJ3200 has a built-in calibration routine that can be run as a foreground operation or a background operation. Foreground operation requires ADC downtime, where the ADC is no longer sampling the input signal, to complete the process. Background calibration can be used to overcome this limitation and allow constant operation of the ADC. See the *Calibration Modes and Trimming* section for detailed information on each mode.

7.3.3.3 Analog Reference Voltage

The reference voltage for the ADC08DJ3200 is derived from an internal band-gap reference. A buffered version of the reference voltage is available at the BG pin for user convenience. This output has an output-current capability of ±100 µA. The BG output must be buffered if more current is required. No provision exists for the use of an external reference voltage, but the full-scale input voltage can be adjusted through the full-scale-range register settings. In unique cases, the VA11 supply voltage can act as the reference voltage by setting BG_BYPASS (see the internal reference bypass register).

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7.3.3.4 ADC Overrange Detection

To ensure that system gain management has the quickest possible response time, a low-latency configurable overrange function is included. The overrange function works by monitoring the converted 8-bit samples at the ADC to quickly detect if the ADC is near saturation or already in an overrange condition. The absolute value of the 8 bits of the ADC data are checked against two programmable thresholds, OVR_T0 and OVR_T1. These thresholds apply to both channel A and channel B in dual-channel mode. 表 2 lists how an ADC sample is converted to an absolute value for a comparison of the thresholds.

表 2. Conversion of ADC Sample for Overrange Comparison

ADC SAMPLE (Offset Binary)	ADC SAMPLE (2's Complement)	ABSOLUTE VALUE	8 BITS USED FOR COMPARISON
1111 1111 (255)	0111 1111 (+127)	111 1111 (127)	1111 1111 (255)
1000 0000 (128)	0000 0000 (0)	000 0000 (0)	0000 0000 (0)
0000 0001 (1)	1000 0001 (–127)	111 1111 (127)	1111 1110 (254)
0000 0000 (0)	1000 0000 (–128)	111 1111 (127)	1111 1111 (255)

If the 8 bits of the absolute value equal or exceed the OVR_T0 or OVR_T1 thresholds during the monitoring period, then the overrange bit associated with the threshold is set to 1, otherwise the overrange bit is 0. In dual-channel mode, the overrange status can be monitored on the ORA0 and ORA1 pins for channel A and the ORB0 and ORB1 pins for channel B, where ORx0 corresponds to the OVR_T0 threshold and ORx1 corresponds to the OVR_T1 threshold. In single-channel mode, the overrange status for the OVR_T0 threshold is determined by monitoring both the ORA0 and ORB0 outputs and the OVR_T1 threshold is determined by monitoring both ORA1 and ORB1 outputs. In single-channel mode, the two outputs for each threshold must be OR'd together to determine whether an overrange condition occurred. OVR_N can be used to set the output pulse duration from the last overrange event. 表 3 lists the overrange pulse lengths for the various OVR_N settings (see the overrange configuration register).

表 3. Overrange Monitoring Period for the ORA0, ORA1, ORB0, and ORB1 Outputs

OVR_N	OVERRANGE PULSE LENGTH SINCE LAST OVERRANGE EVENT (DEVCLK Cycles)
0	8
1	16
2	32
3	64
4	128
5	256
6	512
7	1024

Typically, the OVR_T0 threshold can be set near the full-scale value (228 for example). When the threshold is triggered, a typical system can turn down the system gain to avoid clipping. The OVR_T1 threshold can be set much lower. For example, the OVR_T1 threshold can be set to 64 (peak input voltage of −12 dBFS). If the input signal is strong, the OVR_T1 threshold is tripped occasionally. If the input is quite weak, the threshold is never tripped. The downstream logic device monitors the OVR_T1 bit. If OVR_T1 stays low for an extended period of time, then the system gain can be increased until the threshold is occasionally tripped (meaning the peak level of the signal is above −12 dBFS).

7.3.3.5 Code Error Rate (CER)

ADC cores can generate bit errors within a sample, often called *code errors (CER)* or referred to as *sparkle codes*, resulting from metastability caused by non-ideal comparator limitations. The ADC08DJ3200 uses a unique ADC architecture that inherently allows significant code error rate improvements from traditional pipelined flash or successive approximation register (SAR) ADCs. The code error rate of the ADC08DJ3200 is multiple orders of magnitude better than what can be achieved in alternative architectures at equivalent sampling rates providing significant signal reliability improvements.

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7.3.4 Temperature Monitoring Diode

A built-in thermal monitoring diode is made available on the TDIODE+ and TDIODE– pins. This diode facilitates temperature monitoring and characterization of the device in higher ambient temperature environments. Although the on-chip diode is not highly characterized, the diode can be used effectively by performing a baseline measurement (offset) at a known ambient or board temperature and creating a linear equation with the diode voltage slope provided in the *Electrical Characteristics: DC Specifications* table. Perform offset measurement with the device unpowered or with the PD pin asserted to minimize device self-heating. Only assert the PD pin long enough to take the offset measurement. Recommended monitoring devices include the LM95233 device and similar remote-diode temperature monitoring products from Texas Instruments.

7.3.5 Timestamp

The TMSTP+ and TMSTP– differential input can be used as a time-stamp input to mark a specific sample based on the timing of an external trigger event relative to the sampled signal. TIMESTAMP_EN (see the LSB control bit output register) must be set in order to use the timestamp feature and output the timestamp data. When enabled, the LSB of the 8-bit ADC digital output reports the status of the TMSTP± input. In effect, the 8-bit output sample consists of the upper 7-bits of the 8-bit converter and the LSB of the 8-bit output sample is the output of a parallel 1-bit converter (TMSTP±) with the same latency as the ADC core. The trigger must be applied to the differential TMSTP+ and TMSTP– inputs. The trigger can be asynchronous to the ADC sampling clock and is sampled at approximately the same time as the analog input. Timestamp cannot be used when a JMODE with decimation is selected and instead SYSREF must be used to achieve synchronization through the JESD204B subclass-1 method for achieving deterministic latency.

7.3.6 Clocking

The clocking subsystem of the ADC08DJ3200 has two input signals, device clock (CLK+, CLK–) and SYSREF (SYSREF+, SYSREF–). Within the clocking subsystem there is a noiseless aperture delay adjustment (t_{AD} adjust), a clock duty cycle corrector, and a SYSREF capture block. 图 63 describes the clocking subsystem.

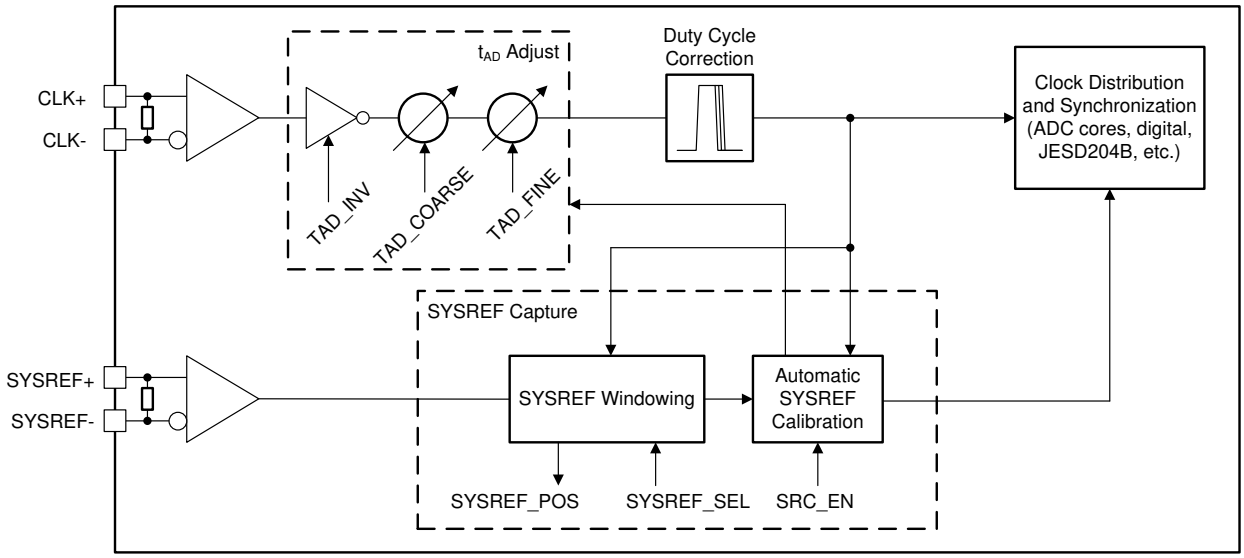


图 63. ADC08DJ3200 Clocking Subsystem

The device clock is used as the sampling clock for the ADC core as well as the clocking for the digital processing and serializer outputs. Use a low-noise (low jitter) device clock to maintain high signal-to-noise ratio (SNR) within the ADC. In dual-channel mode, the analog input signal for each input is sampled on the rising edge of the device clock. In single-channel mode, both the rising and falling edges of the device clock are used to capture the analog signal to reduce the maximum clock rate required by the ADC. A noiseless aperture delay adjustment (t_{AD} adjust) allows the user to shift the sampling instance of the ADC in fine steps in order to synchronize multiple ADC08DJ3200s or to fine-tune system latency. Duty cycle correction is implemented in the ADC08DJ3200 to ease the requirements on the external device clock while maintaining high performance. 表 4 summarizes the device clock interface in dual-channel mode and single-channel mode.

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表 4. Device Clock vs Mode of Operation

MODE OF OPERATION	SAMPLING RATE VS f_{CLK}	SAMPLING INSTANT
Dual-channel mode	1 × f_{CLK}	Rising edge
Single-channel mode	2 × f_{CLK}	Rising and falling edge

SYSREF is a system timing reference used for JESD204B subclass-1 implementations of deterministic latency. SYSREF is used to achieve deterministic latency and for multi-device synchronization. SYSREF must be captured by the correct device clock edge in order to achieve repeatable latency and synchronization. The ADC08DJ3200 includes SYSREF windowing and automatic SYSREF calibration to ease the requirements on the external clocking circuits and to simplify the synchronization process. SYSREF can be implemented as a single pulse or as a periodic clock. In periodic implementations, SYSREF must be equal to, or an integer division of, the local multiframe clock frequency. 公式 2 is used to calculate valid SYSREF frequencies.

$$f_{SYSREF} = \frac{R \times f_{CLK}}{10 \times F \times K \times n} \quad (2)$$

where

- R and F are set by the JMODE setting (see 表 10)
- f_{CLK} is the device clock frequency (CLK±)
- K is the programmed multiframe length (see 表 10 for valid K settings)
- and n is any positive integer

7.3.6.1 Noiseless Aperture Delay Adjustment (t_{AD} Adjust)

The ADC08DJ3200 contains a delay adjustment on the device clock (sampling clock) input path, called t_{AD} adjust, that can be used to shift the sampling instance within the device in order to align sampling instances among multiple devices or for external interleaving of multiple ADC08DJ3200s. Further, t_{AD} adjust can be used for automatic SYSREF calibration to simplify synchronization; see the *Automatic SYSREF Calibration* section. Aperture delay adjustment is implemented in a way that adds no additional noise to the clock path, however a slight degradation in aperture jitter (t_{AJ}) is possible at large values of TAD_COARSE because of internal clock path attenuation. The degradation in aperture jitter can result in minor SNR degradations at high input frequencies (see t_{AJ} in the *Switching Characteristics* table). This feature is programmed using TAD_INV, TAD_COARSE, and TAD_FINE in the DEVCLK timing adjust ramp control register. Setting TAD_INV inverts the input clock resulting in a delay equal to half the clock period. 表 5 summarizes the step sizes and ranges of the TAD_COARSE and TAD_FINE variable analog delays. All three delay options are independent and can be used in conjunction. All clocks within the device are shifted by the programmed t_{AD} adjust amount, which results in a shift of the timing of the JESD204B serialized outputs and affects the capture of SYSREF.

表 5. t_{AD} Adjust Adjustment Ranges

ADJUSTMENT PARAMETER	ADJUSTMENT STEP	DELAY SETTINGS	MAXIMUM DELAY
TAD_INV	1 / (f_{CLK} × 2)	1	1 / (f_{CLK} × 2)
TAD_COARSE	See $t_{TAD(STEP)}$ in the *Switching Characteristics* table	256	See $t_{TAD(MAX)}$ in the *Switching Characteristics* table
TAD_FINE	See $t_{TAD(STEP)}$ in the *Switching Characteristics* table	256	See $t_{TAD(MAX)}$ in the *Switching Characteristics* table

In order to maintain timing alignment between converters, stable and matched power-supply voltages and device temperatures must be provided.

Aperture delay adjustment can be changed on-the-fly during normal operation but may result in brief upsets to the JESD204B data link. Use TAD_RAMP to reduce the probability of the JESD204B link losing synchronization; see the *Aperture Delay Ramp Control (TAD_RAMP)* section.

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7.3.6.2 Aperture Delay Ramp Control (TAD_RAMP)

The ADC08DJ3200 contains a function to gradually adjust the t_{AD} adjust setting towards the newly written TAD_COARSE value. This functionality allows the t_{AD} adjust setting to be adjusted with minimal internal clock circuitry glitches. The TAD_RAMP_RATE parameter allows either a slower (one TAD_COARSE LSB per 256 t_{CLK} cycles) or faster ramp (four TAD_COARSE LSBs per 256 t_{CLK} cycles) to be selected. The TAD_RAMP_EN parameter enables the ramp feature and any subsequent writes to TAD_COARSE initiate a new cramp.

7.3.6.3 SYSREF Capture for Multi-Device Synchronization and Deterministic Latency

The clocking subsystem is largely responsible for achieving multi-device synchronization and deterministic latency. The ADC08DJ3200 uses the JESD204B subclass-1 method to achieve deterministic latency and synchronization. Subclass 1 requires that the SYSREF signal be captured by a deterministic device clock (CLK±) edge at each system power-on and at each device in the system. This requirement imposes setup and hold constraints on SYSREF relative to CLK±, which can be difficult to meet at giga-sample clock rates over all system operating conditions. The ADC08DJ3200 includes a number of features to simplify this synchronization process and to relax system timing constraints:

- The ADC08DJ3200 uses dual-edge sampling (DES) in single-channel mode to reduce the CLK± input frequency by half and double the timing window for SYSREF (see 表 4)
- A SYSREF position detector (relative to CLK±) and selectable SYSREF sampling position aid the user in meeting setup and hold times over all conditions; see the *SYSREF Position Detector and Sampling Position Selection (SYSREF Windowing)* section
- Easy-to-use automatic SYSREF calibration uses the aperture timing adjust block (t_{AD} adjust) to shift the ADC sampling instance based on the phase of SYSREF (rather than adjusting SYSREF based on the phase of the ADC sampling instance); see the *Automatic SYSREF Calibration* section

7.3.6.3.1 SYSREF Position Detector and Sampling Position Selection (SYSREF Windowing)

The SYSREF windowing block is used to first detect the position of SYSREF relative to the CLK± rising edge and then to select a desired SYSREF sampling instance, which is a delay version of CLK±, to maximize setup and hold timing margins. In many cases a single SYSREF sampling position (SYSREF_SEL) is sufficient to meet timing for all systems (device-to-device variation) and conditions (temperature and voltage variations). However, this feature can also be used by the system to expand the timing window by tracking the movement of SYSREF as operating conditions change or to remove system-to-system variation at production test by finding a unique optimal value at nominal conditions for each system.

This section describes proper usage of the SYSREF windowing block. First, apply the device clock and SYSREF to the device. The location of SYSREF relative to the device clock cycle is determined and stored in the SYSREF_POS bits of the SYSREF capture position register. ADC08DJ3200 must see at least 3 rising edges of SYSREF before the SYSREF_POS output is valid. Each bit of SYSREF_POS represents a potential SYSREF sampling position. If a bit in SYSREF_POS is set to 1, then the corresponding SYSREF sampling position has a potential setup or hold violation. Upon determining the valid SYSREF sampling positions (the positions of SYSREF_POS that are set to 0) the desired sampling position can be chosen by setting SYSREF_SEL in the clock control register 0 to the value corresponding to that SYSREF_POS position. In general, the middle sampling position between two setup and hold instances is chosen. Ideally, SYSREF_POS and SYSREF_SEL are performed at the nominal operating conditions of the system (temperature and supply voltage) to provide maximum margin for operating condition variations. This process can be performed at final test and the optimal SYSREF_SEL setting can be stored for use at every system power up. Further, SYSREF_POS can be used to characterize the skew between CLK± and SYSREF± over operating conditions for a system by sweeping the system temperature and supply voltages. For systems that have large variations in CLK± to SYSREF± skew, this characterization can be used to track the optimal SYSREF sampling position as system operating conditions change. In general, a single value can be found that meets timing over all conditions for well-matched systems, such as those where CLK± and SYSREF± come from a single clocking device.

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SYSREF_SEL must be set to 0 when using automatic SYSREF calibration; see the *Automatic SYSREF Calibration* section.

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The step size between each SYSREF_POS sampling position can be adjusted using SYSREF_ZOOM. When SYSREF_ZOOM is set to 0, the delay steps are coarser. When SYSREF_ZOOM is set to 1, the delay steps are finer. See the *Switching Characteristics* table for delay step sizes when SYSREF_ZOOM is enabled and disabled. In general, SYSREF_ZOOM is recommended to always be used (SYSREF_ZOOM = 1) unless a transition region (defined by 1's in SYSREF_POS) is not observed, which can be the case for low clock rates. Bits 0 and 23 of SYSREF_POS are always be set to 1 because there is insufficient information to determine if these settings are close to a timing violation, although the actual valid window can extend beyond these sampling positions. The value programmed into SYSREF_SEL is the decimal number representing the desired bit location in SYSREF_POS. 表 6 lists some example SYSREF_POS readings and the optimal SYSREF_SEL settings. Although 24 sampling positions are provided by the SYSREF_POS status register, SYSREF_SEL only allows selection of the first 16 sampling positions, corresponding to SYSREF_POS bits 0 to 15. The additional SYSREF_POS status bits are intended only to provide additional knowledge of the SYSREF valid window. In general, lower values of SYSREF_SEL are selected because of delay variation over supply voltage, however in the fourth example a value of 15 provides additional margin and can be selected instead.

表 6. Examples of SYSREF_POS Readings and SYSREF_SEL Selections

SYSREF_POS[23:0]			OPTIMAL SYSREF_SEL SETTING
0x02E[7:0] (Largest Delay)	0x02D[7:0](1)	0x02C[7:0](1) (Smallest Delay)	
b10000000	b01100000	b00011001	8 or 9
b10011000	b00000000	b00110001	12
b10000000	b01100000	b00000001	6 or 7
b10000000	b00000011	b00000001	4 or 15
b10001100	b01100011	b00011001	6

(1) Red coloration indicates the bits that are selected, as given in the last column of this table.

7.3.6.3.2 Automatic SYSREF Calibration

The ADC08DJ3200 has an automatic SYSREF calibration feature to alleviate the often challenging setup and hold times associated with capturing SYSREF for giga-sample data converters. Automatic SYSREF calibration uses the t_{AD} adjust feature to shift the device clock to maximize the SYSREF setup and hold times or to align the sampling instance based on the SYSREF rising edge.

The ADC08DJ3200 must have a proper device clock applied and be programmed for normal operation before starting the automatic SYSREF calibration. When ready to initiate automatic SYSREF calibration, a continuous SYSREF signal must be applied. SYSREF must be a continuous (periodic) signal when using the automatic SYSREF calibration. Start the calibration process by setting SRC_EN high in the SYSREF calibration enable register after configuring the automatic SYSREF calibration using the SRC_CFG register. Upon setting SRC_EN high, the ADC08DJ3200 searches for the optimal t_{AD} adjust setting until the device clock falling edge is internally aligned to the SYSREF rising edge. TAD_DONE in the SYSREF calibration status register can be monitored to ensure that the SYSREF calibration has finished. By aligning the device clock falling edge with the SYSREF rising edge, automatic SYSREF calibration maximizes the internal SYSREF setup and hold times relative to the device clock and also sets the sampling instant based on the SYSREF rising edge. After the automatic SYSREF calibration finishes, the rest of the startup procedure can be performed to finish bringing up the system.

For multi-device synchronization, the SYSREF rising edge timing must be matched at all devices and therefore trace lengths must be matched from a common SYSREF source to each ADC08DJ3200. Any skew between the SYSREF rising edge at each device results in additional error in the sampling instance between devices, however repeatable deterministic latency from system startup to startup through each device must still be achieved. No other design requirements are needed in order to achieve multi-device synchronization as long as a proper elastic buffer release point is chosen in the JESD2048 receiver.

图 64 provides a timing diagram of the SYSREF calibration procedure. The optimized setup and hold times are shown as $t_{SU(OPT)}$ and $t_{H(OPT)}$, respectively. Device clock and SYSREF are referred to as *internal* in this diagram because the phase of the internal signals are aligned within the device and not to the external (applied) phase of the device clock or SYSREF.

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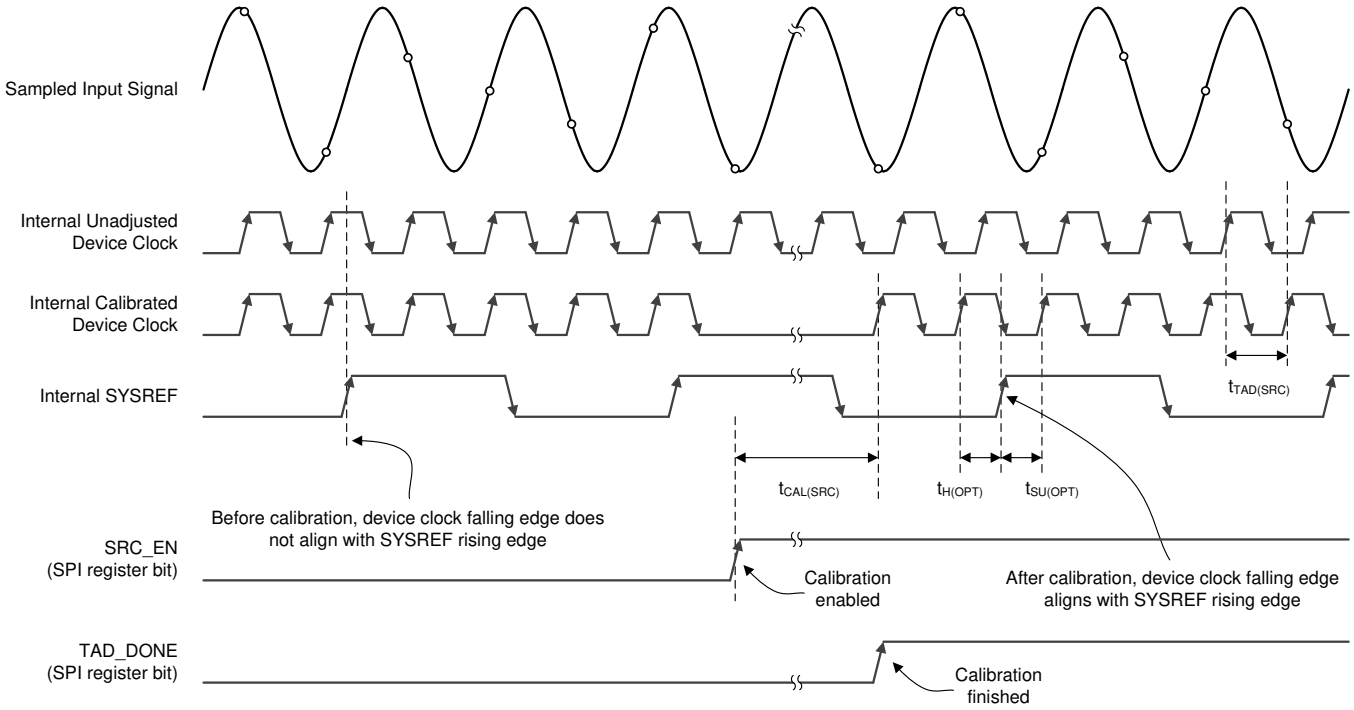


图 64. SYSREF Calibration Timing Diagram

When finished, the t_{AD} adjust setting found by the automatic SYSREF calibration can be read from SRC_TAD in the SYSREF calibration status register. After calibration, the system continues to use the calibrated t_{AD} adjust setting for operation until the system is powered down. However, if desired, the user can then disable the SYSREF calibration and fine-tune the t_{AD} adjust setting according to the systems needs. Alternatively, the use of the automatic SYSREF calibration can be done at product test (or periodic recalibration) of the optimal t_{AD} adjust setting for each system. This value can be stored and written to the TAD register (TAD_INV, TAD_COARSE, and TAD_FINE) upon system startup.

Do not run the SYSREF calibration when the ADC calibration (foreground or background) is running. If background calibration is the desired use case, disable the background calibration when the SYSREF calibration is used, then reenable the background calibration after TAD_DONE goes high. SYSREF_SEL in the clock control register 0 must be set to 0 when using SYSREF calibration.

SYSREF calibration searches the TAD_COARSE delays using both noninverted (TAD_INV = 0) and inverted clock polarity (TAD_INV = 1) to minimize the required TAD_COARSE setting in order to minimize loss on the clock path to reduce aperture jitter (t_{AJ}).

7.3.7 JESD204B Interface

The ADC08DJ3200 uses the JESD204B high-speed serial interface for data converters to transfer data from the ADC to the receiving logic device. The ADC08DJ3200 serialized lanes are capable of operating up to 12.8 Gbps, slightly above the JESD204B maximum lane rate. A maximum of 16 lanes can be used to allow lower lane rates for interfacing with speed-limited logic devices. 图 65 shows a simplified block diagram of the JESD204B interface protocol.

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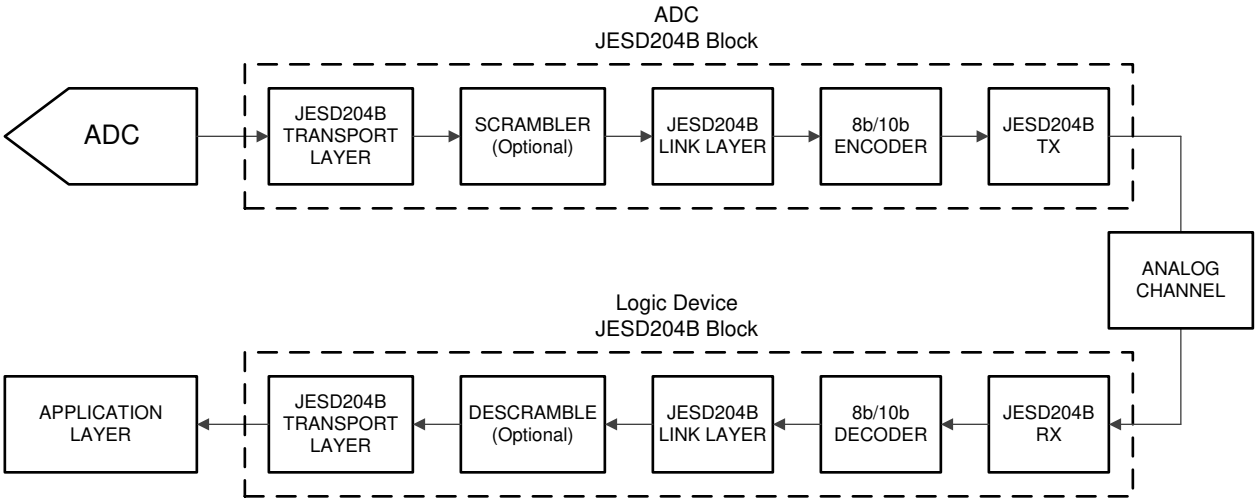


图 65. Simplified JESD204B Interface Diagram

The various signals used in the JESD204B interface and the associated ADC08DJ3200 pin names are summarized briefly in 表 7 for reference.

表 7. Summary of JESD204B Signals

SIGNAL NAME	ADC08DJ3200 PIN NAMES	DESCRIPTION
Data	DA[7:0]+, DA[7:0]–, DB[7:0]+, DB[7:0]–)	High-speed serialized data after 8b, 10b encoding
$\overline{\text{SYNC}}$	$\overline{\text{SYNCSE}}$, TMSTP+, TMSTP–	Link initialization signal, toggles low to start code group synchronization (CGS) process
Device clock	CLK+, CLK–	ADC sampling clock, also used for clocking digital logic and output serializers
SYSREF	SYSREF+, SYSREF–	System timing reference used to deterministically reset the internal local multiframe counters in each JESD204B device

7.3.7.1 Transport Layer

The transport layer takes samples from the ADC output and maps the samples into octets, frames, multiframes, and lanes. Sample mapping is defined by the JESD204B mode that is used, defined by parameters such as L, M, F, S, N, N', CF, and so forth. There are a number of predefined transport layer modes in the ADC08DJ3200 that are defined in 表 10. The high level configuration parameters for the transport layer in the ADC08DJ3200 are described in 表 8. For simplicity, the transport layer mode is chosen by simply setting the JMODE parameter and the desired K value. For reference, the various configuration parameters for JESD204B are defined in 表 9.

7.3.7.2 Scrambler

An optional data scrambler can be used to scramble the octets before transmission across the channel. Scrambling is recommended in order to remove the possibility of spectral peaks in the transmitted data. The JESD204B receiver automatically synchronizes its descrambler to the incoming scrambled data stream. The initial lane alignment sequence (ILA) is never scrambled. Scrambling can be enabled by setting SCR (in the JESD204B control register).

7.3.7.3 Link Layer

The link layer serves multiple purposes in JESD204B, including establishing the code boundaries (see the *Code Group Synchronization (CGS)* section), initializing the link (see the *Initial Lane Alignment Sequence (ILAS)* section), encoding the data (see the *8b, 10b Encoding* section), and monitoring the health of the link (see the *Frame and Multiframe Monitoring* section).

7.3.7.3.1 Code Group Synchronization (CGS)

The first step in initializing the JESD204B link, after SYSREF is processed, is to achieve code group synchronization. The receiver first asserts the SYNC signal when ready to initialize the link. The transmitter responds to the request by sending a stream of K28.5 characters. The receiver then aligns its character clock to the K28.5 character sequence. Code group synchronization is achieved after receiving four K28.5 characters successfully. The receiver deasserts SYNC on the next local multiframe clock (LMFC) edge after CGS is achieved and waits for the transmitter to start the initial lane alignment sequence.

7.3.7.3.2 Initial Lane Alignment Sequence (ILAS)

After the transmitter detects the SYNC signal deassert, the transmitter waits until its next LMFC edge to start sending the initial lane alignment sequence. The ILAS consists of four multiframes each containing a predetermined sequence. The receiver searches for the start of the ILAS to determine the frame and multiframe boundaries. As the ILAS reaches the receiver for each lane, the lane starts to buffer its data until all receivers have received the ILAS and subsequently release the ILAS from all lanes at the same time in order to align the lanes. The second multiframe of the ILAS contains configuration parameters for the JESD204B that can be used by the receiver to verify that the transmitter and receiver configurations match.

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7.3.7.3.3 8b, 10b Encoding

The data link layer converts the 8-bit octets from the transport layer into 10-bit characters for transmission across the link using 8b, 10b encoding. 8b, 10b encoding provides DC balance for AC-coupling of the SerDes links and a sufficient number of edge transitions for the receiver to reliably recover the data clock. 8b, 10b also provides some amount of error detection where a single bit error in a character likely results in either not being able to find the 10-bit character in the 8b, 10b decoder lookup table or incorrect character disparity.

7.3.7.3.4 Frame and Multiframe Monitoring

The ADC08DJ3200 supports frame and multiframe monitoring for verifying the health of the JESD204B link. If the last octet of a frame matches the last octet of the previous frame, then the last octet in the second frame is replaced with an /F/ (/K28.7/) character. If the second frame is the last frame of a multiframe, then an /A/ (/K28.3/) character is used instead. When scrambling is enabled, if the last octet of a frame is 0xFC then the transmitter replaces the octet with an /F/ (/K28.7/) character. With scrambling, if the last octet of a multiframe is 0x7C then the transmitter replaces the octet with an /A/ (/K28.3/) character. When the receiver detects an /F/ or /A/ character, the receiver checks if the character occurs at the end of a frame or multiframe, and replaces that octet with the appropriate data character. The receiver can report an error if the alignment characters occur in the incorrect place and trigger a link realignment.

7.3.7.4 Physical Layer

The JESD204B physical layer consists of a current mode logic (CML) output driver and receiver. The receiver consists of a clock detection and recovery (CDR) unit to extract the data clock from the serialized data stream and can contain an equalizer to correct for the low-pass response of the physical transmission channel. Likewise, the transmitter can contain pre-equalization to account for frequency dependent losses across the channel. The total reach of the SerDes links depends on the data rate, board material, connectors, equalization, noise and jitter, and required bit-error performance. The SerDes lanes do not have to be matched in length because the receiver aligns the lanes during the initial lane alignment sequence.

7.3.7.4.1 SerDes Pre-Emphasis

The ADC08DJ3200 high-speed output drivers can pre-equalize the transmitted data stream by using pre-emphasis in order to compensate for the low-pass response of the transmission channel. Configurable pre-emphasis settings allow the output drive waveform to be optimized for different PCB materials and signal transmission distances. The pre-emphasis setting is adjusted through the serializer pre-emphasis setting SER_PE (in the serializer pre-emphasis control register). Higher values increase the pre-emphasis to compensate for more lossy PCB materials. This adjustment is best used in conjunction with an eye-diagram analysis capability in the receiver. Adjust the pre-emphasis setting to optimize the eye-opening for the specific hardware configuration and line rates needed.

7.3.7.5 JESD204B Enable

The JESD204B interface must be disabled through JESD_EN (in the JESD204B enable register) while any of the other JESD204B parameters are being changed. When JESD_EN is set to 0 the block is held in reset and the serializers are powered down. The clocks for this section are also gated off to further save power. When the parameters are set as desired, the JESD204B block can be enabled (JESD_EN is set to 1).

7.3.7.6 Multi-Device Synchronization and Deterministic Latency

JESD204B subclass 1 outlines a method to achieve deterministic latency across the serial link. If two devices achieve the same deterministic latency then they can be considered synchronized. This latency must be achieved from system startup to startup to be deterministic. There are two key requirements to achieve deterministic latency. The first is proper capture of SYSREF for which the ADC08DJ3200 provides a number of features to simplify this requirement at giga-sample clock rates (see the *SYSREF Capture for Multi-Device Synchronization and Deterministic Latency* section for more information).

The second requirement is to choose a proper elastic buffer release point in the receiver. Because the ADC08DJ3200 is an ADC, the ADC08DJ3200 is the transmitter (TX) in the JESD204B link and the logic device is the receiver (RX). The elastic buffer is the key block for achieving deterministic latency, and does so by absorbing variations in the propagation delays of the serialized data as the data travels from the transmitter to the receiver. A proper release point is one that provides sufficient margin against delay variations. An incorrect

release point results in a latency variation of one LMFC period. Choosing a proper release point requires knowing the average arrival time of data at the elastic buffer, referenced to an LMFC edge, and the total expected delay variation for all devices. With this information the region of invalid release points within the LMFC period can be defined, which stretches from the minimum to maximum delay for all lanes. Essentially, the designer must ensure that the data for all lanes arrives at all devices before the release point occurs.

图 66 provides a timing diagram that demonstrates this requirement. In this figure, the data for two ADCs is shown. The second ADC has a longer routing distance (t_{PCB}) and results in a longer link delay. First, the invalid region of the LMFC period is marked off as determined by the data arrival times for all devices. Then, the release point is set by using the release buffer delay (RBD) parameter to shift the release point an appropriate number of frame clocks from the LMFC edge so that the release point occurs within the valid region of the LMFC cycle. In the case of 图 66, the LMFC edge (RBD = 0) is a good choice for the release point because there is sufficient margin on each side of the valid region.

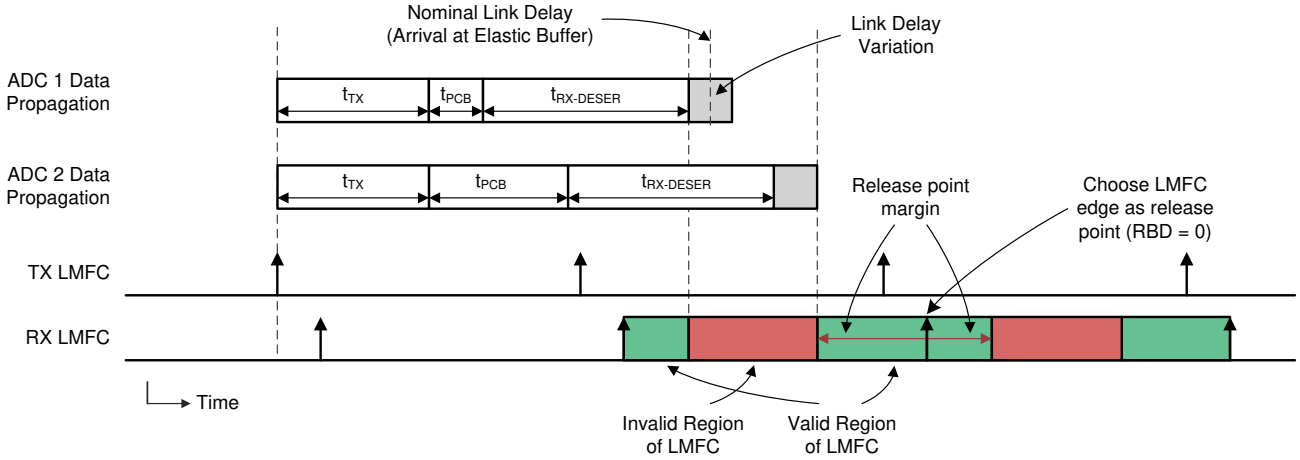


图 66. LMFC Valid Region Definition for Elastic Buffer Release Point Selection

The TX and RX LMFCs do not necessarily need to be phase aligned, but knowledge of their phase is important for proper elastic buffer release point selection. Also, the elastic buffer release point occurs within every LMFC cycle, but the buffers only release when all lanes have arrived. Therefore, the total link delay can exceed a single LMFC period; see *JESD204B multi-device synchronization: Breaking down the requirements* for more information.

7.3.7.7 Operation in Subclass 0 Systems

The ADC08DJ3200 can operate with subclass 0 compatibility provided that multi-ADC synchronization and deterministic latency are not required. With these limitations, the device can operate without the application of SYSREF. The internal local multiframe clock is automatically self-generated with unknown timing. SYNC is used as normal to initiate the CGS and ILA.

7.3.8 Alarm Monitoring

A number of built-in alarms are available to monitor internal events. Several types of alarms and upsets are detected by this feature:

1. Serializer PLL is not locked
2. JESD204B link is not transmitting data (not in the data transmission state)
3. SYSREF causes internal clocks to be realigned
4. An upset that impacts the internal clocks

When an alarm occurs, a bit for each specific alarm is set in ALM_STATUS. Each alarm bit remains set until the host system writes a 1 to clear the alarm. If the alarm type is not masked (see the alarm mask register), then the alarm is also indicated by the ALARM register. The CALSTAT output pin can be configured as an alarm output that goes high when an alarm occurs; see the CAL_STATUS_SEL bit in the calibration pin configuration register.

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7.3.8.1 Clock Upset Detection

The CLK_ALM register bit indicates if the internal clocks have been upset. The clocks in channel A are continuously compared to channel B. If the clocks differ for even one DEVCLK / 2 cycle, the CLK_ALM register bit is set and remains set until cleared by the host system by writing a 1. For the CLK_ALM register bit to function properly, follow these steps:

1. Program JESD_EN = 0
2. Ensure the part is configured to use both channels (PD_ACH = 0, PD_BCH = 0)
3. Program JESD_EN = 1
4. Write CLK_ALM = 1 to clear CLK_ALM
5. Monitor the CLK_ALM status bit or the CALSTAT output pin if CAL_STATUS_SEL is properly configured
6. When exiting global power-down (via MODE or the PD pin), the CLK_ALM status bit may be set and must be cleared by writing a 1 to CLK_ALM

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7.4 Device Functional Modes

The ADC08DJ3200 can be configured to operate in a number of functional modes. These modes are described in this section.

7.4.1 Dual-Channel Mode

The ADC08DJ3200 can be used as a dual-channel ADC where the sampling rate is equal to the clock frequency ($f_S = f_{CLK}$) provided at the CLK+ and CLK– pins. The two inputs, INA± and INB±, serve as the respective inputs for each channel in this mode. This mode is chosen simply by setting JMODE to the appropriate setting for the desired configuration as described in 表 10. The analog inputs can be swapped by setting DUAL_INPUT (see the input mux control register)

7.4.2 Single-Channel Mode (DES Mode)

The ADC08DJ3200 can also be used as a single-channel ADC where the sampling rate is equal to two times the clock frequency ($f_S = 2 \times f_{CLK}$) provided at the CLK+ and CLK– pins. This mode effectively interleaves the two ADC channels together to form a single-channel ADC at twice the sampling rate. This mode is chosen simply by setting JMODE to the appropriate setting for the desired configuration as described in 表 10. Either analog input, INA± or INB±, can serve as the input to the ADC, however INA± is recommended for best performance. The analog input can be selected using SINGLE_INPUT (see the input mux control register). The digital down-converters cannot be used in single-channel mode.

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INA± is strongly recommended to be used as the input to the ADC for optimized performance in single-channel mode.

7.4.3 JESD204B Modes

The ADC08DJ3200 can be programmed as a single-channel or dual-channel ADC and a number JESD204B output formats. 表 8 summarizes the basic operating mode configuration parameters and whether they are user configured or derived.

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Powering down high-speed data outputs (DA0± ... DA7±, DB0± ... DB7±) for extended times can reduce performance of the output serializers, especially at high data rates. For information regarding reliable serializer operation, see the *Power-Down Modes* section.

表 8. ADC08DJ3200 Operating Mode Configuration Parameters

PARAMETER	DESCRIPTION	USER CONFIGURED OR DERIVED	VALUE
JMODE	JESD204B operating mode, automatically derives the rest of the JESD204B parameters, single-channel or dual-channel mode	User configured	Set by JMODE (see the JESD204B mode register)
D	Decimation factor	Derived	See 表 10
DES	1 = single-channel mode, 0 = dual-channel mode	Derived	See 表 10
R	Number of bits transmitted per lane per DEVCLK cycle. The JESD204B line rate is the DEVCLK frequency times R. This parameter sets the SerDes PLL multiplication factor or controls bypassing of the SerDes PLL.	Derived	See 表 10
Links	Number of JESD204B links used	Derived	See 表 10
K	Number of frames per multiframe	User configured	Set by KM1 (see the JESD204B K parameter register), see the allowed values in 表 10

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There are a number of parameters required to define the JESD204B format, all of which are sent across the link during the initial lane alignment sequence. In the ADC08DJ3200, most parameters are automatically derived based on the selected JMODE; however, a few are configured by the user. 表 9 describes these parameters.

表 9. JESD204B Initial Lane Alignment Sequence Parameters

PARAMETER	DESCRIPTION	USER CONFIGURED OR DERIVED	VALUE
ADJCNT	LMFC adjustment amount (not applicable)	Derived	Always 0
ADJDIR	LMFC adjustment direction (not applicable)	Derived	Always 0
BID	Bank ID	Derived	Always 0
CF	Number of control words per frame	Derived	Always 0
CS	Control bits per sample	Derived	Always set to 0 in ILAS, see 表 10 for actual usage
DID	Device identifier, used to identify the link	User configured	Set by DID (see the JESD204B DID parameter register), see 表 11
F	Number of octets (bytes) per frame (per lane)	Derived	See 表 10
HD	High-density format (samples split between lanes)	Derived	Always 0
JESDV	JESD204 standard revision	Derived	Always 1
K	Number of frames per multiframe	User configured	Set by the KM1 register, see the JESD204B K parameter register
L	Number of serial output lanes per link	Derived	See 表 10
LID	Lane identifier for each lane	Derived	See 表 11
M	Number of converters used to determine lane bit packing; may not match number of ADC channels in the device	Derived	See 表 10
N	Sample resolution (before adding control and tail bits)	Derived	See 表 10
N'	Bits per sample after adding control and tail bits	Derived	See 表 10
S	Number of samples per converter (M) per frame	Derived	See 表 10
SCR	Scrambler enabled	User configured	Set by the JESD204B control register
SUBCLASSV	Device subclass version	Derived	Always 1
RES1	Reserved field 1	Derived	Always 0
RES2	Reserved field 2	Derived	Always 0
CHKSUM	Checksum for ILAS checking (sum of all above parameters modulo 256)	Derived	Computed based on parameters in this table

Configuring the ADC08DJ3200 is made easy by using a single configuration parameter called JMODE (see the JESD204B mode register). Using 表 10, the correct JMODE value can be found for the desired operating mode. The modes listed in 表 10 are the only available operating modes. This table also gives a range and allowable step size for the K parameter (set by KM1, see the JESD204B K parameter register), which sets the multiframe length in number of frames.

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表 10. ADC08DJ3200 Operating Modes

ADC08DJ3200 OPERATING MODE	USER-SPECIFIED PARAMETER		DERIVED PARAMETERS											INPUT CLOCK RANGE (MHz)
	JMODE	K [Min:Step:Max]	D	DES	LINKS	N	CS	N'	L (Per Link)	M (Per Link)	F	S	R (Fbit / Fclk)	
Reserved	0-3	—	—	—	—	—	—	—	—	—	—	—	—	—
8-bit, single-channel, 4 lanes	4	18:2:32	1	1	2	8	0	8	2	1	1	2	5	800-2560
8-bit, single-channel, 8 lanes	5	18:2:32	1	1	2	8	0	8	4	1	1	4	2.5	800-3200
8-bit, dual-channel, 4 lanes	6	18:2:32	1	0	2	8	0	8	2	1	1	2	5	800-2560
8-bit, dual-channel, 8 lanes	7	18:2:32	1	0	2	8	0	8	4	1	1	4	2.5	800-3200
Reserved	8-16	—	—	—	—	—	—	—	—	—	—	—	—	—
8-bit, single-channel, 16 lanes	17	18:2:32	1	1	2	8	0	8	8	1	1	8	1.25	800-3200
8-bit, dual-channel, 16 lanes	18	18:2:32	1	0	2	8	0	8	8	1	1	8	1.25	800-3200

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The ADC08DJ3200 has a total of 16 high-speed output drivers that are grouped into two 8-lane JESD204B links. Most operating modes use two links with up to eight lanes per link. The lanes and their derived configuration parameters are described in 表 11. For a specified JMODE, the lowest indexed lanes for each link are used and the higher indexed lanes for each link are automatically powered down. Always route the lowest indexed lanes to the logic device.

表 11. ADC08DJ3200 Lane Assignment and Parameters

DEVICE PIN DESIGNATION	LINK	DID (User Configured)	LID (Derived)
DA0±	A	Set by DID (see the JESD204B DID parameter register), the effective DID is equal to the DID register setting (DID)	0
DA1±			1
DA2±			2
DA3±			3
DA4±			4
DA5±			5
DA6±			6
DA7±			7
DB0±	B	Set by DID (see the JESD204B DID parameter register), the effective DID is equal to the DID register setting plus 1 (DID+1)	0
DB1±			1
DB2±			2
DB3±			3
DB4±			4
DB5±			5
DB6±			6
DB7±			7

7.4.3.1 JESD204B Output Data Formats

Output data are formatted in a specific optimized fashion for each JMODE setting. The following tables show the specific mapping formats for a single frame. In all mappings the tail bits (T) are 0 (zero). In 表 12 to 表 17, the single-channel format samples are defined as Sn, where n is the sample number within the frame. In the dual-channel output formats, the samples are defined as An and Bn, where An are samples from channel A and Bn are samples from channel B. All samples are formatted as MSB first, LSB last.

表 12. JMODE 4 (8-Bit, Decimate-by-1, Single-Channel, 4 Lanes)

OCTET	0	
NIBBLE	0	1
DA0	S0	
DA1	S2	
DB0	S1	
DB1	S3	

表 13. JMODE 5 (8-Bit, Decimate-by-1, Single-Channel, 8 Lanes)

OCTET	0	
NIBBLE	0	1
DA0	S0	
DA1	S2	
DA2	S4	
DA3	S6	
DB0	S1	
DB1	S3	
DB2	S5	
DB3	S7	

表 14. JMODE 6 (8-Bit, Decimate-by-1, Dual-Channel, 4 Lanes)

OCTET	0	
NIBBLE	0	1
DA0	A0	
DA1	A1	
DB0	B0	
DB1	B1	

表 15. JMODE 7 (8-Bit, Decimate-by-1, Dual-Channel, 8 Lanes)

OCTET	0	
NIBBLE	0	1
DA0	A0	
DA1	A1	
DA2	A2	
DA3	A3	
DB0	B0	
DB1	B1	
DB2	B2	
DB3	B3	

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表 16. JMODE 17 (8-bit, Decimate-by-1, Single-Channel, 16 lanes)

OCTET	0	
NIBBLE	0	1
DA0	S0	
DA1	S2	
DA2	S4	
DA3	S6	
DA4	S8	
DA5	S10	
DA6	S12	
DA7	S14	
DB0	S1	
DB1	S3	
DB2	S5	
DB3	S7	
DB4	S9	
DB5	S11	
DB6	S13	
DB7	S15	

表 17. JMODE 18 (8-Bit, Decimate-by-1, Dual-Channel, 16 Lanes)

OCTET	0	
NIBBLE	0	1
DA0	A0	
DA1	A1	
DA2	A2	
DA3	A3	
DA4	A4	
DA5	A5	
DA6	A6	
DA7	A7	
DB0	B0	
DB1	B1	
DB2	B2	
DB3	B3	
DB4	B4	
DB5	B5	
DB6	B6	
DB7	B7	

7.4.4 Power-Down Modes

The PD input pin allows the ADC08DJ3200 devices to be entirely powered down. Power-down can also be controlled by MODE (see the device configuration register). The serial data output drivers are disabled when PD is high. When the device returns to normal operation, the JESD204 link must be re-established, and the ADC pipeline contain meaningless information so the system must wait a sufficient time for the data to be flushed. If power-down for power savings is desired, the system must power down the supply voltages regulators for VA19, VA11, and VD11 rather than make use of the PD input or MODE settings.

CAUTION

Powering down the high-speed data outputs (DA0± ... DA7±, DB0± ... DB7±) for extended times may damage the output serializers, especially at high data rates. Powering down the serializers occurs when the PD pin is held high, the MODE register is programmed to a value other than 0x00 or 0x01, the PD_ACH or PD_BCH registers settings are programmed to 1, or when the JMODE register setting is programmed to a mode that uses less than the 16 total lanes that the device allows. For instance, JMODE 0 uses eight total lanes and therefore the four highest-indexed lanes for each JESD204B link (DA4± ... DA7±, DB4± ... DB7±) are powered down in this mode. When the PD pin is held high or the MODE register is programmed to a value other than 0x00 or 0x01, all output serializers are powered down. When the PD_ACH or PD_BCH register settings are programmed to 1, the associated ADC channel and lanes are powered down. To prevent unreliable operation, the PD pin and MODE register must only be used for brief periods of time to measure temperature diode offsets and not used for long-term power savings. Furthermore, using a JMODE that uses fewer than 16 lanes results in unreliable operation of the unused lanes. If the system never uses the unused lanes during the lifetime of the device, then the unused lanes do not cause issues and can be powered down. If the system may make use of the unused lanes at a later time, the reliable operation of the serializer outputs can be maintained by enabling JEXTRA_A and JEXTRA_B, which results in the VD11 power consumption to increase and the output serializers to toggle.

7.4.5 Test Modes

A number of device test modes are available. These modes insert known patterns of information into the device data path for assistance with system debug, development, or characterization.

7.4.5.1 Serializer Test-Mode Details

Test modes are enabled by setting JTEST (see the JESD204B test pattern control register) to the desired test mode. Each test mode is described in detail in the following sections. Regardless of the test mode, the serializer outputs are powered up based on JMODE. Only enable the test modes when the JESD204B link is disabled. 图 67 provides a diagram showing the various test mode insertion points.

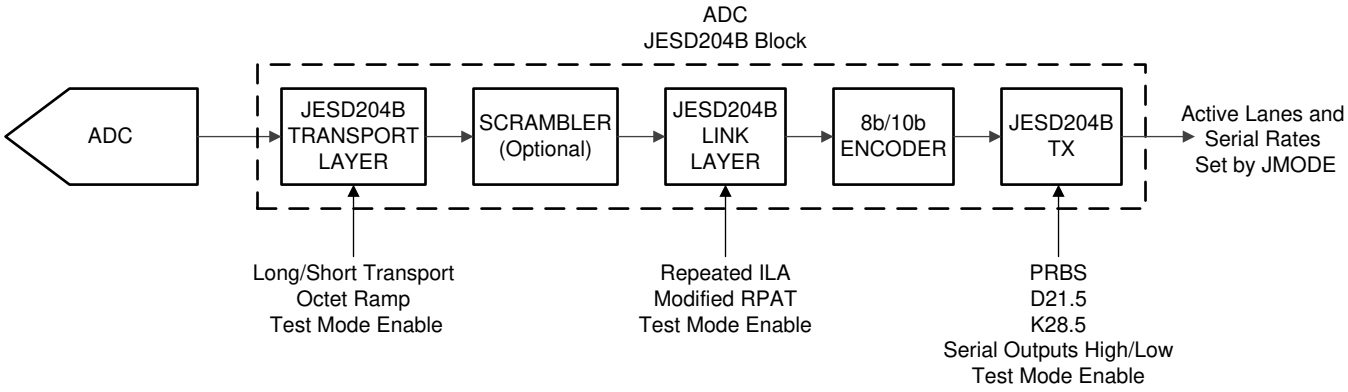


图 67. Test Mode Insertion Points

7.4.5.2 PRBS Test Modes

The PRBS test modes bypass the 8b, 10b encoder. These test modes produce pseudo-random bit streams that comply with the ITU-T O.150 specification. These bit streams are used with lab test equipment that can self-synchronize to the bit pattern and, therefore, the initial phase of the pattern is not defined.

The sequences are defined by a recursive equation. For example, 公式 3 defines the PRBS7 sequence.

$$y[n] = y[n - 6] \oplus y[n - 7] \quad (3)$$

where

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- bit n is the XOR of bit [n – 6] and bit [n – 7], which are previously transmitted bits (3)

表 18 lists equations and sequence lengths for the available PRBS test modes. The initial phase of the pattern is unique for each lane.

表 18. PBRS Mode Equations

PRBS TEST MODE	SEQUENCE	SEQUENCE LENGTH (bits)
PRBS7	y[n] = y[n – 6]⊕y[n – 7]	127
PRBS15	y[n] = y[n – 14]⊕y[n – 15]	32767
PRBS23	y[n] = y[n – 18]⊕y[n – 23]	8388607

7.4.5.3 Ramp Test Mode

In the ramp test mode, the JESD204B link layer operates normally, but the transport layer is disabled and the input from the formatter is ignored. After the ILA sequence, each lane transmits an identical octet stream that increments from 0x00 to 0xFF and repeats.

7.4.5.4 Short and Long Transport Test Mode

JESD204B defines both short and long transport test modes to verify that the transport layers in the transmitter and receiver are operating correctly. The ADC08DJ3200 only supports the short transport test pattern.

7.4.5.4.1 Short Transport Test Pattern

Short transport test patterns send a predefined octet format that repeats every frame. In the ADC08DJ3200, all JMODE configurations that have an N' value of 8 use the short transport test pattern. 表 19 define the short transport test patterns for N' values of 8. All applicable lanes are shown, however only the enabled lanes (lowest indexed) for the configured JMODE are used.

表 19. Short Transport Test Pattern for N' = 8 Modes (Length = 2 Frames)

FRAME	0	1
DA0	0x00	0xFF
DA1	0x01	0xFE
DA2	0x02	0xFD
DA3	0x03	0xFC
DB0	0x00	0xFF
DB1	0x01	0xFE
DB2	0x02	0xFD
DB3	0x03	0xFC

7.4.5.5 D21.5 Test Mode

In this test mode, the controller transmits a continuous stream of D21.5 characters (alternating 0s and 1s).

7.4.5.6 K28.5 Test Mode

In this test mode, the controller transmits a continuous stream of K28.5 characters.

7.4.5.7 Repeated ILA Test Mode

In this test mode, the JESD204B link layer operates normally, except that the ILA sequence (ILAS) repeats indefinitely instead of starting the data phase. Whenever the receiver issues a synchronization request, the transmitter initiates code group synchronization. Upon completion of code group synchronization, the transmitter repeatedly transmits the ILA sequence.

7.4.5.8 Modified RPAT Test Mode

A 12-octet repeating pattern is defined in INCITS TR-35-2004. The purpose of this pattern is to generate white spectral content for JESD204B compliance and jitter testing. 表 20 lists the pattern before and after 8b, 10b encoding.

表 20. Modified RPAT Pattern Values

OCTET NUMBER	Dx.y NOTATION	8-BIT INPUT TO 8b, 10b ENCODER	20b OUTPUT OF 8b, 10b ENCODER (Two Characters)
0	D30.5	0xBE	0x86BA6
1	D23.6	0xD7	
2	D3.1	0x23	0xC6475
3	D7.2	0x47	
4	D11.3	0x6B	0xD0E8D
5	D15.4	0x8F	
6	D19.5	0xB3	0xCA8B4
7	D20.0	0x14	
8	D30.2	0x5E	0x7949E
9	D27.7	0xFB	
10	D21.1	0x35	0xAA665
11	D25.2	0x59	

7.4.6 Calibration Modes and Trimming

The ADC08DJ3200 has two calibration modes available: foreground calibration and background calibration. When foreground calibration is initiated the ADCs are automatically taken offline and the output data becomes mid-code (0x000 in 2's complement) while a calibration is occurring. Background calibration allows the ADC to continue normal operation while the ADC cores are calibrated in the background by swapping in a different ADC core to take its place. Additional offset calibration features are available in both foreground and background calibration modes. Further, a number of ADC parameters can be trimmed to optimize performance in a user system.

The ADC08DJ3200 consists of a total of six sub-ADCs, each referred to as a *bank*, with two banks forming an *ADC core*. The banks sample out-of-phase so that each ADC core is two-way interleaved. The six banks form three ADC cores, referred to as ADC A, ADC B, and ADC C. In foreground calibration mode, ADC A samples INA± and ADC B samples INB± in dual-channel mode and both ADC A and ADC B sample INA± (or INB±) in single-channel mode. In the background calibration modes, the third ADC core, ADC C, is swapped in periodically for ADC A and ADC B so that they can be calibrated without disrupting operation. 图 68 provides a diagram of the calibration system including labeling of the banks that make up each ADC core. When calibration is performed the linearity, gain, and offset voltage for each bank are calibrated to an internally generated calibration signal. The analog inputs can be driven during calibration, both foreground and background, except that when offset calibration (OS_CAL or BGOS_CAL) is used there must be no signals (or aliased signals) near DC for proper estimation of the offset (see the *Offset Calibration* section).

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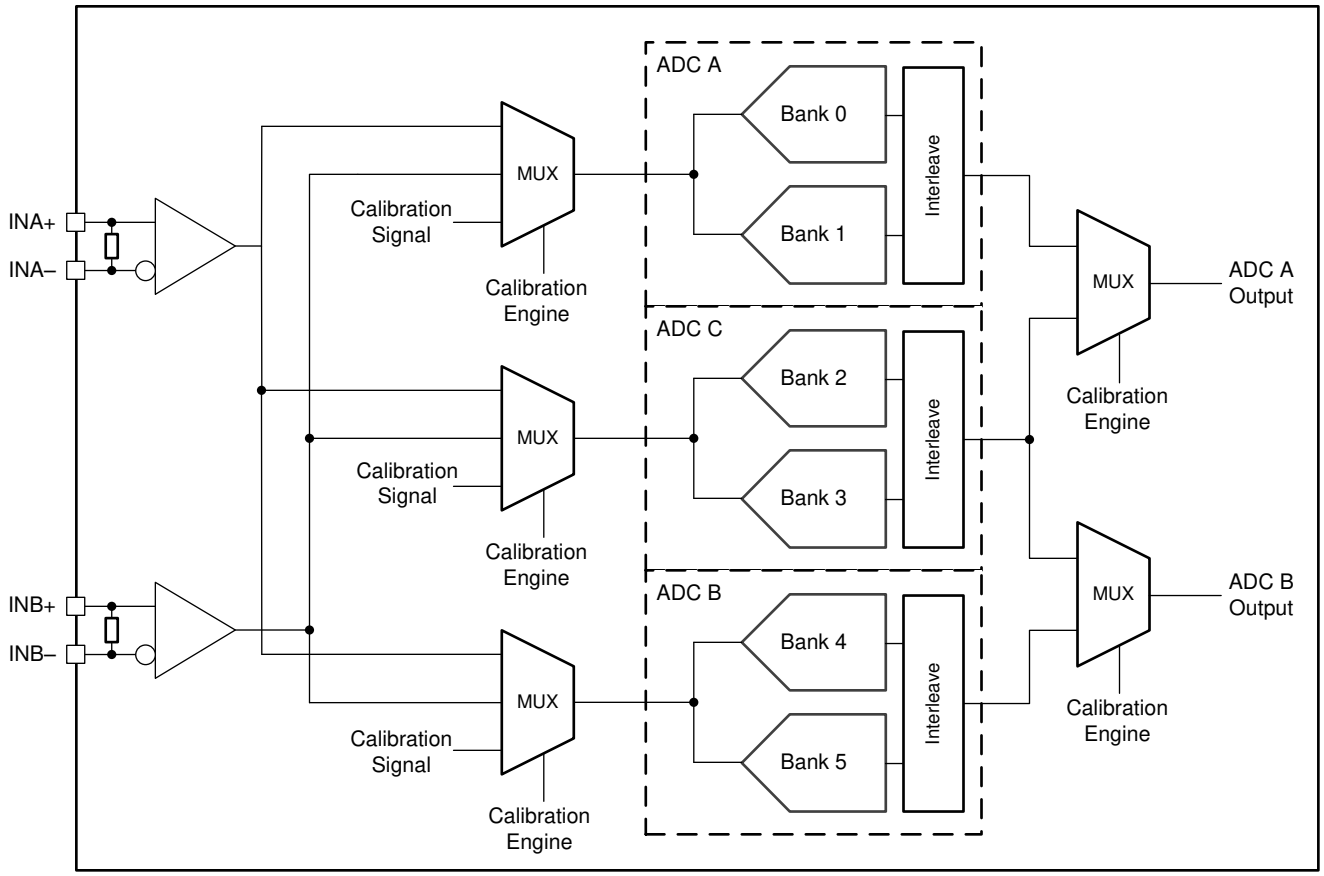


图 68. ADC08DJ3200 Calibration System Block Diagram

In addition to calibration, a number of ADC parameters are user controllable to provide trimming for optimal performance. These parameters include input offset voltage, ADC gain, interleaving timing, and input termination resistance. The default trim values are programmed at the factory to unique values for each device that are determined to be optimal at the test system operating conditions. The user can read the factory-programmed values from the trim registers and adjust as desired. The register fields that control the trimming are labeled according to the input that is being sampled (INA± or INB±), the bank that is being trimmed, or the ADC core that is being trimmed. The user is not expected to change the trim values as operating conditions change, however optimal performance can be obtained by doing so. Any custom trimming must be done on a per device basis because of process variations, meaning that there is no global optimal setting for all parts. See the *Trimming* section for information about the available trim parameters and associated registers.

7.4.6.1 Foreground Calibration Mode

Foreground calibration requires the ADC to stop converting the analog input signals during the procedure. Foreground calibration always runs on power-up and the user must wait a sufficient time before programming the device to ensure that the calibration is finished. Foreground calibration can be initiated by triggering the calibration engine. The trigger source can be either the CAL_TRIG pin or CAL_SOFT_TRIG (see the calibration software trigger register) and is chosen by setting CAL_TRIG_EN (see the calibration pin configuration register).

7.4.6.2 Background Calibration Mode

Background calibration mode allows the ADC to continuously operate, with no interruption of data. This continuous operation is accomplished by activating an extra ADC core that is calibrated and then takes over operation for one of the other previously active ADC cores. When that ADC core is taken off-line, that ADC is calibrated and can in turn take over to allow the next ADC to be calibrated. This process operates continuously, ensuring the ADC cores always provide the optimum performance regardless of system operating condition changes. Because of the additional active ADC core, background calibration mode has increased power

consumption in comparison to foreground calibration mode. The low-power background calibration (LPBG) mode discussed in the *Low-Power Background Calibration (LPBG) Mode* section provides reduced average power consumption in comparison with the standard background calibration mode. Background calibration can be enabled by setting CAL_BG (see the calibration configuration 0 register). CAL_TRIG_EN must be set to 0 and CAL_SOFT_TRIG must be set to 1.

Great care has been taken to minimize effects on converted data as the core switching process occurs, however, small brief glitches may still occur on the converter data as the cores are swapped. See the *Typical Characteristics* section for examples of possible glitches in sine-wave and DC signals.

7.4.6.3 Low-Power Background Calibration (LPBG) Mode

Low-power background calibration (LPBG) mode reduces the power-overhead of enabling the additional ADC core while still allowing background calibration of the ADC cores to maintain optimal performance as operating conditions change. LPBG calibration modifies the background calibration procedure by powering down the spare ADC core until it is ready to be calibrated. Set LP_EN = 1 to enable the low-power background calibration feature. Calibration and swapping of ADC cores can be controlled either automatically by the device or manually by the system by setting LP_TRIG appropriately. Manual control (LP_TRIG=1) allows the system to trigger calibration in order to limit the number of calibration cycles that occur to avoid unnecessary core swaps or to keep power consumption at a minimum. For instance, the user may decide to run calibration only when the system temperature changes by some fixed temperature. If manual control is not necessary the automatic calibration control can be enabled (LP_TRIG=0) to calibrate at fixed time intervals.

In automatic calibration mode (LP_TRIG=0) the spare ADC core sleep time can be controlled by the LP_SLEEP_DLY register setting. LP_SLEEP_DLY is used to adjust the amount of time an ADC sleeps before waking up for calibration (when LP_EN=1 and LP_TRIG = 0). LP_WAKE_DLY sets how long the core is allowed to stabilize after being awoken before calibration begins. In automatic calibration control mode the freshly calibrated core is swapped in for an active core as soon as calibration finishes and the new spare core is powered down for the sleep duration before waking up and calibrating.

Manual calibration control is enabled by setting LP_TRIG high in order to use the calibration trigger (CAL_SOFT_TRIG or CALTRIG) to trigger calibrations and core swaps. When manual control is enabled (LP_TRIG=1) the spare ADC is held in sleep mode while the calibration trigger is high. Setting the calibration trigger low then wakes up the spare ADC core and starts the calibration routine after waiting for the specified wake delay (LP_WAKE_DLY). The spare ADC core is swapped in for an active core once calibration is complete and the calibration trigger is set high again. If the calibration trigger is held low, then the spare ADC core calibrates and remains powered until the calibration trigger goes high; therefore consuming power. can report when the spare ADC finishes calibration on the CALSTAT output pin by setting the CALSTAT pin to output the CAL_STOPPED signal (CAL_STATUS_SEL = 1). For lowest power consumption, set the calibration trigger high before calibration finishes to allow the spare ADC to swap in for an active ADC core as soon as calibration finishes. Otherwise, the ADC core swap can be timed manually by setting the calibration trigger high at the desired time to minimize system impact of potential glitches caused by the swapping procedure.

In LPBG mode there is an increase in power consumption during the ADC core calibration. The longer the spare ADC is held asleep the lower the average power consumption, however large shifts in operating conditions during the sleep cycle may cause degraded ADC performance due to non-optimized calibration data for the active ADC core. The power consumption roughly alternates between the power consumption in foreground calibration when the spare ADC core is sleeping to the power consumption in background calibration when the spare ADC is being calibrated. Design the power-supply network to handle the transient power requirements for this mode, including bulk capacitance after any power supply filtering network to help regulate the supply voltage during the supply transient.

7.4.7 Offset Calibration

Foreground calibration and background calibration modes inherently calibrate the offsets of the ADC cores; however, the input buffers sit outside of the calibration loop and therefore their offsets are not calibrated by the standard calibration process. In both dual-channel mode and single-channel mode, uncalibrated input buffer offsets result in a shift in the mid-code output (DC offset) with no input. Further, in single-channel mode uncalibrated input buffer offsets can result in a fixed spur at f_S / 2. A separate calibration is provided to correct the input buffer offsets.

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There must be no signals at or near DC or aliased signals that fall at or near DC in order to properly calibration the offsets, requiring the system to ensure this condition during normal operation or have the ability to mute the input signal during calibration. Foreground offset calibration is enabled via CAL_OS and only performs the calibration one time as part of the foreground calibration procedure. Background offset calibration is enabled via CAL_BGOS and continues to correct the offset as part of the background calibration routine to account for operating condition changes. When CAL_BGOS is set, the system must ensure that there are no DC or near DC signals or aliased signals that fall at or near DC during normal operation. Offset calibration can be performed as a foreground operation when using background calibration by setting CAL_OS to 1 before setting CAL_EN, but does not correct for variations as operating conditions change.

The offset calibration correction uses the input offset voltage trim registers (see 表 21) to correct the offset and therefore must not be written by the user when offset calibration is used. The user can read the calibrated values by reading the OADJ_x_VINy registers, where x is the ADC core and y is the input (INA± or INB±), after calibration is completed. Only read the values when FG_DONE is read as 1 when using foreground offset calibration (CAL_OS = 1) and do not read the values when using background offset calibration (CAL_BGOS = 1). Setting CAL_OS to 1 and CAL_BG to 1 performs an offset calibration of all three ADC cores during the foreground calibration process.

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7.4.8 Trimming

表 21 lists the parameters that can be trimmed and the associated registers. User trimming is limited to foreground (FG) calibration only.

表 21. Trim Register Descriptions

TRIM PARAMETER	TRIM REGISTER	NOTES
Band-gap reference	BG_TRIM	Measurement on BG output pin.
Input termination resistance	RTRIM_x, where x = A for INA± or B for INB±)	The device must be powered on with a clock applied.
Input offset voltage	OADJ_x_VINy, where x = ADC core (A or B) and y = A for INA± or B for INB±)	Input offset adjustment in dual channel mode consists of changing OADJ_A_VINA for channel A and OADJ_B_VINB for channel B. In single channel mode, OADJ_A_VINx and OADJ_B_VINx must be adjusted together to trim the input offset or adjusted separate to compensate the $f_S/2$ offset spur.
INA± and INB± gain	GAIN_TRIM_x, where x = A for INA± or B for INB±)	Set FS_RANGE_A and FS_RANGE_B to default values before trimming the input. Use FS_RANGE_A and FS_RANGE_B to adjust the full-scale input voltage. To trim the gain of ADC core A, change GAIN_B0 and GAIN_B1 together in the same direction. To trim the gain of ADC core B, change GAIN_B4 and GAIN_B5 together in the same direction. To trim the gain of the two banks within ADC A, change GAIN_B0 and GAIN_B1 in opposite directions. To trim the gain of the two banks within ADC B, change GAIN_B4 and GAIN_B5 in opposite directions.
INA± and INB± full-scale input voltage	FS_RANGE_x, where x = A for INA± or B for INB±)	Full-scale input voltage adjustment for each input. The default value is effected by GAIN_TRIM_x (x = A or B). Trim GAIN_TRIM_x with FS_RANGE_x set to the default value. FS_RANGE_x can then be used to trim the full-scale input voltage.
Intra-ADC core timing (bank timing)	Bx_TIME_y, where x = bank number (0, 1, 4 or 5) and y = 0° or –90° clock phase	Trims the timing between the two banks of an ADC core (ADC A or B). The 0° clock phase is used for dual channel mode and for ADC B in single channel mode. The –90° clock phase is used only for ADC A in single-channel mode. A mismatch in the timing between the two banks of an ADC core can result in an $f_S/2$-f_{IN} spur in dual channel mode or $f_S/4 \pm f_{IN}$ spurs in single channel mode.
Inter-ADC core timing (dual-channel mode)	TADJ_A, TADJ_B	The suffix letter (A or B) indicates the ADC core that is being trimmed. Changing either TADJ_A or TADJ_B adjusts the sampling instance of ADC A relative to ADC B in dual channel mode.
Inter-ADC core timing (single-channel mode)	TADJ_A_FG90, TADJ_B_FG0	These trim registers are used to adjust the timing of ADC core A relative to ADC core B in single channel mode. A mismatch in the timing results in an $f_S/2$-f_{IN} spur that is signal dependent. Changing either TADJ_A_FG90 or TADJ_B_FG0 changes the relative timing of ADC core A relative to ADC core B in single channel mode. These registers are trimmed at production to optimize performance for INA±.

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7.4.9 Offset Filtering

The ADC08DJ3200 has an additional feature that can be enabled to reduce offset-related interleaving spurs at f_S / 2 and f_S / 4 (single input mode only). Offset filtering is enabled via CAL_OSFILT. The OSFILT_BW and OSFILT_SOAK parameters can be adjusted to tradeoff offset spur reduction with potential impact on information in the mission mode signal being processed. Set these two parameters to the same value under most situations. The DC_RESTORE setting is used to either retain or filter out all DC-related content in the signal. This feature implements a notch filter at f_S / 2 and f_S / 4 (single input mode only) and also filters out signals that fall at these frequency locations. Reducing the notch filter bandwidth using OSFILT_BW can reduce the range of signals that are filtered by this feature.

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7.5 Programming

7.5.1 Using the Serial Interface

The serial interface is accessed using the following four pins: serial clock (SCLK), serial data in (SDI), serial data out (SDO), and serial interface chip-select ($\overline{SCS}$). Register access is enabled through the $\overline{SCS}$ pin.

7.5.1.1 $\overline{SCS}$

This signal must be asserted low to access a register through the serial interface. Setup and hold times with respect to the SCLK must be observed.

7.5.1.2 SCLK

Serial data input is accepted at the rising edge of this signal. SCLK has no minimum frequency requirement.

7.5.1.3 SDI

Each register access requires a specific 24-bit pattern at this input. This pattern consists of a read-and-write (R/W) bit, register address, and register value. The data are shifted in MSB first and multi-byte registers are always in little-endian format (least significant byte stored at the lowest address). Setup and hold times with respect to the SCLK must be observed (see the *Timing Requirements* table).

7.5.1.4 SDO

The SDO signal provides the output data requested by a read command. This output is high impedance during write bus cycles and during the read bit and register address portion of read bus cycles.

As shown in 图 69, each register access consists of 24 bits. The first bit is high for a read and low for a write.

The next 15 bits are the address of the register that is to be written to. During write operations, the last eight bits are the data written to the addressed register. During read operations, the last eight bits on SDI are ignored and, during this time, the SDO outputs the data from the addressed register. 图 69 shows the serial protocol details.

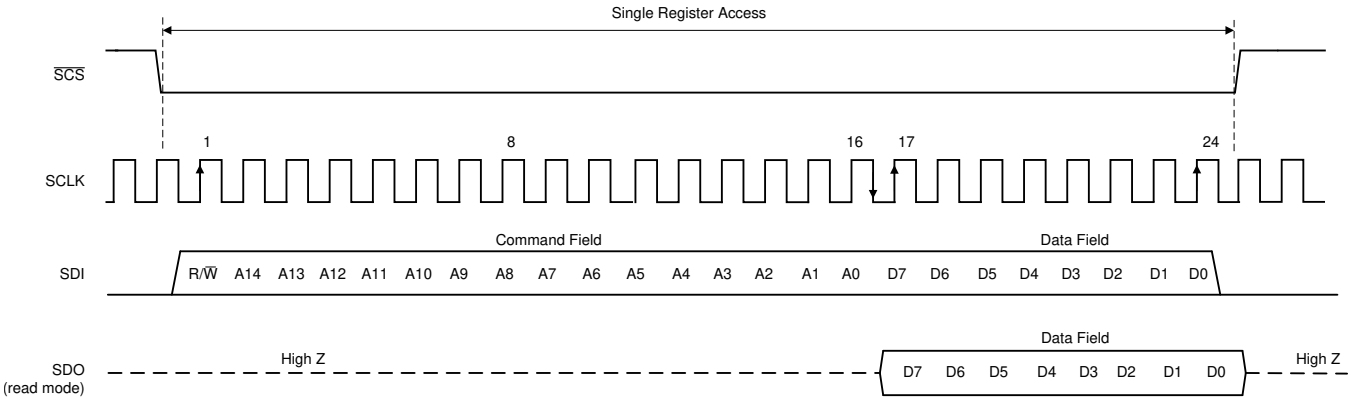


图 69. Serial Interface Protocol: Single Read/Write

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Programming (接下页)

7.5.1.5 Streaming Mode

The serial interface supports streaming reads and writes. In this mode, the initial 24 bits of the transaction specifics the access type, register address, and data value as normal. Additional clock cycles of write or read data are immediately transferred, as long as the SCS input is maintained in the asserted (logic low) state. The register address auto increments (default) or decrements for each subsequent 8-bit transfer of the streaming transaction. The ADDR_ASC bit (register 000h, bits 5 and 2) controls whether the address value ascends (increments) or descends (decrements). Streaming mode can be disabled by setting the ADDR_HOLD bit (see the user SPI configuration register). 图 70 shows the streaming mode transaction details.

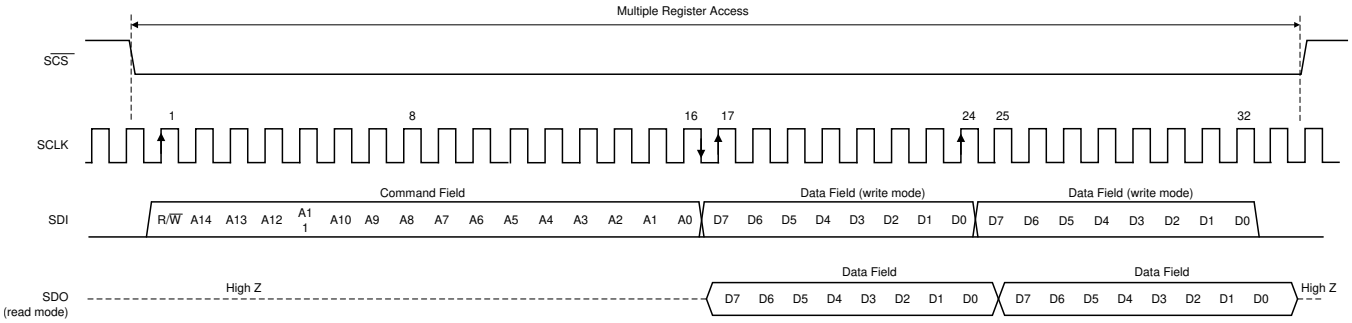


图 70. Serial Interface Protocol: Streaming Read/Write

See the *Register Maps* section for detailed information regarding the registers.

注

The serial interface must not be accessed during ADC calibration. Accessing the serial interface during this time impairs the performance of the device until the device is calibrated correctly. Writing or reading the serial registers also reduces dynamic ADC performance for the duration of the register access time.

7.6 Register Maps

The Memory Map lists all the ADC08DJ3200 registers.

Memory Map

ADDRESS	RESET	ACRONYM	TYPE	REGISTER NAME
STANDARD SPI-3.0 (0x000 to 0x00F)				
0x000	0x30	CONFIG_A	R/W	Configuration A Register
0x001	Undefined	RESERVED	R	RESERVED
0x002	0x00	DEVICE_CONFIG	R/W	Device Configuration Register
0x003	0x03	CHIP_TYPE	R	Chip Type Register
0x004-0x005	0x0020	CHIP_ID	R	Chip ID Registers
0x006	0x0A	CHIP_VERSION	R	Chip Version Register
0x007-0x00B	Undefined	RESERVED	R	RESERVED
0x00C-0x00D	0x0451	VENDOR_ID	R	Vendor Identification Register
0x00E-0x00F	Undefined	RESERVED	R	RESERVED
USER SPI CONFIGURATION (0x010 to 0x01F)				
0x010	0x00	USR0	R/W	User SPI Configuration Register
0x011-0x01F	Undefined	RESERVED	R	RESERVED

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Register Maps (continued)

Memory Map (continued)

ADDRESS	RESET	ACRONYM	TYPE	REGISTER NAME
MISCELLANEOUS ANALOG REGISTERS (0x020 to 0x047)				
0x020-0x028	Undefined	RESERVED	R	RESERVED
0x029	0x00	CLK_CTRL0	R/W	Clock Control Register 0
0x02A	0x20	CLK_CTRL1	R/W	Clock Control Register 1
0x02B	Undefined	RESERVED	R	RESERVED
0x02C-0x02E	Undefined	SYSREF_POS	R	SYSREF Capture Position Register
0x02F	Undefined	RESERVED	R	RESERVED
0x030-0x031	0xA000	FS_RANGE_A	R/W	INA Full-Scale Range Adjust Register
0x032-0x033	0xA000	FS_RANGE_B	R/W	INB Full-Scale Range Adjust Register
0x034-0x037	Undefined	RESERVED	R	RESERVED
0x038	0x00	BG_BYPASS	R/W	Internal Reference Bypass Register
0x039-0x03A	Undefined	RESERVED	R	RESERVED
0x03B	0x00	TMSTP_CTRL	R/W	TMSTP± Control Register
0x03C-0x047	Undefined	RESERVED	R	RESERVED
SERIALIZER REGISTERS (0x048 to 0x05F)				
0x048	0x00	SER_PE	R/W	Serializer Pre-Emphasis Control Register
0x049-0x05F	Undefined	RESERVED	R	RESERVED
CALIBRATION REGISTERS (0x060 to 0x0FF)				
0x060	0x01	INPUT_MUX	R/W	Input Mux Control Register
0x061	0x01	CAL_EN	R/W	Calibration Enable Register
0x062	0x01	CAL_CFG0	R/W	Calibration Configuration 0 Register
0x063-0x069	Undefined	RESERVED	R	RESERVED
0x06A	Undefined	CAL_STATUS	R	Calibration Status Register
0x06B	0x00	CAL_PIN_CFG	R/W	Calibration Pin Configuration Register
0x06C	0x01	CAL_SOFT_TRIG	R/W	Calibration Software Trigger Register
0x06D	Undefined	RESERVED	R	RESERVED
0x06E	0x88	CAL_LP	R/W	Low-Power Background Calibration Register
0x06F	Undefined	RESERVED	R	RESERVED
0x070	0x00	CAL_DATA_EN	R/W	Calibration Data Enable Register
0x071	Undefined	CAL_DATA	R/W	Calibration Data Register
0x072-0x079	Undefined	RESERVED	R	RESERVED
0x07A	Undefined	GAIN_TRIM_A	R/W	Channel A Gain Trim Register
0x07B	Undefined	GAIN_TRIM_B	R/W	Channel B Gain Trim Register
0x07C	Undefined	BG_TRIM	R/W	Band-Gap Reference Trim Register
0x07D	Undefined	RESERVED	R	RESERVED
0x07E	Undefined	RTRIM_A	R/W	VINA Input Resistor Trim Register
0x07F	Undefined	RTRIM_B	R/W	VINB Input Resistor Trim Register
0x080	Undefined	TADJ_A_FG90	R/W	Timing Adjustment for A-ADC, Single-Channel Mode, Foreground Calibration Register
0x081	Undefined	TADJ_B_FG0	R/W	Timing Adjustment for B-ADC, Single-Channel Mode, Foreground Calibration Register
0x082	Undefined	TADJ_A_BG90	R/W	Timing Adjustment for A-ADC, Single-Channel Mode, Background Calibration Register
0x083	Undefined	TADJ_C_BG0	R/W	Timing Adjustment for C-ADC, Single-Channel Mode, Background Calibration Register
0x084	Undefined	TADJ_C_BG90	R/W	Timing Adjustment for C-ADC, Single-Channel Mode, Background Calibration Register

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Register Maps (continued)

Memory Map (continued)

ADDRESS	RESET	ACRONYM	TYPE	REGISTER NAME
0x085	Undefined	TADJ_B_BG0	R/W	Timing Adjustment for B-ADC, Single-Channel Mode, Background Calibration Register
0x086	Undefined	TADJ_A	R/W	Timing Adjustment for A-ADC, Dual-Channel Mode Register
0x087	Undefined	TADJ_CA	R/W	Timing Adjustment for C-ADC Acting for A-ADC, Dual-Channel Mode Register
0x088	Undefined	TADJ_CB	R/W	Timing Adjustment for C-ADC Acting for B-ADC, Dual-Channel Mode Register
0x089	Undefined	TADJ_B	R/W	Timing Adjustment for B-ADC, Dual-Channel Mode Register
0x08A-0x08B	Undefined	OADJ_A_INA	R/W	Offset Adjustment for A-ADC and INA Register
0x08C-0x08D	Undefined	OADJ_A_INB	R/W	Offset Adjustment for A-ADC and INB Register
0x08E-0x08F	Undefined	OADJ_C_INA	R/W	Offset Adjustment for C-ADC and INA Register
0x090-0x091	Undefined	OADJ_C_INB	R/W	Offset Adjustment for C-ADC and INB Register
0x092-0x093	Undefined	OADJ_B_INA	R/W	Offset Adjustment for B-ADC and INA Register
0x094-0x095	Undefined	OADJ_B_INB	R/W	Offset Adjustment for B-ADC and INB Register
0x096	Undefined	RESERVED	R	RESERVED
0x097	0x00	OSFILT0	R/W	Offset Filtering Control 0
0x098	0x33	OSFILT1	R/W	Offset Filtering Control 1
0x099-0x0FF	Undefined	RESERVED	R	RESERVED
ADC BANK REGISTERS (0x100 to 0x15F)				
0x100-0x101	Undefined	RESERVED	R	RESERVED
0x102	Undefined	B0_TIME_0	R/W	Timing Adjustment for Bank 0 (0° Clock) Register
0x103	Undefined	B0_TIME_90	R/W	Timing Adjustment for Bank 0 (–90° Clock) Register
0x104-0x111	Undefined	RESERVED	R	RESERVED
0x112	Undefined	B1_TIME_0	R/W	Timing Adjustment for Bank 1 (0° Clock) Register
0x113	Undefined	B1_TIME_90	R/W	Timing Adjustment for Bank 1 (–90° Clock) Register
0x114-0x121	Undefined	RESERVED	R	RESERVED
0x122	Undefined	B2_TIME_0	R/W	Timing Adjustment for Bank 2 (0° Clock) Register
0x123	Undefined	B2_TIME_90	R/W	Timing Adjustment for Bank 2 (–90° Clock) Register
0x124-0x131	Undefined	RESERVED	R	RESERVED
0x132	Undefined	B3_TIME_0	R/W	Timing Adjustment for Bank 3 (0° Clock) Register
0x133	Undefined	B3_TIME_90	R/W	Timing Adjustment for Bank 3 (–90° Clock) Register
0x134-0x141	Undefined	RESERVED	R	RESERVED
0x142	Undefined	B4_TIME_0	R/W	Timing Adjustment for Bank 4 (0° Clock) Register
0x143	Undefined	B4_TIME_90	R/W	Timing Adjustment for Bank 4 (–90° Clock) Register
0x144-0x151	Undefined	RESERVED	R	RESERVED
0x152	Undefined	B5_TIME_0	R/W	Timing Adjustment for Bank 5 (0° Clock) Register
0x153	Undefined	B5_TIME_90	R/W	Timing Adjustment for Bank 5 (–90° Clock) Register
0x154-0x15F	Undefined	RESERVED	R	RESERVED
LSB CONTROL REGISTERS (0x160 to 0x1FF)				
0x160	0x00	ENC_LSB	R/W	LSB Control Bit Output Register
0x161-0x1FF	Undefined	RESERVED	R	RESERVED
JESD204B REGISTERS (0x200 to 0x20F)				
0x200	0x01	JESD_EN	R/W	JESD204B Enable Register
0x201	0x02	JMODE	R/W	JESD204B Mode (JMODE) Register
0x202	0x1F	KM1	R/W	JESD204B K Parameter Register
0x203	0x01	JSYNC_N	R/W	JESD204B Manual SYNC Request Register
0x204	0x02	JCTRL	R/W	JESD204B Control Register

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Register Maps (continued)

Memory Map (continued)

ADDRESS	RESET	ACRONYM	TYPE	REGISTER NAME
0x205	0x00	JTEST	R/W	JESD204B Test Pattern Control Register
0x206	0x00	DID	R/W	JESD204B DID Parameter Register
0x207	0x00	FCHAR	R/W	JESD204B Frame Character Register
0x208	Undefined	JESD_STATUS	R/W	JESD204B, System Status Register
0x209	0x00	PD_CH	R/W	JESD204B Channel Power-Down
0x20A	0x00	JEXTRA_A	R/W	JESD204B Extra Lane Enable (Link A)
0x20B	0x00	JEXTRA_B	R/W	JESD204B Extra Lane Enable (Link B)
0x20C-0x210	Undefined	RESERVED	R	RESERVED
DIGITAL DOWN CONVERTER REGISTERS (0x210-0x2AF)				
0x211	0xF2	OVR_T0	R/W	Overrange Threshold 0 Register
0x212	0xAB	OVR_T1	R/W	Overrange Threshold 1 Register
0x213	0x07	OVR_CFG	R/W	Overrange Configuration Register
0x214-0x296	Undefined	RESERVED	R	RESERVED
0x297	Undefined	SPIN_ID	R	Spin Identification Value
0x298-0x2AF	Undefined	RESERVED	R	RESERVED
SYSREF CALIBRATION REGISTERS (0x2B0 to 0x2BF)				
0x2B0	0x00	SRC_EN	R/W	SYSREF Calibration Enable Register
0x2B1	0x05	SRC_CFG	R/W	SYSREF Calibration Configuration Register
0x2B2-0x2B4	Undefined	SRC_STATUS	R	SYSREF Calibration Status
0x2B5-0x2B7	0x00	TAD	R/W	DEVCLK Aperture Delay Adjustment Register
0x2B8	0x00	TAD_RAMP	R/W	DEVCLK Timing Adjust Ramp Control Register
0x2B9-0x2BF	Undefined	RESERVED	R	RESERVED
ALARM REGISTERS (0x2C0 to 0x2C2)				
0x2C0	Undefined	ALARM	R	Alarm Interrupt Status Register
0x2C1	0x1F	ALM_STATUS	R/W	Alarm Status Register
0x2C2	0x1F	ALM_MASK	R/W	Alarm Mask Register

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7.6.1 Register Descriptions

Table 22 lists the access codes for the ADC08DJ3200 registers.

Table 22. ADC08DJ3200 Access Type Codes

Access Type	Code	Description
R	R	Read
R-W	R/W	Read or write
W	W	Write
-n		Value after reset or the default value

7.6.1.1 Standard SPI-3.0 (0x000 to 0x00F)

Table 23. Standard SPI-3.0 Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x000	0x30	CONFIG_A	Configuration A Register	Configuration A Register (address = 0x000) [reset = 0x30]
0x001	Undefined	RESERVED	RESERVED	—
0x002	0x00	DEVICE_CONFIG	Device Configuration Register	Device Configuration Register (address = 0x002) [reset = 0x00]
0x003	0x03	CHIP_TYPE	Chip Type Register	Chip Type Register (address = 0x003) [reset = 0x03]
0x004-0x005	0x0020	CHIP_ID	Chip ID Registers	Chip ID Register (address = 0x004 to 0x005) [reset = 0x0020]
0x006	0x0A	CHIP_VERSION	Chip Version Register	Chip Version Register (address = 0x006) [reset = 0x01]
0x007-0x00B	Undefined	RESERVED	RESERVED	—
0x00C-0x00D	0x0451	VENDOR_ID	Vendor Identification Register	Vendor Identification Register (address = 0x00C to 0x00D) [reset = 0x0451]
0x00E-0x00F	Undefined	RESERVED	RESERVED	—

7.6.1.1.1 Configuration A Register (address = 0x000) [reset = 0x30]

Figure 71. Configuration A Register (CONFIG_A)

7	6	5	4	3	2	1	0
SOFT_RESET	RESERVED	ADDR_ASC	SDO_ACTIVE	RESERVED			
R/W-0	R-0	R/W-1	R-1	R-0000			

Table 24. CONFIG_A Field Descriptions

Bit	Field	Type	Reset	Description
7	SOFT_RESET	R/W	0	Setting this bit results in a full reset of the device. This bit is self-clearing. After writing this bit, the device may take up to 750 ns to reset. During this time, do not perform any SPI transactions.
6	RESERVED	R	0	RESERVED
5	ADDR_ASC	R/W	1	0: Descend – decrement address while streaming reads/writes 1: Ascend – increment address while streaming reads/writes (default)
4	SDO_ACTIVE	R	1	Always returns 1, indicating that the device always uses 4-wire SPI mode.
3-0	RESERVED	R	0000	RESERVED

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7.6.1.1.2 Device Configuration Register (address = 0x002) [reset = 0x00]

Figure 72. Device Configuration Register (DEVICE_CONFIG)

7	6	5	4	3	2	1	0
RESERVED						MODE	
R-0000 00						R/W-00	

Table 25. DEVICE_CONFIG Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	0000 00	RESERVED
1-0	MODE	R/W	00	The SPI 3.0 specification lists 1 as the low-power functional mode, 2 as the low-power fast resume, and 3 as power-down. This device does not support these modes. 0: Normal operation – full power and full performance (default) 1: Normal operation – full power and full performance 2: Power down - everything is powered down. Only use this setting for brief periods of time to calibrate the on-chip temperature diode measurement. See the *Recommended Operating Conditions* table for more information. 3: Power down - everything is powered down. Only use this setting for brief periods of time to calibrate the on-chip temperature diode measurement. See the *Recommended Operating Conditions* table for more information.

7.6.1.1.3 Chip Type Register (address = 0x003) [reset = 0x03]

Figure 73. Chip Type Register (CHIP_TYPE)

7	6	5	4	3	2	1	0
RESERVED				CHIP_TYPE			
R-0000				R-0011			

Table 26. CHIP_TYPE Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000	RESERVED
3-0	CHIP_TYPE	R	0011	Always returns 0x3, indicating that the device is a high-speed ADC.

7.6.1.1.4 Chip ID Register (address = 0x004 to 0x005) [reset = 0x0020]

Figure 74. Chip ID Register (CHIP_ID)

15	14	13	12	11	10	9	8
CHIP_ID[15:8]							
R-0x00h							
7	6	5	4	3	2	1	0
CHIP_ID[7:0]							
R-0x20h							

Table 27. CHIP_ID Field Descriptions

Bit	Field	Type	Reset	Description
15-0	CHIP_ID	R	0x0020h	Always returns 0x0020, indicating that this device is part of the ADC08DJxx00 family.

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7.6.1.1.5 Chip Version Register (address = 0x006) [reset = 0x01]

Figure 75. Chip Version Register (CHIP_VERSION)

7	6	5	4	3	2	1	0
CHIP_VERSION							
R-0000 1010							

Table 28. CHIP_VERSION Field Descriptions

Bit	Field	Type	Reset	Description
7-0	CHIP_VERSION	R	0000 1010	Chip version, returns 0x0A.

7.6.1.1.6 Vendor Identification Register (address = 0x00C to 0x00D) [reset = 0x0451]

Figure 76. Vendor Identification Register (VENDOR_ID)

15	14	13	12	11	10	9	8
VENDOR_ID[15:8]							
R-0x04h							
7	6	5	4	3	2	1	0
VENDOR_ID[7:0]							
R-0x51h							

Table 29. VENDOR_ID Field Descriptions

Bit	Field	Type	Reset	Description
15-0	VENDOR_ID	R	0x0451h	Always returns 0x0451 (TI vendor ID).

7.6.1.2 User SPI Configuration (0x010 to 0x01F)

Table 30. User SPI Configuration Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x010	0x00	USR0	User SPI Configuration Register	User SPI Configuration Register (address = 0x010) [reset = 0x00]
0x011-0x01F	Undefined	RESERVED	RESERVED	—

7.6.1.2.1 User SPI Configuration Register (address = 0x010) [reset = 0x00]

Figure 77. User SPI Configuration Register (USR0)

7	6	5	4	3	2	1	0
RESERVED							ADDR_HOLD
R-0000 000							R/W-0

Table 31. USR0 Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	ADDR_HOLD	R/W	0	0: Use the ADDR_ASC bit to define what happens to the address during streaming (default) 1: Address remains static throughout streaming operation; this setting is useful for reading/writing calibration vector information at the CAL_DATA register

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7.6.1.3 Miscellaneous Analog Registers (0x020 to 0x047)

Table 32. Miscellaneous Analog Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x020-0x028	Undefined	RESERVED	RESERVED	—
0x029	0x00	CLK_CTRL0	Clock Control Register 0	Clock Control Register 0 (address = 0x029) [reset = 0x00]
0x02A	0x20	CLK_CTRL1	Clock Control Register 1	Clock Control Register 1 (address = 0x02A) [reset = 0x00]
0x02B	Undefined	RESERVED	RESERVED	—
0x02C-0x02E	Undefined	SYSREF_POS	SYSREF Capture Position Register	SYSREF Capture Position Register (address = 0x02C-0x02E) [reset = Undefined]
0x02F	Undefined	RESERVED	RESERVED	—
0x030-0x031	0xA000	FS_RANGE_A	INA Full-Scale Range Adjust Register	INA Full-Scale Range Adjust Register (address = 0x030-0x031) [reset = 0xA000]
0x032-0x033	0xA000	FS_RANGE_B	INB Full-Scale Range Adjust Register	INB Full-Scale Range Adjust Register (address = 0x032-0x033) [reset = 0xA000]
0x034-0x037	Undefined	RESERVED	RESERVED	—
0x038	0x00	BG_BYPASS	Internal Reference Bypass Register	Internal Reference Bypass Register (address = 0x038) [reset = 0x00]
0x039-0x03A	Undefined	RESERVED	RESERVED	—
0x03B	0x00	SYNC_CTRL	TMSTP± Control Register	TMSTP± Control Register (address = 0x03B) [reset = 0x00]
0x03C-0x047	Undefined	RESERVED	RESERVED	—

7.6.1.3.1 Clock Control Register 0 (address = 0x029) [reset = 0x00]

Figure 78. Clock Control Register 0 (CLK_CTRL0)

7	6	5	4	3	2	1	0
RESERVED	SYSREF_PROC_EN	SYSREF_RECV_EN	SYSREF_ZOOM	SYSREF_SEL			
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0000			

Table 33. CLK_CTRL0 Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	RESERVED
6	SYSREF_PROC_EN	R/W	0	This bit enables the SYSREF processor. This bit must be set to allow the device to process SYSREF events. SYSREF_RECV_EN must be set before setting SYSREF_PROC_EN.
5	SYSREF_RECV_EN	R/W	0	Set this bit to enable the SYSREF receiver circuit.
4	SYSREF_ZOOM	R/W	0	Set this bit to *zoom* in the SYSREF strobe status (affects SYSREF_POS).
3-0	SYSREF_SEL	R/W	0000	Set this field to select which SYSREF delay to use. Set this field based on the results returned by SYSREF_POS. Set this field to 0 to use SYSREF calibration.

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7.6.1.3.2 Clock Control Register 1 (address = 0x02A) [reset = 0x00]

Figure 79. Clock Control Register 1 (CLK_CTRL1)

7	6	5	4	3	2	1	0
RESERVED					DEVCLK_LVPECL_EN	SYSREF_LVPECL_EN	SYSREF_INVERTED
R/W-0010 0					R/W-0	R/W-0	R/W-0

Table 34. CLK_CTRL1 Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	0010 0	RESERVED
2	DEVCLK_LVPECL_EN	R/W	0	Activate low-voltage PECL mode for DEVCLK.
1	SYSREF_LVPECL_EN	R/W	0	Activate low-voltage PECL mode for SYSREF.
0	SYSREF_INVERTED	R/W	0	Inverts the SYSREF signal used for alignment.

7.6.1.3.3 SYSREF Capture Position Register (address = 0x02C-0x02E) [reset = Undefined]

Figure 80. SYSREF Capture Position Register (SYSREF_POS)

23	22	21	20	19	18	17	16
SYSREF_POS[23:16]							
R-Undefined							
15	14	13	12	11	10	9	8
SYSREF_POS[15:8]							
R-Undefined							
7	6	5	4	3	2	1	0
SYSREF_POS[7:0]							
R-Undefined							

Table 35. SYSREF_POS Field Descriptions

Bit	Field	Type	Reset	Description
23-0	SYSREF_POS	R	Undefined	This field returns a 24-bit status value that indicates the position of the SYSREF edge with respect to DEVCLK. Use this field to program SYSREF_SEL.

7.6.1.3.4 INA Full-Scale Range Adjust Register (address = 0x030-0x031) [reset = 0xA000]

Figure 81. INA Full-Scale Range Adjust Register (FS_RANGE_A)

15	14	13	12	11	10	9	8
FS_RANGE_A[15:8]							
R/W-0xA0h							
7	6	5	4	3	2	1	0
FS_RANGE_A[7:0]							
R/W-0x00h							

Table 36. FS_RANGE_A Field Descriptions

Bit	Field	Type	Reset	Description
15-0	FS_RANGE_A	R/W	0xA000h	This field enables adjustment of the analog full-scale range for INA. 0x0000: Settings below 0x2000 may result in degraded device performance 0x2000: 500 mV_{PP} - Recommended minimum setting 0xA000: 800 mV_{PP} (default) 0xFFFF: 1000 mV_{PP}

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7.6.1.3.5 INB Full-Scale Range Adjust Register (address = 0x032-0x033) [reset = 0xA000]

Figure 82. INB Full Scale Range Adjust Register (FS_RANGE_B)

15	14	13	12	11	10	9	8
FS_RANGE_B[15:8]							
R/W-0xA0							
7	6	5	4	3	2	1	0
FS_RANGE_B[7:0]							
R/W-0x00							

Table 37. FS_RANGE_B Field Descriptions

Bit	Field	Type	Reset	Description
15-0	FS_RANGE_B	R/W	0xA000h	This field enables adjustment of the analog full-scale range for INB. 0x0000: Settings below 0x2000 may result in degraded device performance 0x2000: 500 mV_{PP} - Recommended minimum setting 0xA000: 800 mV_{PP} (default) 0xFFFF: 1000 mV_{PP}

7.6.1.3.6 Internal Reference Bypass Register (address = 0x038) [reset = 0x00]

Figure 83. Internal Reference Bypass Register (BG_BYPASS)

7	6	5	4	3	2	1	0
RESERVED							BG_BYPASS
R/W-0000 000							R/W-0

Table 38. BG_BYPASS Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	BG_BYPASS	R/W	0	When set, VA11 is used as the voltage reference instead of the internal reference.

7.6.1.3.7 TMSTP± Control Register (address = 0x03B) [reset = 0x00]

Figure 84. TMSTP± Control Register (TMSTP_CTRL)

7	6	5	4	3	2	1	0
RESERVED						TMSTP_LVPECL_EN	TMSTP_RECV_EN
R/W-0000 00						R/W-0	R/W-0

Table 39. TMSTP_CTRL Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R/W	0000 00	RESERVED
1	TMSTP_LVPECL_EN	R/W	0	When set, this bit activates the low-voltage PECL mode for the differential TMSTP± input.
0	TMSTP_RECV_EN	R/W	0	This bit enables the differential TMSTP± input.

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7.6.1.4 Serializer Registers (0x048 to 0x05F)

Table 40. Serializer Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x048	0x00	SER_PE	Serializer Pre-Emphasis Control Register	Serializer Pre-Emphasis Control Register (address = 0x048) [reset = 0x00]
0x049-0x05F	Undefined	RESERVED	RESERVED	—

7.6.1.4.1 Serializer Pre-Emphasis Control Register (address = 0x048) [reset = 0x00]

Figure 85. Serializer Pre-Emphasis Control Register (SER_PE)

7	6	5	4	3	2	1	0
RESERVED				SER_PE			
R/W-0000				R/W-0000			

Table 41. SER_PE Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	RESERVED
3-0	SER_PE	R/W	0000	This field sets the pre-emphasis for the serial lanes to compensate for the low-pass response of the PCB trace. This setting is a global setting that affects all 16 lanes.

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7.6.1.5 Calibration Registers (0x060 to 0x0FF)

Table 42. Calibration Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x060	0x01	INPUT_MUX	Input Mux Control Register	Input Mux Control Register (address = 0x060) [reset = 0x01]
0x061	0x01	CAL_EN	Calibration Enable Register	Calibration Enable Register (address = 0x061) [reset = 0x01]
0x062	0x01	CAL_CFG0	Calibration Configuration 0 Register	Calibration Configuration 0 Register (address = 0x062) [reset = 0x01]
0x063-0x069	Undefined	RESERVED	RESERVED	—
0x06A	Undefined	CAL_STATUS	Calibration Status Register	Calibration Status Register (address = 0x06A) [reset = Undefined]
0x06B	0x00	CAL_PIN_CFG	Calibration Pin Configuration Register	Calibration Pin Configuration Register (address = 0x06B) [reset = 0x00]
0x06C	0x01	CAL_SOFT_TRIG	Calibration Software Trigger Register	Calibration Software Trigger Register (address = 0x06C) [reset = 0x01]
0x06D	Undefined	RESERVED	RESERVED	—
0x06E	0x88	CAL_LP	Low-Power Background Calibration Register	Low-Power Background Calibration Register (address = 0x06E) [reset = 0x88]
0x06F	Undefined	RESERVED	RESERVED	—
0x070	0x00	CAL_DATA_EN	Calibration Data Enable Register	Calibration Data Enable Register (address = 0x070) [reset = 0x00]
0x071	Undefined	CAL_DATA	Calibration Data Register	Calibration Data Register (address = 0x071) [reset = Undefined]
0x072-0x079	Undefined	RESERVED	RESERVED	—
0x07A	Undefined	GAIN_TRIM_A	Channel A Gain Trim Register	Channel A Gain Trim Register (address = 0x07A) [reset = Undefined]
0x07B	Undefined	GAIN_TRIM_B	Channel B Gain Trim Register	Channel B Gain Trim Register (address = 0x07B) [reset = Undefined]
0x07C	Undefined	BG_TRIM	Band-Gap Reference Trim Register	Band-Gap Reference Trim Register (address = 0x07C) [reset = Undefined]
0x07D	Undefined	RESERVED	RESERVED	—
0x07E	Undefined	RTRIM_A	VINA Input Resistor Trim Register	VINA Input Resistor Trim Register (address = 0x07E) [reset = Undefined]
0x07F	Undefined	RTRIM_B	VINB Input Resistor Trim Register	VINB Input Resistor Trim Register (address = 0x07F) [reset = Undefined]
0x080	Undefined	TADJ_A_FG90	Timing Adjustment for A-ADC, Single-Channel Mode, Foreground Calibration Register	Timing Adjust for A-ADC, Single-Channel Mode, Foreground Calibration Register (address = 0x080) [reset = Undefined]
0x081	Undefined	TADJ_B_FG0	Timing Adjustment for B-ADC, Single-Channel Mode, Foreground Calibration Register	Timing Adjust for B-ADC, Single-Channel Mode, Foreground Calibration Register (address = 0x081) [reset = Undefined]
0x082	Undefined	TADJ_A_BG90	Timing Adjustment for A-ADC, Single-Channel Mode, Background Calibration Register	Timing Adjust for A-ADC, Single-Channel Mode, Background Calibration Register (address = 0x082) [reset = Undefined]
0x083	Undefined	TADJ_C_BG0	Timing Adjustment for C-ADC, Single-Channel Mode, Background Calibration Register	Timing Adjust for C-ADC, Single-Channel Mode, Background Calibration Register (address = 0x084) [reset = Undefined]
0x084	Undefined	TADJ_C_BG90	Timing Adjustment for C-ADC, Single-Channel Mode, Background Calibration Register	Timing Adjust for C-ADC, Single-Channel Mode, Background Calibration Register (address = 0x084) [reset = Undefined]
0x085	Undefined	TADJ_B_BG0	Timing Adjustment for B-ADC, Single-Channel Mode, Background Calibration Register	Timing Adjust for B-ADC, Single-Channel Mode, Background Calibration Register (address = 0x085) [reset = Undefined]
0x086	Undefined	TADJ_A	Timing Adjustment for A-ADC, Dual-Channel Mode Register	Timing Adjust for A-ADC, Dual-Channel Mode Register (address = 0x086) [reset = Undefined]
0x087	Undefined	TADJ_CA	Timing Adjustment for C-ADC Acting for A-ADC, Dual-Channel Mode Register	Timing Adjust for C-ADC Acting for A-ADC, Dual-Channel Mode Register (address = 0x087) [reset = Undefined]
0x088	Undefined	TADJ_CB	Timing Adjustment for C-ADC Acting for B-ADC, Dual-Channel Mode Register	Timing Adjust for C-ADC Acting for B-ADC, Dual-Channel Mode Register (address = 0x088) [reset = Undefined]

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Table 42. Calibration Registers (continued)

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x089	Undefined	TADJ_B	Timing Adjustment for B-ADC, Dual-Channel Mode Register	Timing Adjust for B-ADC, Dual-Channel Mode Register (address = 0x089) [reset = Undefined]
0x08A-0x08B	Undefined	OADJ_A_INA	Offset Adjustment for A-ADC and INA Register	Offset Adjustment for A-ADC and INA Register (address = 0x08A-0x08B) [reset = Undefined]
0x08C-0x08D	Undefined	OADJ_A_INB	Offset Adjustment for A-ADC and INB Register	Offset Adjustment for A-ADC and INB Register (address = 0x08C-0x08D) [reset = Undefined]
0x08E-0x08F	Undefined	OADJ_C_INA	Offset Adjustment for C-ADC and INA Register	Offset Adjustment for C-ADC and INA Register (address = 0x08E-0x08F) [reset = Undefined]
0x090-0x091	Undefined	OADJ_C_INB	Offset Adjustment for C-ADC and INB Register	Offset Adjustment for C-ADC and INB Register (address = 0x090-0x091) [reset = Undefined]
0x092-0x093	Undefined	OADJ_B_INA	Offset Adjustment for B-ADC and INA Register	Offset Adjustment for B-ADC and INA Register (address = 0x092-0x093) [reset = Undefined]
0x094-0x095	Undefined	OADJ_B_INB	Offset Adjustment for B-ADC and INB Register	Offset Adjustment for B-ADC and INB Register (address = 0x094-0x095) [reset = Undefined]
0x096	Undefined	RESERVED	RESERVED	—
0x097	0x00	0SFILT0	Offset Filtering Control 0	Offset Filtering Control 0 Register (address = 0x097) [reset = 0x00]
0x098	0x33	OSFILT1	Offset Filtering Control 1	Offset Filtering Control 1 Register (address = 0x098) [reset = 0x33]
0x099-0x0FF	Undefined	RESERVED	RESERVED	—

7.6.1.5.1 Input Mux Control Register (address = 0x060) [reset = 0x01]

Figure 86. Input Mux Control Register (INPUT_MUX)

7	6	5	4	3	2	1	0
RESERVED			DUAL_INPUT	RESERVED		SINGLE_INPUT	
R/W-000			R/W-0	R/W-00		R/W-01	

Table 43. INPUT_MUX Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	RESERVED
4	DUAL_INPUT	R/W	0	This bit selects inputs for dual-channel modes. If JMODE is selecting a single-channel mode, this register has no effect. 0: A channel samples INA, B channel samples INB (no swap, default) 1: A channel samples INB, B channel samples INA (swap)
3-2	RESERVED	R/W	00	RESERVED
1-0	SINGLE_INPUT	R/W	01	Thid field defines which input is sampled in single-channel mode. If JMODE is not selecting a single-channel mode, this register has no effect. 0: Reserved 1: INA is used (default) 2: INB is used 3: Reserved

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7.6.1.5.2 Calibration Enable Register (address = 0x061) [reset = 0x01]

Figure 87. Calibration Enable Register (CAL_EN)

7	6	5	4	3	2	1	0
RESERVED							CAL_EN
R/W-0000 000							R/W-1

Table 44. CAL_EN Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	CAL_EN	R/W	1	Calibration enable. Set this bit high to run calibration. Set this bit low to hold the calibration in reset to program new calibration settings. Clearing CAL_EN also resets the clock dividers that clock the digital block and JESD204B interface. Some calibration registers require clearing CAL_EN before making any changes. All registers with this requirement contain a note in their descriptions. After changing the registers, set CAL_EN to re-run calibration with the new settings. Always set CAL_EN before setting JESD_EN. Always clear JESD_EN before clearing CAL_EN.

7.6.1.5.3 Calibration Configuration 0 Register (address = 0x062) [reset = 0x01]

Only change this register when CAL_EN is 0.

Figure 88. Calibration Configuration 0 Register (CAL_CFG0)

7	6	5	4	3	2	1	0
RESERVED			CAL_OSFILT	CAL_BGOS	CAL_OS	CAL_BG	CAL_FG
R/W-000			R/W-0	R/W-0	R/W-0	R/W-0	R/W-1

Table 45. CAL_CFG0 Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	0000	RESERVED
4	CAL_OSFILT	R/W	0	Enable offset filtering by setting this bit high.
3	CAL_BGOS	R/W	0	0 : Disables background offset calibration (default) 1: Enables background offset calibration (requires CAL_BG to be set).
2	CAL_OS	R/W	0	0 : Disables foreground offset calibration (default) 1: Enables foreground offset calibration (requires CAL_FG to be set)
1	CAL_BG	R/W	0	0 : Disables background calibration (default) 1: Enables background calibration
0	CAL_FG	R/W	1	0 : Resets calibration values, skips foreground calibration 1: Resets calibration values, then runs foreground calibration (default)

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7.6.1.5.4 Calibration Status Register (address = 0x06A) [reset = Undefined]

Figure 89. Calibration Status Register (CAL_STATUS)

7	6	5	4	3	2	1	0
RESERVED						CAL_STOPPED	FG_DONE
R						R	R

Table 46. CAL_STATUS Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R		RESERVED
1	CAL_STOPPED	R		This bit returns a 1 when the background calibration has successfully stopped at the requested phase. This bit returns a 0 when calibration starts operating again. If background calibration is disabled, this bit is set when foreground calibration is completed or skipped.
0	FG_DONE	R		This bit is set high when the foreground calibration completes.

7.6.1.5.5 Calibration Pin Configuration Register (address = 0x06B) [reset = 0x00]

Figure 90. Calibration Pin Configuration Register (CAL_PIN_CFG)

7	6	5	4	3	2	1	0
RESERVED					CAL_STATUS_SEL		CAL_TRIG_EN
R/W-0000 0					R/W-00		R/W-0

Table 47. CAL_PIN_CFG Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	0000 0	RESERVED
2-1	CAL_STATUS_SEL	R/W	00	0: CALSTAT output pin matches FG_DONE 1: RESERVED 2: CALSTAT output pin matches ALARM 3: CALSTAT output pin is always low
0	CAL_TRIG_EN	R/W	0	Choose the hardware or software trigger source with this bit. 0: Use the CAL_SOFT_TRIG register for the calibration trigger; the CAL_TRIG input is disabled (ignored) 1: Use the CAL_TRIG input for the calibration trigger; the CAL_SOFT_TRIG register is ignored

7.6.1.5.6 Calibration Software Trigger Register (address = 0x06C) [reset = 0x01]

Figure 91. Calibration Software Trigger Register (CAL_SOFT_TRIG)

7	6	5	4	3	2	1	0
RESERVED							CAL_SOFT_TRIG
R/W-0000 000							R/W-1

Table 48. CAL_SOFT_TRIG Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	CAL_SOFT_TRIG	R/W	1	CAL_SOFT_TRIG is a software bit to provide functionality of the CAL_TRIG input. Program CAL_TRIG_EN = 0 to use CAL_SOFT_TRIG for the calibration trigger. If no calibration trigger is needed, leave CAL_TRIG_EN = 0 and CAL_SOFT_TRIG = 1 (trigger is set high).

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7.6.1.5.7 Low-Power Background Calibration Register (address = 0x06E) [reset = 0x88]

Figure 92. Low-Power Background Calibration Register (CAL_LP)

7	6	5	4	3	2	1	0
LP_SLEEP_DLY			LP_WAKE_DLY		RESERVED	LP_TRIG	LP_EN
R/W-010			R/W-01		R/W-0	R/W-0	R/W-0

Table 49. CAL_LP Field Descriptions

Bit	Field	Type	Reset	Description
7-5	LP_SLEEP_DLY	R/W	010	Adjust how long an ADC sleeps before waking up for calibration (only applies when LP_EN = 1 and LP_TRIG = 0). Values below 4 are not recommended because of limited overall power reduction benefits. 0: Sleep delay = $(2^3 + 1) \times 256 \times t_{DEVCLK}$ 1: Sleep delay = $(2^{15} + 1) \times 256 \times t_{DEVCLK}$ 2: Sleep delay = $(2^{18} + 1) \times 256 \times t_{DEVCLK}$ 3: Sleep delay = $(2^{21} + 1) \times 256 \times t_{DEVCLK}$ 4: Sleep delay = $(2^{24} + 1) \times 256 \times t_{DEVCLK}$: default is approximately 1338 ms with a 3.2-GHz clock 5: Sleep delay = $(2^{27} + 1) \times 256 \times t_{DEVCLK}$ 6: Sleep delay = $(2^{30} + 1) \times 256 \times t_{DEVCLK}$ 7: Sleep delay = $(2^{33} + 1) \times 256 \times t_{DEVCLK}$
4-3	LP_WAKE_DLY	R/W	01	Adjust how much time is given up for settling before calibrating an ADC after wake-up (only applies when LP_EN = 1). Values lower than 1 are not recommended because there is insufficient time for the core to stabilize before calibration begins. 0:Wake Delay = $(2^3 + 1) \times 256 \times t_{DEVCLK}$ 1: Wake Delay = $(2^{18} + 1) \times 256 \times t_{DEVCLK}$: default is approximately 21 ms with a 3.2-GHz clock 2: Wake Delay = $(2^{21} + 1) \times 256 \times t_{DEVCLK}$ 3: Wake Delay = $(2^{24} + 1) \times 256 \times t_{DEVCLK}$
2	RESERVED	R/W	0	RESERVED
1	LP_TRIG	R/W	0	0: ADC sleep duration is set by LP_SLEEP_DLY (autonomous mode) 1: ADCs sleep until woken by a trigger; an ADC is awoken when the calibration trigger (CAL_SOFT_TRIG bit or CAL_TRIG input) is low
0	LP_EN	R/W	0	0: Disables low-power background calibration (default) 1: Enables low-power background calibration (only applies when CAL_BG = 1)

7.6.1.5.8 Calibration Data Enable Register (address = 0x070) [reset = 0x00]

Figure 93. Calibration Data Enable Register (CAL_DATA_EN)

7	6	5	4	3	2	1	0
RESERVED							CAL_DATA_EN
R/W-0000 000							R/W-0

Table 50. CAL_DATA_EN Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	CAL_DATA_EN	R/W	0	Set this bit to enable the CAL_DATA register to enable reading and writing of calibration data; see the calibration data register for more information.

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7.6.1.5.9 Calibration Data Register (address = 0x071) [reset = Undefined]

Figure 94. Calibration Data Register (CAL_DATA)

7	6	5	4	3	2	1	0
CAL_DATA							
R/W							

Table 51. CAL_DATA Field Descriptions

Bit	Field	Type	Reset	Description
7-0	CAL_DATA	R/W	Undefined	After setting CAL_DATA_EN, repeated reads of this register return all calibration values for the ADCs. Repeated writes of this register input all calibration values for the ADCs. To read the calibration data, read the register 673 times. To write the vector, write the register 673 times with previously stored calibration data. To speed up the read/write operation, set ADDR_HOLD = 1 and use the streaming read or write process. Accessing the CAL_DATA register when CAL_STOPPED = 0 corrupts the calibration. Also, stopping the process before reading or writing 673 times leaved the calibration data in an invalid state.

7.6.1.5.10 Channel A Gain Trim Register (address = 0x07A) [reset = Undefined]

Figure 95. Channel A Gain Trim Register (GAIN_TRIM_A)

7	6	5	4	3	2	1	0
GAIN_TRIM_A							
R/W							

Table 52. GAIN_TRIM_A Field Descriptions

Bit	Field	Type	Reset	Description
7-0	GAIN_TRIM_A	R/W	Undefined	This register enables gain trim of channel A. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.11 Channel B Gain Trim Register (address = 0x07B) [reset = Undefined]

Figure 96. Channel B Gain Trim Register (GAIN_TRIM_B)

7	6	5	4	3	2	1	0
GAIN_TRIM_B							
R/W							

Table 53. GAIN_TRIM_B Field Descriptions

Bit	Field	Type	Reset	Description
7-0	GAIN_TRIM_B	R/W	Undefined	This register enables gain trim of channel B. After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.5.12 Band-Gap Reference Trim Register (address = 0x07C) [reset = Undefined]

Figure 97. Band-Gap Reference Trim Register (BG_TRIM)

7	6	5	4	3	2	1	0
RESERVED				BG_TRIM			
R/W-0000				R/W			

Table 54. BG_TRIM Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	RESERVED
3-0	BG_TRIM	R/W	Undefined	This register enables the internal band-gap reference to be trimmed. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.13 VINA Input Resistor Trim Register (address = 0x07E) [reset = Undefined]

Figure 98. VINA Input Resistor Trim Register (RTRIM_A)

7	6	5	4	3	2	1	0
RTRIM							
R/W							

Table 55. RTRIM_A Field Descriptions

Bit	Field	Type	Reset	Description
7-0	RTRIM_A	R/W	Undefined	This register controls the VINA ADC input termination trim. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.14 VINB Input Resistor Trim Register (address = 0x07F) [reset = Undefined]

Figure 99. VINB Input Resistor Trim Register (RTRIM_B)

7	6	5	4	3	2	1	0
RTRIM							
R/W							

Table 56. RTRIM_B Field Descriptions

Bit	Field	Type	Reset	Description
7-0	RTRIM_B	R/W	Undefined	This register controls the VINB ADC input termination trim. After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.5.15 Timing Adjust for A-ADC, Single-Channel Mode, Foreground Calibration Register (address = 0x080) [reset = Undefined]

Figure 100. Register (TADJ_A_FG90)

7	6	5	4	3	2	1	0
TADJ_A_FG90							
R/W							

Table 57. TADJ_A_FG90 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_A_FG90	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.16 Timing Adjust for B-ADC, Single-Channel Mode, Foreground Calibration Register (address = 0x081) [reset = Undefined]

Figure 101. Register (TADJ_B_FG0)

7	6	5	4	3	2	1	0
TADJ_B_FG0							
R/W							

Table 58. TADJ_B_FG0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_B_FG0	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.17 Timing Adjust for A-ADC, Single-Channel Mode, Background Calibration Register (address = 0x082) [reset = Undefined]

Figure 102. Register (TADJ_A_BG90)

7	6	5	4	3	2	1	0
TADJ_A_BG90							
R/W							

Table 59. TADJ_B_FG0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_A_BG90	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.5.18 Timing Adjust for C-ADC, Single-Channel Mode, Background Calibration Register (address = 0x083) [reset = Undefined]

Figure 103. Timing Adjust for C-ADC, Single-Channel Mode, Background Calibration Register (TADJ_C_BG0)

7	6	5	4	3	2	1	0
TADJ_C_BG0							
R/W							

Table 60. TADJ_B_FG0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_C_BG0	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.19 Timing Adjust for C-ADC, Single-Channel Mode, Background Calibration Register (address = 0x084) [reset = Undefined]

Figure 104. Timing Adjust for C-ADC, Single-Channel Mode, Background Calibration Register (TADJ_C_BG90)

7	6	5	4	3	2	1	0
TADJ_C_BG90							
R/W							

Table 61. TADJ_B_FG0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_C_BG90	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.20 Timing Adjust for B-ADC, Single-Channel Mode, Background Calibration Register (address = 0x085) [reset = Undefined]

Figure 105. Timing Adjust for B-ADC, Single-Channel Mode, Background Calibration Register (TADJ_B_BG0)

7	6	5	4	3	2	1	0
TADJ_B_BG0							
R/W							

Table 62. TADJ_B_FG0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_B_BG0	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.5.21 Timing Adjust for A-ADC, Dual-Channel Mode Register (address = 0x086) [reset = Undefined]

Figure 106. Timing Adjust for A-ADC, Dual-Channel Mode Register (TADJ_A)

7	6	5	4	3	2	1	0
TADJ_A							
R/W							

Table 63. TADJ_A Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_A	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.22 Timing Adjust for C-ADC Acting for A-ADC, Dual-Channel Mode Register (address = 0x087) [reset = Undefined]

Figure 107. Timing Adjust for C-ADC Acting for A-ADC, Dual-Channel Mode Register (TADJ_CA)

7	6	5	4	3	2	1	0
TADJ_CA							
R/W							

Table 64. TADJ_CA Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_CA	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.23 Timing Adjust for C-ADC Acting for B-ADC, Dual-Channel Mode Register (address = 0x088) [reset = Undefined]

Figure 108. Timing Adjust for C-ADC Acting for B-ADC, Dual-Channel Mode Register (TADJ_CB)

7	6	5	4	3	2	1	0
TADJ_CB							
R/W							

Table 65. TADJ_CB Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_CB	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.5.24 Timing Adjust for B-ADC, Dual-Channel Mode Register (address = 0x089) [reset = Undefined]

Figure 109. Timing Adjust for B-ADC, Dual-Channel Mode Register (TADJ_B)

7	6	5	4	3	2	1	0
TADJ_B							
R/W							

Table 66. TADJ_B Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TADJ_B	R/W	Undefined	This register (and other subsequent TADJ* registers) are used to adjust the sampling instant of each ADC core. Different TADJ registers apply to different ADCs under different modes or phases of background calibration. After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.5.25 Offset Adjustment for A-ADC and INA Register (address = 0x08A-0x08B) [reset = Undefined]

Figure 110. Offset Adjustment for A-ADC and INA Register (OADJ_A_INA)

15	14	13	12	11	10	9	8
RESERVED				OADJ_A_INA[11:8]			
R/W-0000				R/W			
7	6	5	4	3	2	1	0
OADJ_A_INA[7:0]							
R/W							

Table 67. OADJ_A_INA Field Descriptions

Bit	Field	Type	Reset	Description
15-12	RESERVED	R/W	0000	RESERVED
11-0	OADJ_A_INA	R/W	Undefined	Offset adjustment value for ADC0 (A-ADC) applied when ADC0 samples INA. The format is unsigned. After reset, the factory-trimmed value can be read and adjusted as required. Important notes: • Never write OADJ* registers while foreground calibration is underway • Never write OADJ* registers if CAL_BG and CAL_BGOS are set • If CAL_OS = 1 and CAL_BGOS = 0, only read OADJ* registers if FG_DONE = 1 • If CAL_BG = 1 and CAL_BGOS = 1, only read OADJ* register if CAL_STOPPED = 1

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7.6.1.5.26 Offset Adjustment for A-ADC and INB Register (address = 0x08C-0x08D) [reset = Undefined]

Figure 111. Offset Adjustment for A-ADC and INB Register (OADJ_A_INB)

15	14	13	12	11	10	9	8
RESERVED				OADJ_A_INB[11:8]			
R/W-0000				R/W			
7	6	5	4	3	2	1	0
OADJ_A_INB[7:0]							
R/W							

Table 68. OADJ_A_INB Field Descriptions

Bit	Field	Type	Reset	Description
15-12	RESERVED	R/W	0000	RESERVED
11-0	OADJ_A_INB	R/W	Undefined	Offset adjustment value for ADC0 (A-ADC) applied when ADC0 samples INB. The format is unsigned. After reset, the factory-trimmed value can be read and adjusted as required. Important notes: • Never write OADJ* registers while foreground calibration is underway • Never write OADJ* registers if CAL_BG and CAL_BGOS are set • If CAL_OS = 1 and CAL_BGOS = 0, only read OADJ* registers if FG_DONE = 1 • If CAL_BG = 1 and CAL_BGOS = 1, only read OADJ* register if CAL_STOPPED = 1

7.6.1.5.27 Offset Adjustment for C-ADC and INA Register (address = 0x08E-0x08F) [reset = Undefined]

Figure 112. Offset Adjustment for C-ADC and INA Register (OADJ_C_INA)

15	14	13	12	11	10	9	8
RESERVED				OADJ_C_INA[11:8]			
R/W-0000				R/W			
7	6	5	4	3	2	1	0
OADJ_C_INA[7:0]							
R/W							

Table 69. OADJ_C_INA Field Descriptions

Bit	Field	Type	Reset	Description
15-12	RESERVED	R/W	0000	RESERVED
11-0	OADJ_C_INA	R/W	Undefined	Offset adjustment value for ADC1 (A-ADC) applied when ADC1 samples INA. The format is unsigned. After reset, the factory-trimmed value can be read and adjusted as required. Important notes: • Never write OADJ* registers while foreground calibration is underway • Never write OADJ* registers if CAL_BG and CAL_BGOS are set • If CAL_OS = 1 and CAL_BGOS = 0, only read OADJ* registers if FG_DONE = 1 • If CAL_BG = 1 and CAL_BGOS = 1, only read OADJ* register if CAL_STOPPED = 1

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7.6.1.5.28 Offset Adjustment for C-ADC and INB Register (address = 0x090-0x091) [reset = Undefined]

Figure 113. Offset Adjustment for C-ADC and INB Register (OADJ_C_INB)

15	14	13	12	11	10	9	8
RESERVED				OADJ_C_INB[11:8]			
R/W-0000				R/W			
7	6	5	4	3	2	1	0
OADJ_C_INB[7:0]							
R/W							

Table 70. OADJ_C_INB Field Descriptions

Bit	Field	Type	Reset	Description
15-12	RESERVED	R/W	0000	RESERVED
11-0	OADJ_C_INB	R/W	Undefined	Offset adjustment value for ADC1 (A-ADC) applied when ADC1 samples INB. The format is unsigned. After reset, the factory-trimmed value can be read and adjusted as required. Important notes: • Never write OADJ* registers while foreground calibration is underway • Never write OADJ* registers if CAL_BG and CAL_BGOS are set • If CAL_OS = 1 and CAL_BGOS = 0, only read OADJ* registers if FG_DONE = 1 • If CAL_BG = 1 and CAL_BGOS = 1, only read OADJ* register if CAL_STOPPED = 1

7.6.1.5.29 Offset Adjustment for B-ADC and INA Register (address = 0x092-0x093) [reset = Undefined]

Figure 114. Offset Adjustment for B-ADC and INA Register (OADJ_B_INA)

15	14	13	12	11	10	9	8
RESERVED				OADJ_B_INA[11:8]			
R/W-0000				R/W			
7	6	5	4	3	2	1	0
OADJ_B_INA[7:0]							
R/W							

Table 71. OADJ_B_INA Field Descriptions

Bit	Field	Type	Reset	Description
15-12	RESERVED	R/W	0000	RESERVED
11-0	OADJ_B_INA	R/W	Undefined	Offset adjustment value for ADC2 (B-ADC) applied when ADC2 samples INA. The format is unsigned. After reset, the factory-trimmed value can be read and adjusted as required. Important notes: • Never write OADJ* registers while foreground calibration is underway • Never write OADJ* registers if CAL_BG and CAL_BGOS are set • If CAL_OS = 1 and CAL_BGOS = 0, only read OADJ* registers if FG_DONE = 1 • If CAL_BG = 1 and CAL_BGOS = 1, only read OADJ* register if CAL_STOPPED = 1

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7.6.1.5.30 Offset Adjustment for B-ADC and INB Register (address = 0x094-0x095) [reset = Undefined]

Figure 115. Offset Adjustment for B-ADC and INB Register (OADJ_B_INB)

15	14	13	12	11	10	9	8
RESERVED				OADJ_B_INB[11:8]			
R/W-0000				R/W			
7	6	5	4	3	2	1	0
OADJ_B_INB[7:0]							
R/W							

Table 72. OADJ_B_INB Field Descriptions

Bit	Field	Type	Reset	Description
15-12	RESERVED	R/W	0000	RESERVED
11-0	OADJ_B_INB	R/W	Undefined	Offset adjustment value for ADC2 (B-ADC) applied when ADC2 samples INB. The format is unsigned. After reset, the factory-trimmed value can be read and adjusted as required. Important notes: • Never write OADJ* registers while foreground calibration is underway • Never write OADJ* registers if CAL_BG and CAL_BGOS are set • If CAL_OS = 1 and CAL_BGOS=0, only read OADJ* registers if FG_DONE = 1 • If CAL_BG = 1 and CAL_BGOS=1, only read OADJ* register if CAL_STOPPED = 1

7.6.1.5.31 Offset Filtering Control 0 Register (address = 0x097) [reset = 0x00]

Figure 116. Offset Filtering Control 0 Register (OSFILT0)

7	6	5	4	3	2	1	0
RESERVED							DC_RESTORE
R/W-0000 000							R/W

Table 73. OSFILT0 Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	DC_RESTORE	R/W	0	When set, the offset filtering feature (enabled by CAL_OSFILT) filters only the offset mismatch across ADC banks and does not remove the frequency content near DC. When cleared, the feature filters all offsets from all banks, thus filtering all DC content in the signal; see the *Offset Filtering* section.

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7.6.1.5.32 Offset Filtering Control 1 Register (address = 0x098) [reset = 0x33]

Figure 117. Offset Filtering Control 1 Register (OSFILT1)

7	6	5	4	3	2	1	0
OSFILT_BW				OSFILT_SOAK			
R/W-0011				R/W-0011			

Table 74. OSFILT1 Field Descriptions

Bit	Field	Type	Reset	Description
7-4	OSFILT_BW	R/W	0011	This field adjusts the IIR filter bandwidth for the offset filtering feature (enabled by CAL_OSFILT). More bandwidth suppresses more flicker noise from the ADCs and reduces the offset spurs. Less bandwidth minimizes the impact of the filters on the mission mode signal. OSFILT_BW: IIR coefficient: –3-dB bandwidth (single sided) 0: Reserved 1: 2^{-10} : 609e-9 × F_{DEVCLK} 2: 2^{-11} : 305e-9 × F_{DEVCLK} 3: 2^{-12} : 152e-9 × F_{DEVCLK} 4: 2^{-13} : 76e-9 × F_{DEVCLK} 5: 2^{-14} : 38e-9 × F_{DEVCLK} 6-15: Reserved
3-0	OSFILT_SOAK	R/W	0011	This field adjusts the IIR soak time for the offset filtering feature. This field applies when offset filtering and background calibration are both enabled. This field determines how long the IIR filter is allowed to settle when first connected to an ADC after the ADC is calibrated. After the soak time completes, the ADC is placed online using the IIR filter. Set OSFILT_SOAK = OSFILT_BW.

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7.6.1.6 ADC Bank Registers (0x100 to 0x15F)

Table 75. ADC Bank Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x100-0x101	Undefined	RESERVED	RESERVED	—
0x102	Undefined	B0_TIME_0	Timing Adjustment for Bank 0 (0° Clock) Register	Timing Adjustment for Bank 0 (0° Clock) Register (address = 0x102) [reset = Undefined]
0x103	Undefined	B0_TIME_90	Timing Adjustment for Bank 0 (–90° Clock) Register	Timing Adjustment for Bank 0 (–90° Clock) Register (address = 0x103) [reset = Undefined]
0x104-0x111	Undefined	RESERVED	RESERVED	—
0x112	Undefined	B1_TIME_0	Timing Adjustment for Bank 1 (0° Clock) Register	Timing Adjustment for Bank 1 (0° Clock) Register (address = 0x112) [reset = Undefined]
0x113	Undefined	B1_TIME_90	Timing Adjustment for Bank 1 (–90° Clock) Register	Timing Adjustment for Bank 1 (–90° Clock) Register (address = 0x113) [reset = Undefined]
0x114-0x121	Undefined	RESERVED	RESERVED	—
0x122	Undefined	B2_TIME_0	Timing Adjustment for Bank 2 (0° Clock) Register	Timing Adjustment for Bank 2 (0° Clock) Register (address = 0x122) [reset = Undefined]
0x123	Undefined	B2_TIME_90	Timing Adjustment for Bank 2 (–90° Clock) Register	Timing Adjustment for Bank 2 (–90° Clock) Register (address = 0x123) [reset = Undefined]
0x124-0x131	Undefined	RESERVED	RESERVED	—
0x132	Undefined	B3_TIME_0	Timing Adjustment for Bank 3 (0° Clock) Register	Timing Adjustment for Bank 3 (0° Clock) Register (address = 0x132) [reset = Undefined]
0x133	Undefined	B3_TIME_90	Timing Adjustment for Bank 3 (–90° Clock) Register	Timing Adjustment for Bank 3 (–90° Clock) Register (address = 0x133) [reset = Undefined]
0x134-0x141	Undefined	RESERVED	RESERVED	—
0x142	Undefined	B4_TIME_0	Timing Adjustment for Bank 4 (0° Clock) Register	Timing Adjustment for Bank 4 (0° Clock) Register (address = 0x142) [reset = Undefined]
0x143	Undefined	B4_TIME_90	Timing Adjustment for Bank 4 (–90° Clock) Register	Timing Adjustment for Bank 4 (–90° Clock) Register (address = 0x143) [reset = Undefined]
0x144-0x151	Undefined	RESERVED	RESERVED	—
0x152	Undefined	B5_TIME_0	Timing Adjustment for Bank 5 (0° Clock) Register	Timing Adjustment for Bank 5 (0° Clock) Register (address = 0x152) [reset = Undefined]
0x153	Undefined	B5_TIME_90	Timing Adjustment for Bank 5 (–90° Clock) Register	Timing Adjustment for Bank 5 (–90° Clock) Register (address = 0x153) [reset = Undefined]
0x154-0x15F	Undefined	RESERVED	RESERVED	—

7.6.1.6.1 Timing Adjustment for Bank 0 (0° Clock) Register (address = 0x102) [reset = Undefined]

Figure 118. Timing Adjustment for Bank 0 (0° Clock) Register (B0_TIME_0)

7	6	5	4	3	2	1	0
B0_TIME_0							
R/W							

Table 76. B0_TIME_0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B0_TIME_0	R/W	Undefined	Time adjustment for bank 0 (applied when the ADC is configured for 0° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.6.2 Timing Adjustment for Bank 0 (–90° Clock) Register (address = 0x103) [reset = Undefined]

Figure 119. Timing Adjustment for Bank 0 (–90° Clock) Register (B0_TIME_90)

7	6	5	4	3	2	1	0
B0_TIME_90							
R/W							

Table 77. B0_TIME_90 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B0_TIME_90	R/W	Undefined	Time adjustment for bank 0 (applied when the ADC is configured for –90° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.3 Timing Adjustment for Bank 1 (0° Clock) Register (address = 0x112) [reset = Undefined]

Figure 120. Timing Adjustment for Bank 1 (0° Clock) Register (B1_TIME_0)

7	6	5	4	3	2	1	0
B1_TIME_0							
R/W							

Table 78. B1_TIME_0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B1_TIME_0	R/W	Undefined	Time adjustment for bank 1 (applied when the ADC is configured for 0° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.4 Timing Adjustment for Bank 1 (–90° Clock) Register (address = 0x113) [reset = Undefined]

Figure 121. Timing Adjustment for Bank 1 (–90° Clock) Register (B1_TIME_90)

7	6	5	4	3	2	1	0
B1_TIME_90							
R/W							

Table 79. B1_TIME_90 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B1_TIME_90	R/W	Undefined	Time adjustment for bank 1 (applied when the ADC is configured for –90° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.5 Timing Adjustment for Bank 2 (0° Clock) Register (address = 0x122) [reset = Undefined]

Figure 122. Timing Adjustment for Bank 2 (0° Clock) Register (B2_TIME_0)

7	6	5	4	3	2	1	0
B2_TIME_0							
R/W							

Table 80. B2_TIME_0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B2_TIME_0	R/W	Undefined	Time adjustment for bank 2 (applied when the ADC is configured for 0° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.6.6 Timing Adjustment for Bank 2 (–90° Clock) Register (address = 0x123) [reset = Undefined]

Figure 123. Timing Adjustment for Bank 2 (–90° Clock) Register (B2_TIME_90)

7	6	5	4	3	2	1	0
B2_TIME_90							
R/W							

Table 81. B2_TIME_90 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B2_TIME_90	R/W	Undefined	Time adjustment for bank 2 (applied when the ADC is configured for –90° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.7 Timing Adjustment for Bank 3 (0° Clock) Register (address = 0x132) [reset = Undefined]

Figure 124. Timing Adjustment for Bank 3 (0° Clock) Register (B3_TIME_0)

7	6	5	4	3	2	1	0
B3_TIME_0							
R/W							

Table 82. B3_TIME_0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B3_TIME_0	R/W	Undefined	Time adjustment for bank 3 (applied when the ADC is configured for 0° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.8 Timing Adjustment for Bank 3 (–90° Clock) Register (address = 0x133) [reset = Undefined]

Figure 125. Timing Adjustment for Bank 3 (–90° Clock) Register (B3_TIME_90)

7	6	5	4	3	2	1	0
B3_TIME_90							
R/W							

Table 83. B3_TIME_90 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B3_TIME_90	R/W	Undefined	Time adjustment for bank 3 (applied when the ADC is configured for –90° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.9 Timing Adjustment for Bank 4 (0° Clock) Register (address = 0x142) [reset = Undefined]

Figure 126. Timing Adjustment for Bank 4 (0° Clock) Register (B4_TIME_0)

7	6	5	4	3	2	1	0
B4_TIME_0							
R/W							

Table 84. B4_TIME_0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B4_TIME_0	R/W	Undefined	Time adjustment for bank 4 (applied when the ADC is configured for 0° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.6.10 Timing Adjustment for Bank 4 (–90° Clock) Register (address = 0x143) [reset = Undefined]

Figure 127. Timing Adjustment for Bank 4 (–90° Clock) Register (B4_TIME_90)

7	6	5	4	3	2	1	0
B4_TIME_90							
R/W							

Table 85. B4_TIME_90 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B4_TIME_90	R/W	Undefined	Time adjustment for bank 4 (applied when the ADC is configured for –90° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.11 Timing Adjustment for Bank 5 (0° Clock) Register (address = 0x152) [reset = Undefined]

Figure 128. Timing Adjustment for Bank 5 (0° Clock) Register (B5_TIME_0)

7	6	5	4	3	2	1	0
B5_TIME_0							
R/W							

Table 86. B5_TIME_0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B5_TIME_0	R/W	Undefined	Time adjustment for bank 5 (applied when the ADC is configured for 0° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

7.6.1.6.12 Timing Adjustment for Bank 5 (–90° Clock) Register (address = 0x153) [reset = Undefined]

Figure 129. Timing Adjustment for Bank 5 (–90° Clock) Register (B5_TIME_90)

7	6	5	4	3	2	1	0
B5_TIME_90							
R/W							

Table 87. B5_TIME_90 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	B5_TIME_90	R/W	Undefined	Time adjustment for bank 5 (applied when the ADC is configured for –90° clock phase). After reset, the factory-trimmed value can be read and adjusted as required.

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7.6.1.7 LSB Control Registers (0x160 to 0x1FF)

Table 88. LSB Control Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x160	0x00	ENC_LSB	LSB Control Bit Output Register	LSB Control Bit Output Register (address = 0x160) [reset = 0x00]
0x161-0x1FF	Undefined	RESERVED	RESERVED	—

7.6.1.7.1 LSB Control Bit Output Register (address = 0x160) [reset = 0x00]

Figure 130. LSB Control Bit Output Register (ENC_LSB)

7	6	5	4	3	2	1	0
RESERVED							TIMESTAMP_EN
R/W-0000 000							R/W-0

Table 89. ENC_LSB Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	TIMESTAMP_EN	R/W	0	When set, the transport layer transmits the timestamp signal on the LSB of the output samples. TIMESTAMP_EN has priority over CAL_STATE_EN. TMSTP_RECV_EN must also be set high when using timestamp. The latency of the timestamp signal (through the entire device) matches the latency of the analog ADC inputs. The control bit enabled by this register is never advertised in the ILA (the $\overline{CS}$ field is 0 in the ILA).

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7.6.1.8 JESD204B Registers (0x200 to 0x20F)

Table 90. JESD204B Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x200	0x01	JESD_EN	JESD204B Enable Register	JESD204B Enable Register (address = 0x200) [reset = 0x01]
0x201	0x02	JMODE	JESD204B Mode Register	JESD204B Mode Register (address = 0x201) [reset = 0x02]
0x202	0x1F	KM1	JESD204B K Parameter Register	JESD204B K Parameter Register (address = 0x202) [reset = 0x1F]
0x203	0x01	JSYNC_N	JESD204B Manual SYNC Request Register	JESD204B Manual SYNC Request Register (address = 0x203) [reset = 0x01]
0x204	0x02	JCTRL	JESD204B Control Register	JESD204B Control Register (address = 0x204) [reset = 0x02]
0x205	0x00	JTEST	JESD204B Test Pattern Control Register	JESD204B Test Pattern Control Register (address = 0x205) [reset = 0x00]
0x206	0x00	DID	JESD204B DID Parameter Register	JESD204B DID Parameter Register (address = 0x206) [reset = 0x00]
0x207	0x00	FCHAR	JESD204B Frame Character Register	JESD204B Frame Character Register (address = 0x207) [reset = 0x00]
0x208	Undefined	JESD_STATUS	JESD204B, System Status Register	JESD204B, System Status Register (address = 0x208) [reset = Undefined]
0x209	0x00	PD_CH	JESD204B Channel Power-Down	JESD204B Channel Power-Down Register (address = 0x209) [reset = 0x00]
0x20A	0x00	JEXTRA_A	JESD204B Extra Lane Enable (Link A)	JESD204B Extra Lane Enable (Link A) Register (address = 0x20A) [reset = 0x00]
0x20B	0x00	JEXTRA_B	JESD204B Extra Lane Enable (Link B)	JESD204B Extra Lane Enable (Link B) Register (address = 0x20B) [reset = 0x00]
0x20C-0x210	Undefined	RESERVED	RESERVED	—

7.6.1.8.1 JESD204B Enable Register (address = 0x200) [reset = 0x01]

Figure 131. JESD204B Enable Register (JESD_EN)

7	6	5	4	3	2	1	0
RESERVED							JESD_EN
R/W-0000 000							R/W-1

Table 91. JESD_EN Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	JESD_EN	R/W	1	0 : Disables JESD204B interface 1 : Enables JESD204B interface Before altering other JESD204B registers, JESD_EN must be cleared. When JESD_EN is 0, the block is held in reset and the serializers are powered down. The clocks are gated off to save power. The LMFC counter is also held in reset, so SYSREF does not align the LMFC. Always set CAL_EN before setting JESD_EN. Always clear JESD_EN before clearing CAL_EN.

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7.6.1.8.2 JESD204B Mode Register (address = 0x201) [reset = 0x02]

Figure 132. JESD204B Mode Register (JMODE)

7	6	5	4	3	2	1	0
RESERVED			JMODE				
R/W-000			R/W-0001 0				

Table 92. JMODE Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	RESERVED
4-0	JMODE	R/W	0001 0	Specify the JESD204B output mode. Only change this register when JESD_EN = 0 and CAL_EN = 0.

7.6.1.8.3 JESD204B K Parameter Register (address = 0x202) [reset = 0x1F]

Figure 133. JESD204B K Parameter Register (KM1)

7	6	5	4	3	2	1	0
RESERVED			KM1				
R/W-000			R/W-1111 1				

Table 93. KM1 Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	RESERVED
4-0	KM1	R/W	1111 1	K is the number of frames per multiframe and this register must be programmed as K-1. Depending on the JMODE setting, there are constraints on the legal values of K. (default: KM1 = 31, K = 32). Only change this register when JESD_EN is 0.

7.6.1.8.4 JESD204B Manual SYNC Request Register (address = 0x203) [reset = 0x01]

Figure 134. JESD204B Manual SYNC Request Register (JSYNC_N)

7	6	5	4	3	2	1	0
RESERVED							JSYNC_N
R/W-0000 000							R/W-1

Table 94. JSYNC_N Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	JSYNC_N	R/W	1	Set this bit to 0 to request JESD204B synchronization (equivalent to the $\overline{\text{SYNCSE}}$ pin being asserted). For normal operation, leave this bit set to 1. The JSYNC_N register can always generate a synchronization request, regardless of the SYNC_SEL register. However, if the selected sync pin is stuck low, the synchronization request cannot be de-asserted unless SYNC_SEL = 2 is programmed.

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7.6.1.8.5 JESD204B Control Register (address = 0x204) [reset = 0x02]

Figure 135. JESD204B Control Register (JCTRL)

7	6	5	4	3	2	1	0
RESERVED				SYNC_SEL		SFORMAT	SCR
R/W-0000				R/W-00		R/W-1	R/W-0

Table 95. JCTRL Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	RESERVED
3-2	SYNC_SEL	R/W	00	0: Use the $\overline{\text{SYNCSE}}$ input for the SYNC~ function (default) 1: Use the TMSTP± differential input for the SYNC~ function; TMSTP_RECV_EN must also be set 2: Do not use any sync input signal (use software SYNC~ through JSYNC_N)
1	SFORMAT	R/W	1	Output sample format for JESD204B samples. 0: Offset binary 1: Signed 2's complement (default)
0	SCR	R/W	0	0: Scrambler disabled (default) 1: Scrambler enabled Only change this register when JESD_EN is 0.

7.6.1.8.6 JESD204B Test Pattern Control Register (address = 0x205) [reset = 0x00]

Figure 136. JESD204B Test Pattern Control Register (JTEST)

7	6	5	4	3	2	1	0
RESERVED				JTEST			
R/W-0000				R/W-0000			

Table 96. JTEST Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	RESERVED
3-0	JTEST	R/W	0000	0: Test mode disabled; normal operation (default) 1: PRBS7 test mode 2: PRBS15 test mode 3: PRBS23 test mode 4: Ramp test mode 5: Transport layer test mode 6: D21.5 test mode 7: K28.5 test mode 8: Repeated ILA test mode 9: Modified RPAT test mode 10: Serial outputs held low 11: Serial outputs held high 12–15: Reserved Only change this register when JESD_EN is 0.

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7.6.1.8.7 JESD204B DID Parameter Register (address = 0x206) [reset = 0x00]

Figure 137. JESD204B DID Parameter Register (DID)

7	6	5	4	3	2	1	0
DID							
R/W-0000 0000							

Table 97. DID Field Descriptions

Bit	Field	Type	Reset	Description
7-0	DID	R/W	0000 0000	Specifies the device ID (DID) value that is transmitted during the second multiframe of the JESD204B ILA. Link A transmits DID, and link B transmits DID+1. Bit 0 is ignored and always returns 0 (if an odd number is programmed, that number is decremented to an even number). Only change this register when JESD_EN is 0.

7.6.1.8.8 JESD204B Frame Character Register (address = 0x207) [reset = 0x00]

Figure 138. JESD204B Frame Character Register (FCHAR)

7	6	5	4	3	2	1	0
RESERVED						FCHAR	
R/W-0000 00						R/W-00	

Table 98. FCHAR Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R/W	0000 00	RESERVED
1-0	FCHAR	R/W	00	Specify which comma character is used to denote end-of-frame. This character is transmitted opportunistically (see the *Frame and Multiframe Monitoring* section). 0: Use K28.7 (default, JESD204B compliant) 1: Use K28.1 (not JESD204B compliant) 2: Use K28.5 (not JESD204B compliant) 3: Reserved When using a JESD204B receiver, always use FCHAR = 0. When using a general-purpose 8b, 10b receiver, the K28.7 character may cause issues. When K28.7 is combined with certain data characters, a false, misaligned comma character can result, and some receivers realign to the false comma. To avoid this condition, program FCHAR to 1 or 2. Only change this register when JESD_EN is 0.

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7.6.1.8.9 JESD204B, System Status Register (address = 0x208) [reset = Undefined]

Figure 139. JESD204B, System Status Register (JESD_STATUS)

7	6	5	4	3	2	1	0
RESERVED	LINK_UP	SYNC_STATUS	REALIGNED	ALIGNED	PLL_LOCKED	RESERVED	
R	R	R	R/W	R/W	R	R	

Table 99. JESD_STATUS Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R	Undefined	RESERVED
6	LINK_UP	R	Undefined	When set, this bit indicates that the JESD204B link is up.
5	SYNC_STATUS	R	Undefined	Returns the state of the JESD204B SYNC~ signal. 0: SYNC~ asserted 1: SYNC~ de-asserted
4	REALIGNED	R/W	Undefined	When high, this bit indicates that an internal digital clock, frame clock, or multiframe (LMFC) clock phase was realigned by SYSREF. Write a 1 to clear this bit.
3	ALIGNED	R/W	Undefined	When high, this bit indicates that the multiframe (LMFC) clock phase has been established by SYSREF. The first SYSREF event after enabling the JESD204B encoder will set this bit. Write a 1 to clear this bit.
2	PLL_LOCKED	R	Undefined	When high, this bit indicates that the PLL is locked.
1-0	RESERVED	R	Undefined	RESERVED

7.6.1.8.10 JESD204B Channel Power-Down Register (address = 0x209) [reset = 0x00]

Figure 140. JESD204B Channel Power-Down Register (PD_CH)

7	6	5	4	3	2	1	0
RESERVED						PD_BCH	PD_ACH
R/W-0000 00						R/W-0	R/W-0

Table 100. PD_CH Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R/W	0000 00	RESERVED
1	PD_BCH	R/W	0	When set, the *B* ADC channel is powered down. The ADC channel B SerDes lanes are also powered down when PD_BCH is set. Important notes: Set JESD_EN = 0 before changing PD_CH. To power-down both ADC channels, use MODE. If both channels are powered down, then the entire JESD204B subsystem (including the PLL and LMFC) are powered down If the selected JESD204B mode transmits A and B data on link A, and the B digital channel is disabled, link A remains operational, but the B-channel samples are undefined.
0	PD_ACH	R/W	0	When set, the *A* ADC channel is powered down. The ADC channel A SerDes lanes are also powered down when PD_ACH is set. Important notes: Set JESD_EN = 0 before changing PD_CH. To power-down both ADC channels, use MODE. If both channels are powered down, then the entire JESD204B subsystem (including the PLL and LMFC) are powered down If the selected JESD204B mode transmits A and B data on link A, and the B digital channel is disabled, link A remains operational, but the B-channel samples are undefined.

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7.6.1.8.11 JESD204B Extra Lane Enable (Link A) Register (address = 0x20A) [reset = 0x00]

Figure 141. JESD204B Extra Lane Enable (Link A) Register (JEXTRA_A)

7	6	5	4	3	2	1	0
EXTRA_LANE_A							EXTRA_SER_A
R/W-0000 000							R/W-0

Table 101. JESD204B Extra Lane Enable (Link A) Field Descriptions

Bit	Field	Type	Reset	Description
7-1	EXTRA_LANE_A	R/W	0000 000	Program these register bits to enable extra lanes (even if the selected JMODE does not require the lanes to be enabled). EXTRA_LANE_A(n) enables An (n = 1 to 7). This register enables the link layer clocks for the affected lanes. To also enable the extra serializes set EXTRA_SER_A = 1.
0	EXTRA_SER_A	R/W	0	0: Only the link layer clocks for extra lanes are enabled. 1: Serializers for extra lanes are also enabled. Use this mode to transmit data from the extra lanes. Important notes: Only change this register when JESD_EN = 0. The bit-rate and mode of the extra lanes are set by the JMODE and JTEST parameters. This register does not override the PD_CH register, so ensure that the link is enabled to use this feature. To enable serializer n, the lower number lanes 0 to n-1 must also be enabled, otherwise serializer n does not receive a clock.

7.6.1.8.12 JESD204B Extra Lane Enable (Link B) Register (address = 0x20B) [reset = 0x00]

Figure 142. JESD204B Extra Lane Enable (Link B) Register (JEXTRA_B)

7	6	5	4	3	2	1	0
EXTRA_LANE_B							EXTRA_SER_B
R/W-0000 000							R/W-0

Table 102. JESD204B Extra Lane Enable (Link B) Field Descriptions

Bit	Field	Type	Reset	Description
7-1	EXTRA_LANE_B	R/W	0000 000	Program these register bits to enable extra lanes (even if the selected JMODE does not require the lanes to be enabled). EXTRA_LANE_B(n) enables Bn (n = 1 to 7). This register enables the link layer clocks for the affected lanes. To also enable the extra serializes set EXTRA_SER_B = 1.
0	EXTRA_SER_B	R/W	0	0: Only the link layer clocks for extra lanes are enabled. 1: Serializers for extra lanes are also enabled. Use this mode to transmit data from the extra lanes. Important notes: Only change this register when JESD_EN = 0. The bit-rate and mode of the extra lanes are set by the JMODE and JTEST parameters. This register does not override the PD_CH register, so ensure that the link is enabled to use this feature. To enable serializer n, the lower number lanes 0 to n-1 must also be enabled, otherwise serializer n does not receive a clock.

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7.6.1.9 Digital Down Converter Registers (0x210-0x2AF)

Table 103. Overrange Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x211	0xF2	OVR_T0	Overrange Threshold 0 Register	Overrange Threshold 0 Register (address = 0x211) [reset = 0xF2]
0x212	0xAB	OVR_T1	Overrange Threshold 1 Register	Overrange Threshold 1 Register (address = 0x212) [reset = 0xAB]
0x213	0x07	OVR_CFG	Overrange Configuration Register	Overrange Configuration Register (address = 0x213) [reset = 0x07]
0x214-0x296	Undefined	RESERVED	RESERVED	—
0x297	Undefined	SPIN_ID	Spin Identification Value	Spin Identification Register (address = 0x297) [reset = Undefined]
0x298-0x2AF	Undefined	RESERVED	RESERVED	—

7.6.1.9.1 Overrange Threshold 0 Register (address = 0x211) [reset = 0xF2]

Figure 143. Overrange Threshold 0 Register (OVR_T0)

7	6	5	4	3	2	1	0
OVR_T0							
R/W-1111 0010							

Table 104. OVR_T0 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	OVR_T0	R/W	1111 0010	Overrange threshold 0. This parameter defines the absolute sample level that causes control bit 0 to be set. The detection level in dBFS (peak) is: 20_{log10}(OVR_T0 / 256) Default: 0xF2 = 242 → –0.5 dBFS.

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7.6.1.9.2 Overrange Threshold 1 Register (address = 0x212) [reset = 0xAB]

Figure 144. Overrange Threshold 1 Register (OVR_T1)

7	6	5	4	3	2	1	0
OVR_T1							
R/W-1010 1011							

Table 105. OVR_T1 Field Descriptions

Bit	Field	Type	Reset	Description
7-0	OVR_T1	R/W	1010 1011	Overrange threshold 1. This parameter defines the absolute sample level that causes control bit 1 to be set. The detection level in dBFS (peak) is: 20_{log10}(OVR_T1 / 256) Default: 0xAB = 171 → –3.5 dBFS.

7.6.1.9.3 Overrange Configuration Register (address = 0x213) [reset = 0x07]

Figure 145. Overrange Configuration Register (OVR_CFG)

7	6	5	4	3	2	1	0
RESERVED				OVR_EN	OVR_N		
R/W-0000				R/W-0	R/W-111		

Table 106. OVR_CFG Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000 0	RESERVED
3	OVR_EN	R/W	0	Enables overrange status output pins when set high. The ORA0, ORA1, ORB0, and ORB1 outputs are held low when OVR_EN is set low. This register only effects the overrange output pins (ORxx) and not the overrange status embedded in the data samples.
2-0	OVR_N (1)	R/W	111	Program this register to adjust the pulse extension for the ORA0, ORA1 and ORB0, ORB1 outputs. The minimum pulse duration of the overrange outputs is 8×2^{OVR_N} DEVCLK cycles. Incrementing this field doubles the monitoring period.

(1) Changing the OVR_N setting while JESD_EN=1 may cause the phase of the monitoring period to change.

7.6.1.10 Spin Identification Register (address = 0x297) [reset = Undefined]

Figure 146. Spin Identification Register (SPIN_ID)

7	6	5	4	3	2	1	0
RESERVED				SPIN_ID			
R-000				R			

Table 107. SPIN_ID Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R	000	RESERVED
4-0	SPIN_ID	R	2	Spin identification value. 2 : ADC08DJ3200

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7.6.2 SYSREF Calibration Registers (0x2B0 to 0x2BF)

Table 108. SYSREF Calibration Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x2B0	0x00	SRC_EN	SYSREF Calibration Enable Register	SYSREF Calibration Enable Register (address = 0x2B0) [reset = 0x00]
0x2B1	0x05	SRC_CFG	SYSREF Calibration Configuration Register	SYSREF Calibration Configuration Register (address = 0x2B1) [reset = 0x05]
0x2B2-0x2B4	Undefined	SRC_STATUS	SYSREF Calibration Status	SYSREF Calibration Status Register (address = 0x2B2 to 0x2B4) [reset = Undefined]
0x2B5-0x2B7	0x00	TAD	DEVCLK Aperture Delay Adjustment Register	DEVCLK Aperture Delay Adjustment Register (address = 0x2B5 to 0x2B7) [reset = 0x000000]
0x2B8	0x00	TAD_RAMP	DEVCLK Timing Adjust Ramp Control Register	DEVCLK Timing Adjust Ramp Control Register (address = 0x2B8) [reset = 0x00]
0x2B9-0x2BF	Undefined	RESERVED	RESERVED	—

7.6.2.1 SYSREF Calibration Enable Register (address = 0x2B0) [reset = 0x00]

Figure 147. SYSREF Calibration Enable Register (SRC_EN)

7	6	5	4	3	2	1	0
RESERVED							SRC_EN
R/W-0000 000							R/W-0

Table 109. SRC_EN Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000 000	RESERVED
0	SRC_EN	R/W	0	0: SYSREF calibration disabled; use the TAD register to manually control the TAD[16:0] output and adjust the DEVCLK delay (default) 1: SYSREF calibration enabled; the DEVCLK delay is automatically calibrated; the TAD register is ignored A 0-to-1 transition on SRC_EN starts the SYSREF calibration sequence. Program SRC_CFG before setting SRC_EN. Ensure that ADC calibration is not currently running before setting SRC_EN.

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7.6.2.2 SYSREF Calibration Configuration Register (address = 0x2B1) [reset = 0x05]

Figure 148. SYSREF Calibration Configuration Register (SRC_CFG)

7	6	5	4	3	2	1	0
RESERVED				SRC_AVG		SRC_HDUR	
R/W-0000				R/W-01		R/W-01	

Table 110. SRC_CFG Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000 00	RESERVED
3-2	SRC_AVG	R/W	01	Specifies the amount of averaging used for SYSREF calibration. Larger values increase calibration time and reduce the variance of the calibrated value. 0: 4 averages 1: 16 averages 2: 64 averages 3: 256 averages
1-0	SRC_HDUR	R/W	01	Specifies the duration of each high-speed accumulation for SYSREF Calibration. If the SYSREF period exceeds the supported value, the calibration fails. Larger values increase calibration time and support longer SYSREF periods. For a given SYSREF period, larger values also reduce the variance of the calibrated value. 0: 4 cycles per accumulation, max SYSREF period of 85 DEVCLK cycles 1: 16 cycles per accumulation, max SYSREF period of 1100 DEVCLK cycles 2: 64 cycles per accumulation, max SYSREF period of 5200 DEVCLK cycles 3: 256 cycles per accumulation, max SYSREF period of 21580 DEVCLK cycles Max duration of SYSREF calibration is bounded by: $T_{SYSREFCAL}$ (in DEVCLK cycles) = $256 \times 19 \times 4^{(SRC_AVG + SRC_HDUR + 2)}$

7.6.2.3 SYSREF Calibration Status Register (address = 0x2B2 to 0x2B4) [reset = Undefined]

Figure 149. SYSREF Calibration Status Register (SRC_STATUS)

23	22	21	20	19	18	17	16
RESERVED						SRC_DONE	SRC_TAD[16]
R						R	R
15	14	13	12	11	10	9	8
SRC_TAD[15:8]							
R							
7	6	5	4	3	2	1	0
SRC_TAD[7:0]							
R							

Table 111. SRC_STATUS Field Descriptions

Bit	Field	Type	Reset	Description
23-18	RESERVED	R	Undefined	RESERVED
17	SRC_DONE	R	Undefined	This bit returns a 1 when SRC_EN = 1 and SYSREF calibration is complete.
16-0	SRC_TAD	R	Undefined	This field returns the value for TAD[16:0] computed by the SYSREF calibration. This field is only valid if SRC_DONE = 1.

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7.6.2.4 DEVCLK Aperture Delay Adjustment Register (address = 0x2B5 to 0x2B7) [reset = 0x000000]

Figure 150. DEVCLK Aperture Delay Adjustment Register (TAD)

23	22	21	20	19	18	17	16
RESERVED							TAD_INV
R/W-0000 000							R/W-0
15	14	13	12	11	10	9	8
TAD_COARSE							
R/W-0000 0000							
7	6	5	4	3	2	1	0
TAD_FINE							
R/W-0000 0000							

Table 112. TAD Field Descriptions

Bit	Field	Type	Reset	Description
23-17	RESERVED	R/W	0000 000	RESERVED
16	TAD_INV	R/W	0	Invert DEVCLK by setting this bit equal to 1.
15-8	TAD_COARSE	R/W	0000 0000	This register controls the DEVCLK aperture delay adjustment when SRC_EN = 0. Use this register to manually control the DEVCLK aperture delay when SYSREF calibration is disabled. If ADC calibration or JESD204B is running, TI recommends gradually increasing or decreasing this value (1 code at a time) to avoid clock glitches. See the *Switching Characteristics* table for TAD_COARSE resolution.
7-0	TAD_FINE	R/W	0000 0000	See the *Switching Characteristics* table for TAD_FINE resolution.

7.6.2.5 DEVCLK Timing Adjust Ramp Control Register (address = 0x2B8) [reset = 0x00]

Figure 151. DEVCLK Timing Adjust Ramp Control Register (TAD_RAMP)

7	6	5	4	3	2	1	0
RESERVED						TAD_RAMP_RATE	TAD_RAMP_EN
R/W-0000 00						R/W-0	R/W-0

Table 113. TAD_RAMP Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R/W	0000 00	RESERVED
1	TAD_RAMP_RATE	R/W	0	Specifies the ramp rate for the TAD[15:8] output when the TAD[15:8] register is written when TAD_RAMP_EN = 1. 0: TAD[15:8] ramps up or down one code per 256 DEVCLK cycles. 1: TAD[15:8] ramps up or down 4 codes per 256 DEVCLK cycles.
0	TAD_RAMP_EN	R/W	0	TAD ramp enable. Set this bit if coarse TAD adjustments are desired to ramp up or down instead of changing abruptly. 0: After writing the TAD[15:8] register the aperture delay is updated within 1024 DEVCLK cycles 1: After writing the TAD[15:8] register the aperture delay ramps up or down until the aperture delay matches the TAD[15:8] register

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7.6.3 Alarm Registers (0x2C0 to 0x2C2)

Table 114. Alarm Registers

ADDRESS	RESET	ACRONYM	REGISTER NAME	SECTION
0x2C0	Undefined	ALARM	Alarm Interrupt Status Register	Alarm Interrupt Register (address = 0x2C0) [reset = Undefined]
0x2C1	0x1F	ALM_STATUS	Alarm Status Register	Alarm Status Register (address = 0x2C1) [reset = 0x1F]
0x2C2	0x1F	ALM_MASK	Alarm Mask Register	Alarm Mask Register (address = 0x2C2) [reset = 0x1F]

7.6.3.1 Alarm Interrupt Register (address = 0x2C0) [reset = Undefined]

Figure 152. Alarm Interrupt Register (ALARM)

7	6	5	4	3	2	1	0
RESERVED							ALARM
R							R

Table 115. ALARM Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R	Undefined	RESERVED
0	ALARM	R	Undefined	This bit returns a 1 whenever any alarm occurs that is unmasked in the ALM_STATUS register. Use ALM_MASK to mask (disable) individual alarms. CAL_STATUS_SEL can be used to drive the ALARM bit onto the CALSTAT output pin to provide a hardware alarm interrupt signal.

7.6.3.2 Alarm Status Register (address = 0x2C1) [reset = 0x1F]

Figure 153. Alarm Status Register (ALM_STATUS)

7	6	5	4	3	2	1	0
RESERVED			PLL_ALM	LINK_ALM	REALIGNED_ALM	RESERVED	CLK_ALM
R/W-000			R/W-1	R/W-1	R/W-1	R/W-1	R/W-1

Table 116. ALM_STATUS Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	RESERVED
4	PLL_ALM	R/W	1	PLL lock lost alarm. This bit is set whenever the PLL is not locked. Write a 1 to clear this bit.
3	LINK_ALM	R/W	1	Link alarm. This bit is set whenever the JESD204B link is enabled, but is not in the DATA_ENC state. Write a 1 to clear this bit.
2	REALIGNED_ALM	R/W	1	Realigned alarm. This bit is set whenever SYSREF causes the internal clocks (including the LMFC) to be realigned. Write a 1 to clear this bit.
1	RESERVED	R/W	1	RESERVED
0	CLK_ALM	R/W	1	Clock alarm. This bit can be used to detect an upset to the digital block and JESD204B clocks. This bit is set whenever the internal clock dividers for the A and B channels do not match. Write a 1 to clear this bit.

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7.6.3.3 Alarm Mask Register (address = 0x2C2) [reset = 0x1F]

Figure 154. Alarm Mask Register (ALM_MASK)

7	6	5	4	3	2	1	0
RESERVED			MASK_PLL_ALM	MASK_LINK_ALM	MASK_REALIGNED_ALM	MASK_NCO_ALM	MASK_CLK_ALM
R/W-000			R/W-1	R/W-1	R/W-1	R/W-1	R/W-1

Table 117. ALM_MASK Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	RESERVED
4	MASK_PLL_ALM	R/W	1	When set, PLL_ALM is masked and does not impact the ALARM register bit.
3	MASK_LINK_ALM	R/W	1	When set, LINK_ALM is masked and does not impact the ALARM register bit.
2	MASK_REALIGNED_ALM	R/W	1	When set, REALIGNED_ALM is masked and does not impact the ALARM register bit.
1	MASK_NCO_ALM	R/W	1	When set, NCO_ALM is masked and does not impact the ALARM register bit.
0	MASK_CLK_ALM	R/W	1	When set, CLK_ALM is masked and does not impact the ALARM register bit.

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8 Application and Implementation

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Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The ADC08DJ3200 can be used in a wide range of applications including radar, satellite communications, test equipment (communications testers and oscilloscopes), and software-defined radios (SDRs). The wide input bandwidth enables direct RF sampling to at least 8 GHz and the high sampling rate allows signal bandwidths of greater than 2 GHz. The *Typical Applications* section describes one configuration that meets the needs of a number of these applications.

8.2 Typical Applications

8.2.1 Wideband RF Sampling Receiver

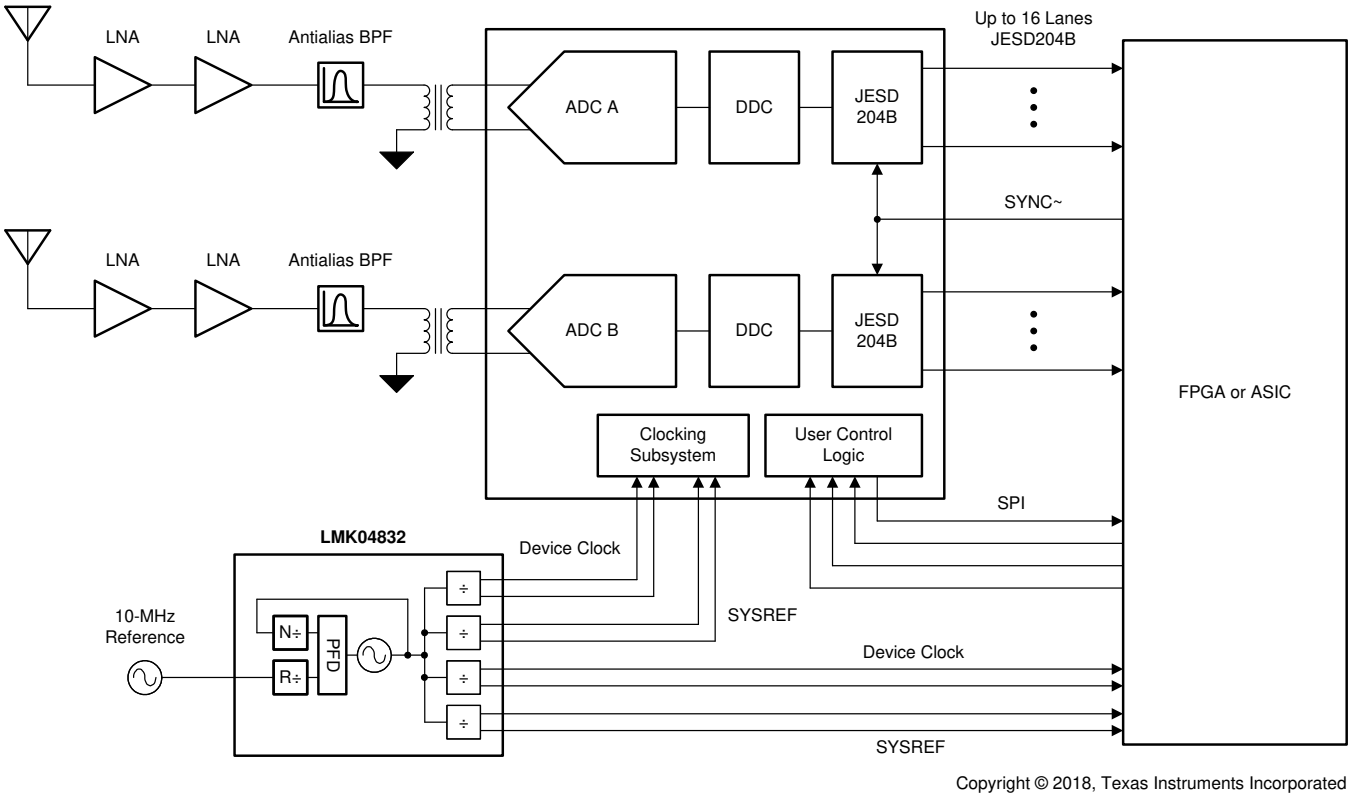


图 155. Typical Configuration for Wideband RF Sampling

8.2.1.1 Design Requirements

8.2.1.1.1 Input Signal Path

Use appropriate band-limiting filters to reject unwanted frequencies in the input signal path.

A 1:2 balun transformer is needed to convert the 50-Ω, single-ended signal to 100-Ω differential for input to the ADC. The balun outputs can be either AC-coupled, or directly connected to the ADC differential inputs, which are terminated internally to GND.

Typical Applications (接下页)

Drivers must be selected to provide any needed signal gain and that have the necessary bandwidth capabilities.

Baluns must be selected to cover the needed frequency range, have a 1:2 impedance ratio, and have acceptable gain and phase balance over the frequency range of interest. 表 118 lists a number of recommended baluns for different frequency ranges.

表 118. Recommended Baluns

PART NUMBER	MANUFACTURER(1)	MINIMUM FREQUENCY (MHz)	MAXIMUM FREQUENCY (MHz)
BAL-0009SMG	Marki Microwave	0.5	9000
BAL-0208SMG	Marki Microwave	2000	8000
TCM2-43X+	Mini-Circuits	10	4000
TCM2-33WX+	Mini-Circuits	10	3000
B0430J50100AHF	Anaren	400	3000

(1) See the *Third-Party Products Disclaimer* section.

8.2.1.1.2 Clocking

The ADC08DJ3200 clock inputs must be AC-coupled to the device to ensure rated performance. The clock source must have extremely low jitter (integrated phase noise) to enable rated performance. Recommended clock synthesizers include the LMX2594, LMX2592, and LMX2582.

The JESD204B data converter system (ADC plus FPGA) requires additional SYSREF and device clocks. The LMK04828, LMK04826, and LMK04821 devices are suitable to generate these clocks. Depending on the ADC clock frequency and jitter requirements, this device may also be used as the system clock synthesizer or as a device clock and SYSREF distribution device when multiple ADC08DJ3200 devices are used in a system.

8.2.1.2 Detailed Design Procedure

Certain component values used in conjunction with the ADC08DJ3200 must be calculated based on system parameters. Those items are covered in this section.

8.2.1.2.1 Calculating Values of AC-Coupling Capacitors

AC-coupling capacitors are used in the input CLK± and JESD204B output data pairs. The capacitor values must be large enough to address the lowest frequency signals of interest, but not so large as to cause excessively long startup biasing times, or unwanted parasitic inductance.

The minimum capacitor value can be calculated based on the lowest frequency signal that is transferred through the capacitor. Given a 50-Ω single-ended clock or data path impedance, good practice is to set the capacitor impedance to be <1 Ω at the lowest frequency of interest. This setting ensures minimal impact on signal level at that frequency. For the CLK± path, the minimum-rated clock frequency is 800 MHz. Therefore, the minimum capacitor value can be calculated from:

$$Z_C = 1/(2 \times \pi \times f_{CLK} \times C) \quad (4)$$

Setting Z_c = 1 Ω and rearranging gives:

$$C = 1/(2 \times \pi \times 800\ \text{MHz} \times 1\ \Omega) = 199\ \text{pF} \quad (5)$$

Therefore, a capacitance value of at least 199 pF is needed to provide the low-frequency response for the CLK± path. If the minimum clock frequency is higher than 800 MHz, this calculation can be revisited for that frequency. Similar calculations can be done for the JESD204B output data capacitors based on the minimum frequency in that interface. Capacitors must also be selected for good response at high frequencies, and with dimensions that match the high-frequency signal traces they are connected to. Capacitors of the 0201 size are frequently well suited to these applications.

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8.2.1.3 Application Curves

The ADC08DJ3200 can be used in a number of different operating modes to suit multiple applications. 图 156 to 图 157 describe operation with a 497.77-MHz input signal in the following configurations:

- 6.4-GSPS, single-input mode, JMODE5
- 6.4-GSPS, dual-input mode, JMODE7

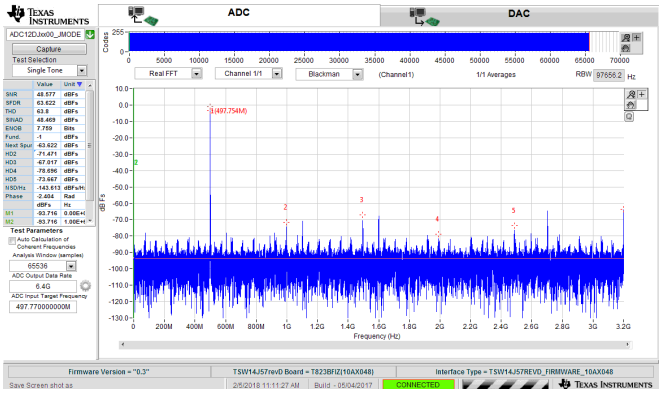


图 156. FFT for 497.77-MHz Input Signal, 6.4 GSPS, JMODE5

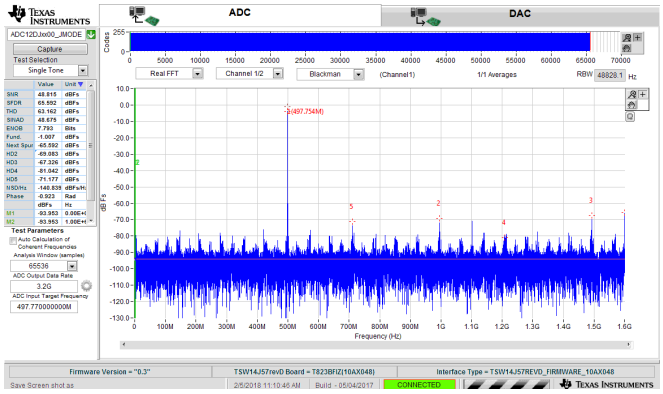


图 157. FFT for 497.77-MHz Input Signal, 3.2 GSPS, JMODE7

8.2.2 Reconfigurable Dual-Channel 2.5-GSPS or Single-Channel 5.0-Gsps Oscilloscope

This section demonstrates the use of the ADC08DJ3200 in a reconfigurable oscilloscope. The oscilloscope can operate as a dual-channel oscilloscope running at 2.5 GSPS or can be reconfigured through SPI programming as a single-channel, 5-GSPS oscilloscope. This reconfigurable setup allows users to trade off the number of channels and the sampling rate of the oscilloscope as needed without changing the hardware. Set the input bandwidth to the desired maximum signal bandwidth through the use of an antialiasing, low-pass filter. Digital filtering can then be used to reconfigure the analog bandwidth as required. For instance, the maximum bandwidth can be set to 1 GHz for use during pulsed transient detection and then reconfigured to 100 MHz through digital filtering for low-noise, sine-wave observation. 图 158 shows the application block diagram.

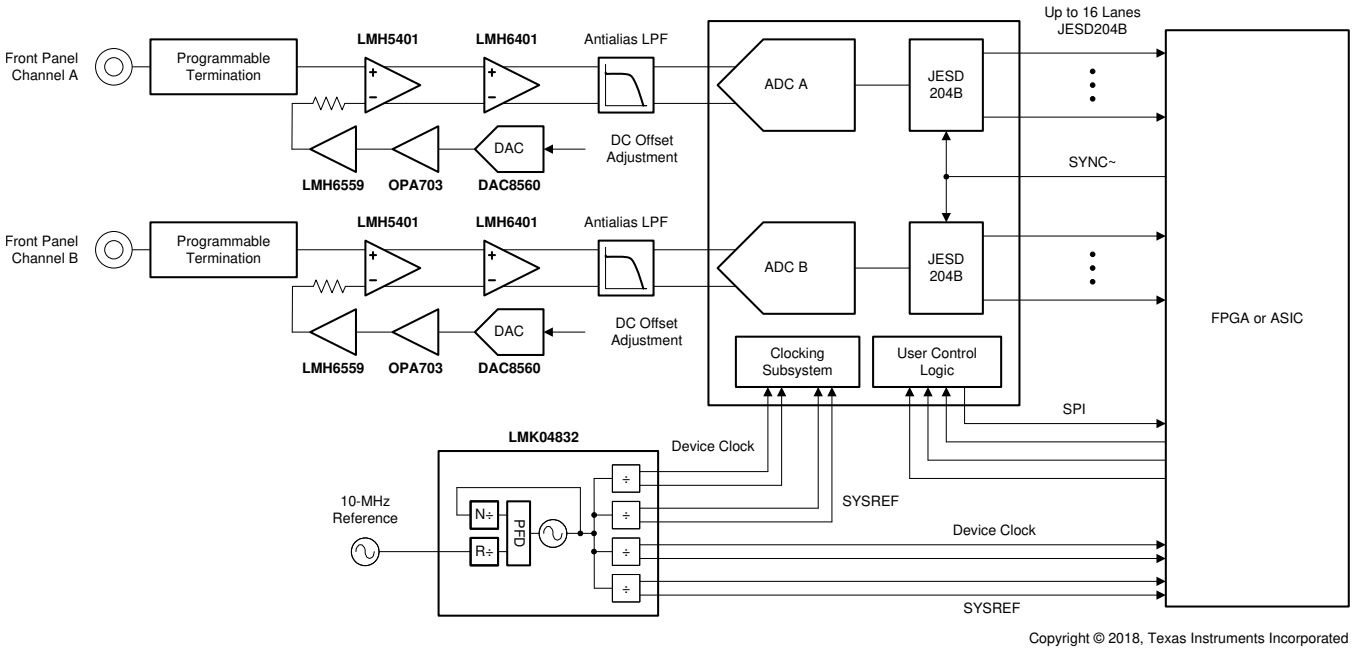


图 158. Typical Configuration for Reconfigurable Oscilloscope

8.2.2.1 Design Requirements

8.2.2.1.1 Input Signal Path

Most oscilloscopes are required to be DC-coupled in order to monitor DC or low-frequency signals. This requirement forces the design to use DC-coupled, fully differential amplifiers to convert from single-ended signaling at the front panel to differential signaling at the ADC. This design uses two differential amplifiers. The first amplifier shown in 图 158 is the LMH5401 that converts from single-ended to differential signaling. The LMH5401 interfaces with the front panel through a programmable termination network and has an offset adjustment input. The amplifier has an 8-GHz, gain-bandwidth product that is sufficient to support a 1-GHz bandwidth oscilloscope. A second amplifier, the LMH6401, comes after the LMH5401 to provide a digitally programmable gain control for the oscilloscope. The LMH6401 supports a gain range from –6 dB to 26 dB in 1-dB steps. If gain control is not necessary or is performed in a different location in the signal chain, then this amplifier can be replaced with a second LMH5401 for additional fixed gain or omitted altogether.

The input of the oscilloscope contains a programmable termination block that is not covered in detail here. This block enables the front-panel input termination to be programmed. For instance, many oscilloscopes allow the termination to be programmed as either 50-Ω or 1-MΩ to meet the needs of various applications. A 75-Ω termination can also be desired to support cable infrastructure use cases. This block can also contain an option for DC blocking to remove the DC component of the external signal and therefore pass only AC signals.

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A precision DAC is used to configure the offset of the oscilloscope front-end to prevent saturation of the analog signal chain for input signals containing large DC offsets. The DAC8560 is shown in 图 158 along with signal-conditioning amplifiers OPA703 and LMH6559. The first differential amplifier, LMH5401, is driven by the front panel input circuitry on one input, and the DC offset bias on the second input. The impedance of these driving signals must be matched at DC and over frequency to ensure good even-order harmonic performance in the single-ended to differential conversion operation. The high bandwidth of the LMH6559 allows the device to maintain low impedance over a wide frequency range.

An antialiasing, low-pass filter is positioned at the input of the ADC to limit the bandwidth of the input signal into the ADC. This amplifier also band-limits the front-end noise to prevent aliased noise from degrading the signal-to-noise ratio of the overall system. Design this filter for the maximum input signal bandwidth specified by the oscilloscope. The input bandwidth can then be reconfigured through the use of digital filters in the FPGA or ASIC to limit the oscilloscope input bandwidth to a bandwidth less than the maximum.

8.2.2.1.2 Clocking

The ADC08DJ3200 clock inputs must be AC-coupled to the device to ensure rated performance. The clock source must have extremely low jitter (integrated phase noise) to enable rated performance. Recommended clock synthesizers include the LMX2594, LMX2592, and LMX2582.

The JESD204B data converter system (ADC plus FPGA) requires additional SYSREF and device clocks. The LMK04832, LMK04828, LMK04826, and LMK04821 devices are suitable to generate these clocks. Depending on the ADC clock frequency and jitter requirements, this device can also be used as the system clock synthesizer or as a device clock and SYSREF distribution device when multiple ADC08DJ3200 devices are used in a system.

8.2.2.1.3 ADC08DJ3200

The ADC08DJ3200 is ideally suited for oscilloscope applications. The ability to tradeoff channel count and sampling speed allows designers to build flexible hardware to meet multiple needs. This flexibility saves development time and cost, allows hardware reuse for various projects and enables software upgrade paths for additional functionality. The low code-error rate eliminates concerns about undesired time domain glitches or sparkle codes. This rate makes the ADC08DJ3200 a perfect fit for long-duration transient detection measurements and reduces the probability of false triggers. The input common-mode voltage of 0 V allows the driving amplifiers to use equal split power supplies that center the amplifier output common-mode voltage at 0 V and eliminates the need for common-mode voltage shifting before the ADC inputs. The high input bandwidth of the ADC08DJ3200 simplifies the design of the driving amplifier circuit and antialiasing, low-pass filter. The use of dual-edge sampling (DES) in single-channel mode eliminates the need to change the clock frequency when switching between dual- and single-channel modes and simplifies synchronization by relaxing the setup and hold timing requirements of SYSREF. The t_{AD} adjust circuit allows the user to time-align the sampling instances of multiple ADC08DJ3200 devices.

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8.2.2.2 Application Curves

The following application curves demonstrate performance and results only of the ADC. The amplifier front-end is not included in these measurements. The following configurations and measurements are shown in 图 159 to 图 165:

- 8-bit, 5-GSPS, single-channel oscilloscope using JMODE4 (4 lanes at 12.5 Gbps)
  - Idle-channel noise (no input)
  - 40-MHz, square-wave time domain
  - 200-MHz, sine-wave time domain
  - 200-MHz, sine-wave frequency domain (FFT)
- 8-bit, 2.5-GSPS, dual-channel oscilloscope using JMODE6 (4 lanes at 12.5 Gbps)
  - Idle-channel noise (no input)
  - 40-MHz, square-wave (channel B) and 200-MHz, sine-wave (channel A) time domain
  - 40-MHz, square-wave (channel B) time domain and 200-MHz, sine-wave (channel A) frequency domain (FFT)

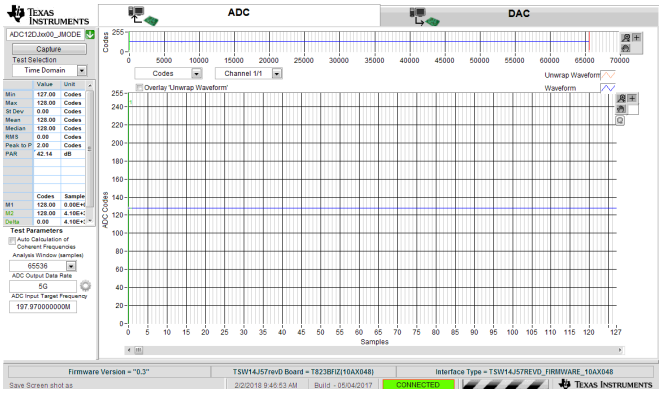


图 159. Idle-Channel Noise (No Input) for 5-GSPS, Single-Channel Oscilloscope

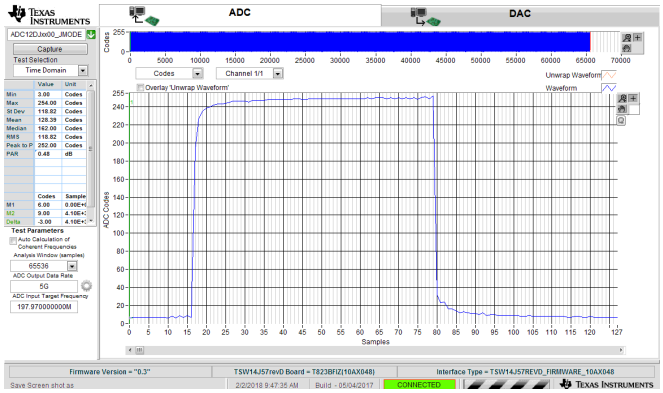


图 160. 40-MHz, Square-Wave Time Domain for 5-GSPS, Single-Channel Oscilloscope

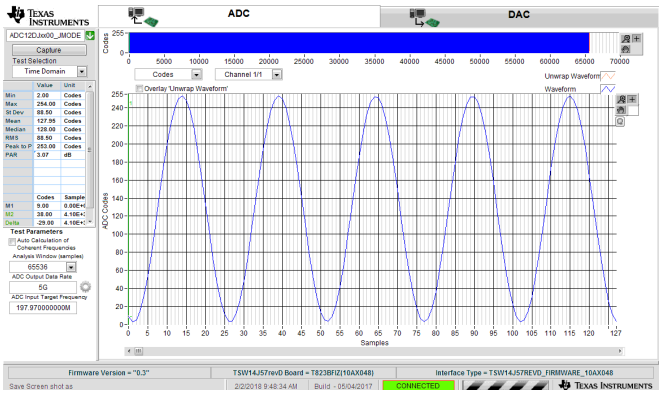


图 161. 200-MHz, Sine-Wave Time Domain for 5-GSPS, Single-Channel Oscilloscope

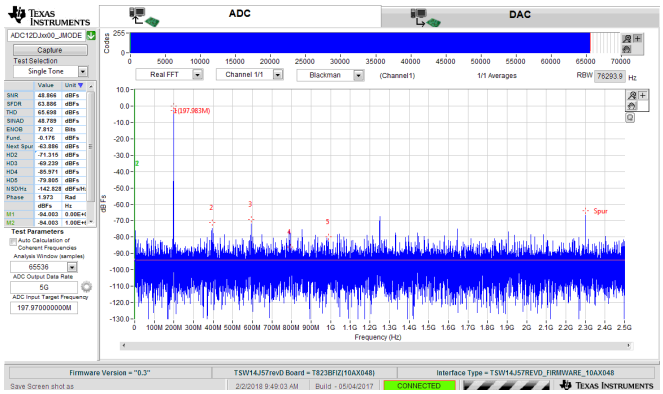


图 162. 200-MHz, Sine-Wave Frequency Domain (FFT) for 5-GSPS, Single-Channel Oscilloscope

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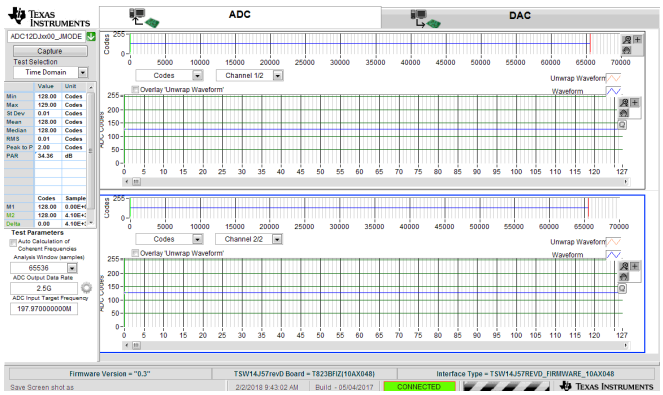


图 163. Idle-Channel Noise (No Input) for 2.5-GSPS, Dual-Channel Oscilloscope

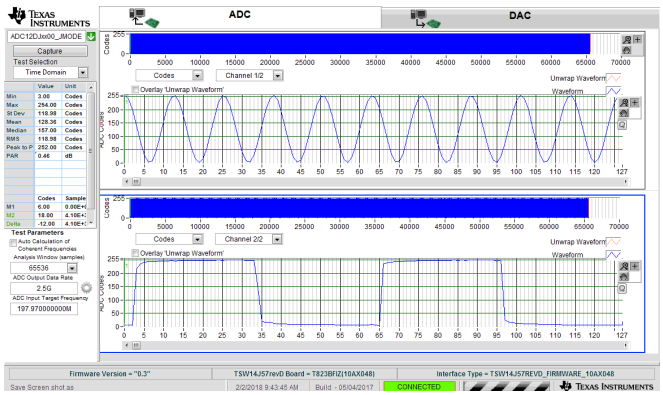


图 164. 200-MHz, Sine-Wave (Channel A) and 40-MHz, Square-Wave (Channel B) Time Domain for 5-GSPS, Single-Channel Oscilloscope

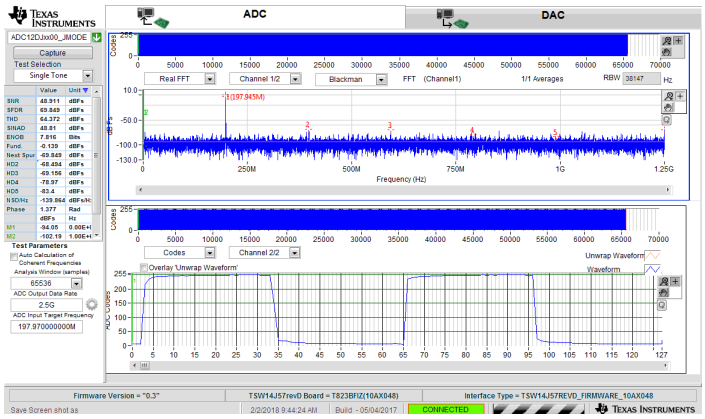


图 165. 200-MHz, Sine-Wave (Channel A) Frequency Domain (FFT) and 40-MHz, Square-Wave (Channel B) Time Domain for 5-GSPS, Single-Channel Oscilloscope

8.3 Initialization Set Up

The device and JESD204 interface require a specific startup and alignment sequence. The general order of that sequence is listed in the following steps.

1. Power-up or reset the device.
2. Apply a stable device CLK signal at the desired frequency.
3. Program JESD_EN = 0 to stop the JESD204B state machine and allow setting changes.
4. Program CAL_EN = 0 to stop the calibration state machine and allow setting changes.
5. Program the desired JMODE.
6. Program the desired KM1 value. KM1 = K–1.
7. Program SYNC_SEL as needed. Choose SYNCSE or timestamp differential inputs.
8. Configure device calibration settings as desired. Select foreground or background calibration modes and offset calibration as needed.
9. Program CAL_EN = 1 to enable the calibration state machine.
10. Enable overrange via OVR_EN and adjust settings if desired.
11. Program JESD_EN = 1 to re-start the JESD204B state machine and allow the link to restart.
12. The JESD204B interface operates in response to the applied SYNC signal from the receiver.
13. Program CAL_SOFT_TRIG = 0.
14. Program CAL_SOFT_TRIG = 1 to initiate a calibration.

9 Power Supply Recommendations

The device requires two different power-supply voltages. 1.9 V DC is required for the VA19 power bus and 1.1 V DC is required for the VA11 and VD11 power buses.

The power-supply voltages must be low noise and provide the needed current to achieve rated device performance.

There are two recommended power supply architectures:

1. Step down using high-efficiency switching converters, followed by a second stage of regulation to provide switching noise reduction and improved voltage accuracy.
2. Directly step down the final ADC supply voltage using high-efficiency switching converters. This approach provides the best efficiency, but care must be taken to ensure switching noise is minimized to prevent degraded ADC performance.

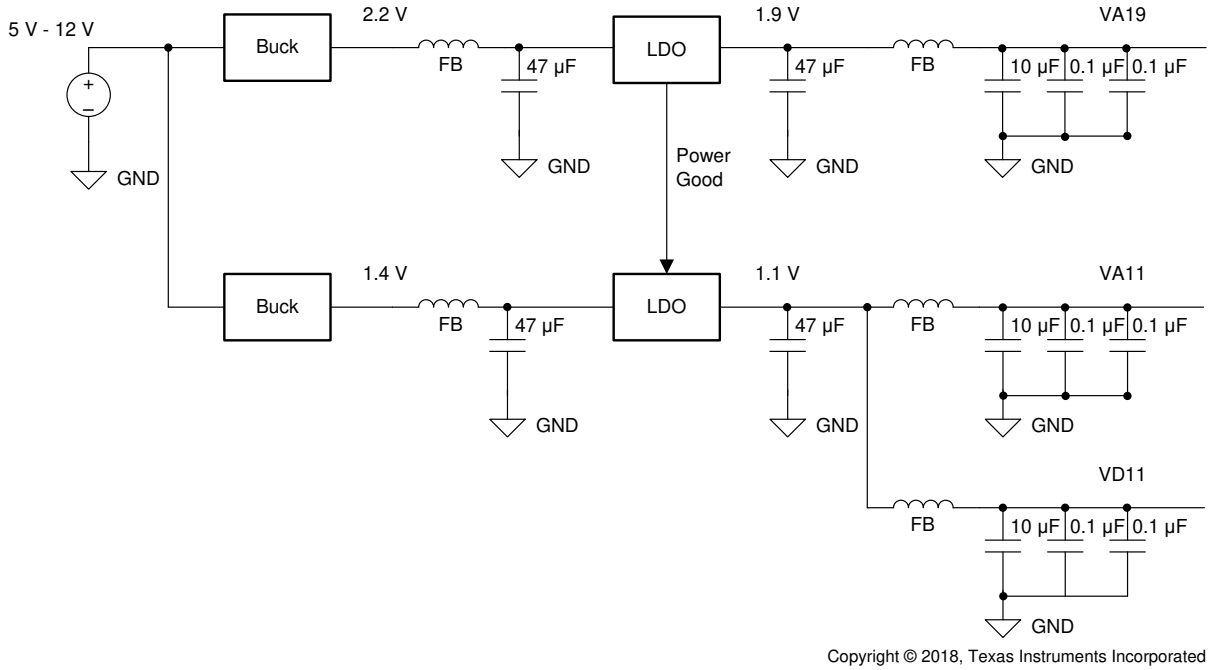
TI WEBENCH® Power Designer can be used to select and design the individual power supply elements needed: see the WEBENCH® Power Designer

Recommended switching regulators for the first stage include the TPS62085, TPS82130, TPS62130A, and similar devices.

Recommended Low Drop-Out (LDO) linear regulators include the TPS7A7200, TPS74401, and similar devices.

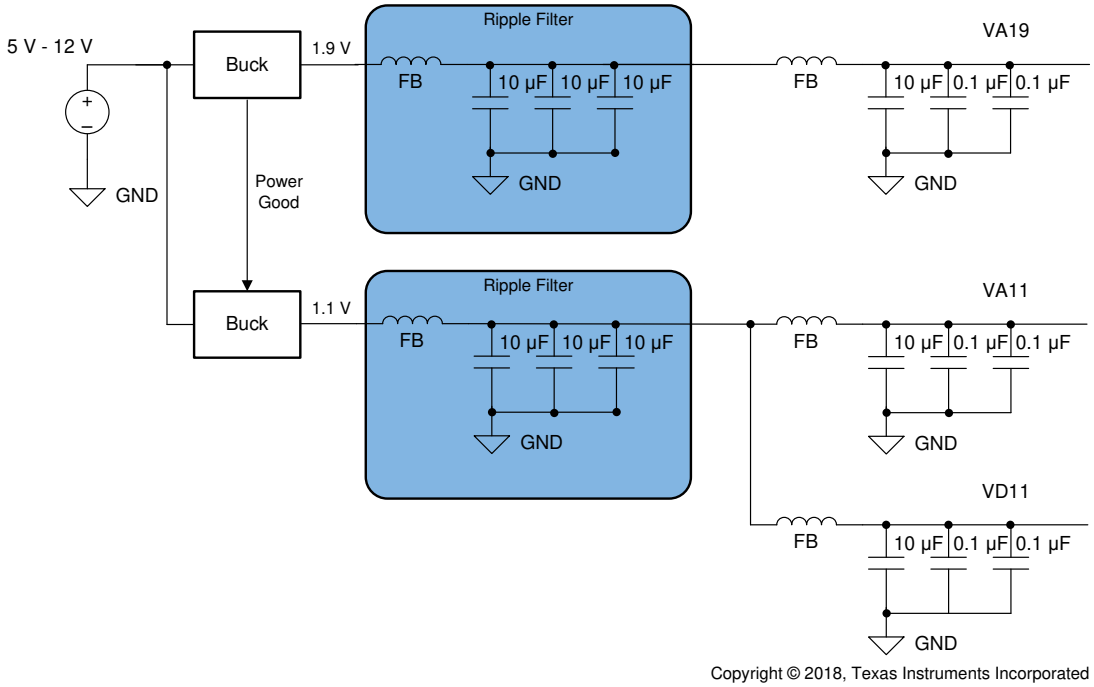
For the switcher only approach, the ripple filter must be designed with a notch frequency that aligns with the switching ripple frequency of the DC-DC converter. Make a note of the switching frequency reported from WEBENCH® and design the EMI filter and capacitor combination to have the notch frequency centered as needed. 图 166 and 图 167 illustrate the two approaches.

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NOTE: FB = ferrite bead filter.

图 166. LDO Linear Regulator Approach Example



NOTE: Ripple filter notch frequency to match the fs of the buck converter.

NOTE: FB = ferrite bead filter.

图 167. Switcher-Only Approach Example

9.1 Power Sequencing

The voltage regulators must be sequenced using the power-good outputs and enable inputs to ensure that the Vx11 regulator is enabled after the VA19 supply is good. Similarly, as soon as the VA19 supply drops out of regulation on power-down, the Vx11 regulator is disabled.

The general requirement for the ADC is that VA19 ≥ Vx11 during power-up, operation, and power-down.

TI also recommends that VA11 and VD11 are derived from a common 1.1-V regulator. This recommendation ensures that all 1.1-V blocks are at the same voltage, and no sequencing problems exist between these supplies. Also use ferrite bead filters to isolate any noise on the VA11 and VD11 buses from affecting each other.

10 Layout

10.1 Layout Guidelines

There are many critical signals that require specific care during board design:

1. Analog input signals
2. CLK and SYSREF
3. JESD204B data outputs:
    1. Lower eight pairs operating at up to 12.8 Gbit per second
    2. Upper eight pairs operating at up to 6.4 Gbit per second
4. Power connections
5. Ground connections

Items 1, 2, and 3 must be routed for excellent signal quality at high frequencies. Use the following general practices:

1. Route using loosely coupled 100-Ω differential traces. This routing minimizes impact of corners and length-matching serpentines on pair impedance.
2. Provide adequate pair-to-pair spacing to minimize crosstalk.
3. Provide adequate ground plane pour spacing to minimize coupling with the high-speed traces.
4. Use smoothly radiused corners. Avoid 45- or 90-degree bends.
5. Incorporate ground plane cutouts at component landing pads to avoid impedance discontinuities at these locations. Cut-out below the landing pads on one or multiple ground planes to achieve a pad size or stackup height that achieves the needed 50-Ω, single-ended impedance.
6. Avoid routing traces near irregularities in the reference ground planes. Irregularities include ground plane clearances associated with power and signal vias and through-hole component leads.
7. Provide symmetrically located ground tie vias adjacent to any high-speed signal vias.
8. When high-speed signals must transition to another layer using vias, transition as far through the board as possible (top to bottom is best case) to minimize via stubs on top or bottom of the vias. If layer selection is not flexible, use back-drilled or buried, blind vias to eliminate stubs.

In addition, TI recommends performing signal quality simulations of the critical signal traces before committing to fabrication. Insertion loss, return loss, and time domain reflectometry (TDR) evaluations should be done.

The power and ground connections for the device are also very important. These rules must be followed:

1. Provide low-resistance connection paths to all power and ground pins.
2. Use multiple power layers if necessary to access all pins.
3. Avoid narrow isolated paths that increase connection resistance.
4. Use a signal, ground, or power circuit board stackup to maximum coupling between the ground and power planes.

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10.2 Layout Example

图 168 to 图 170 provide examples of the critical traces routed on the device evaluation module (EVM).

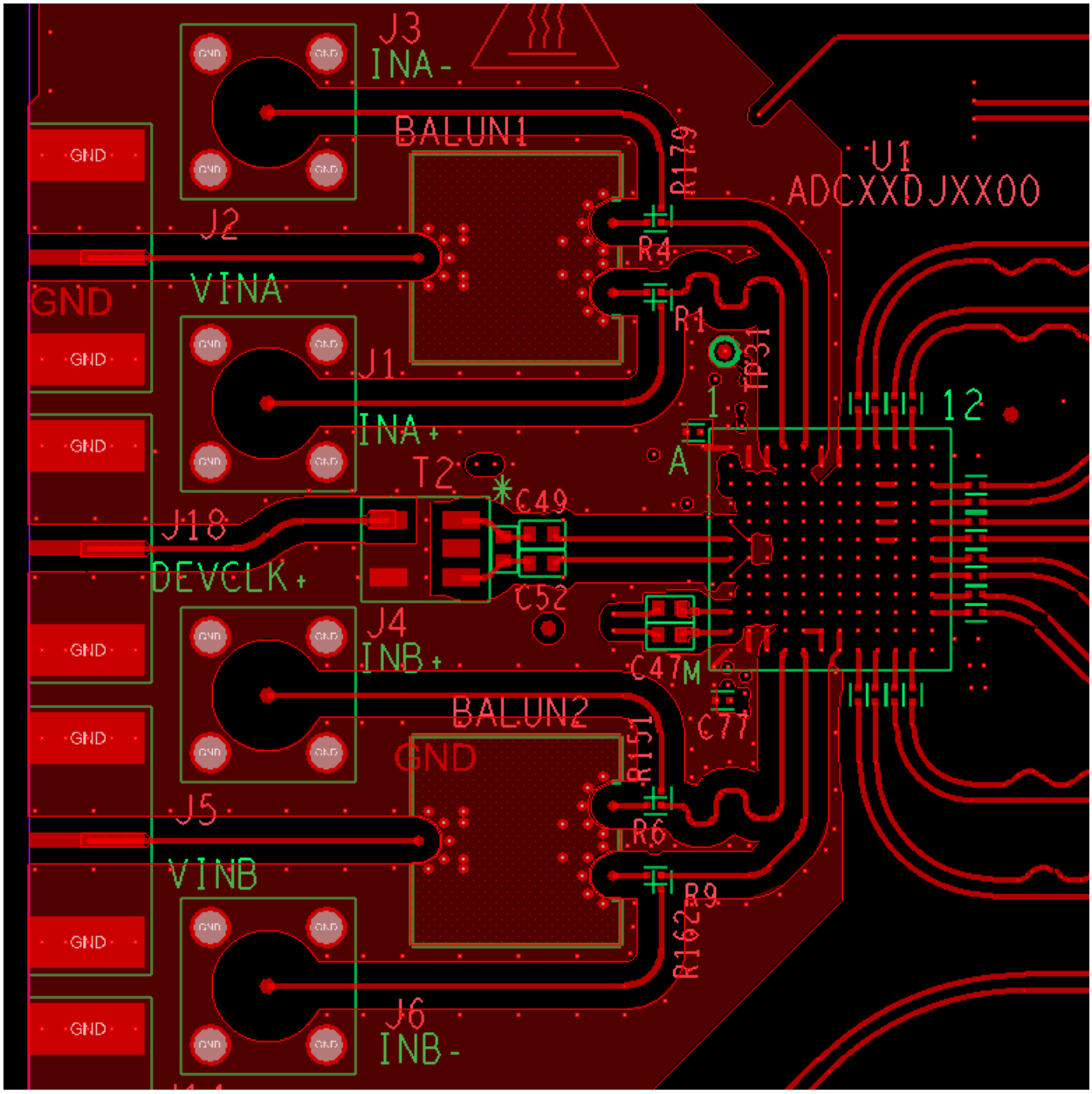


图 168. Top Layer Routing: Analog Inputs, CLK and SYSREF, DA0-3, DB0-3

Layout Example (接下页)

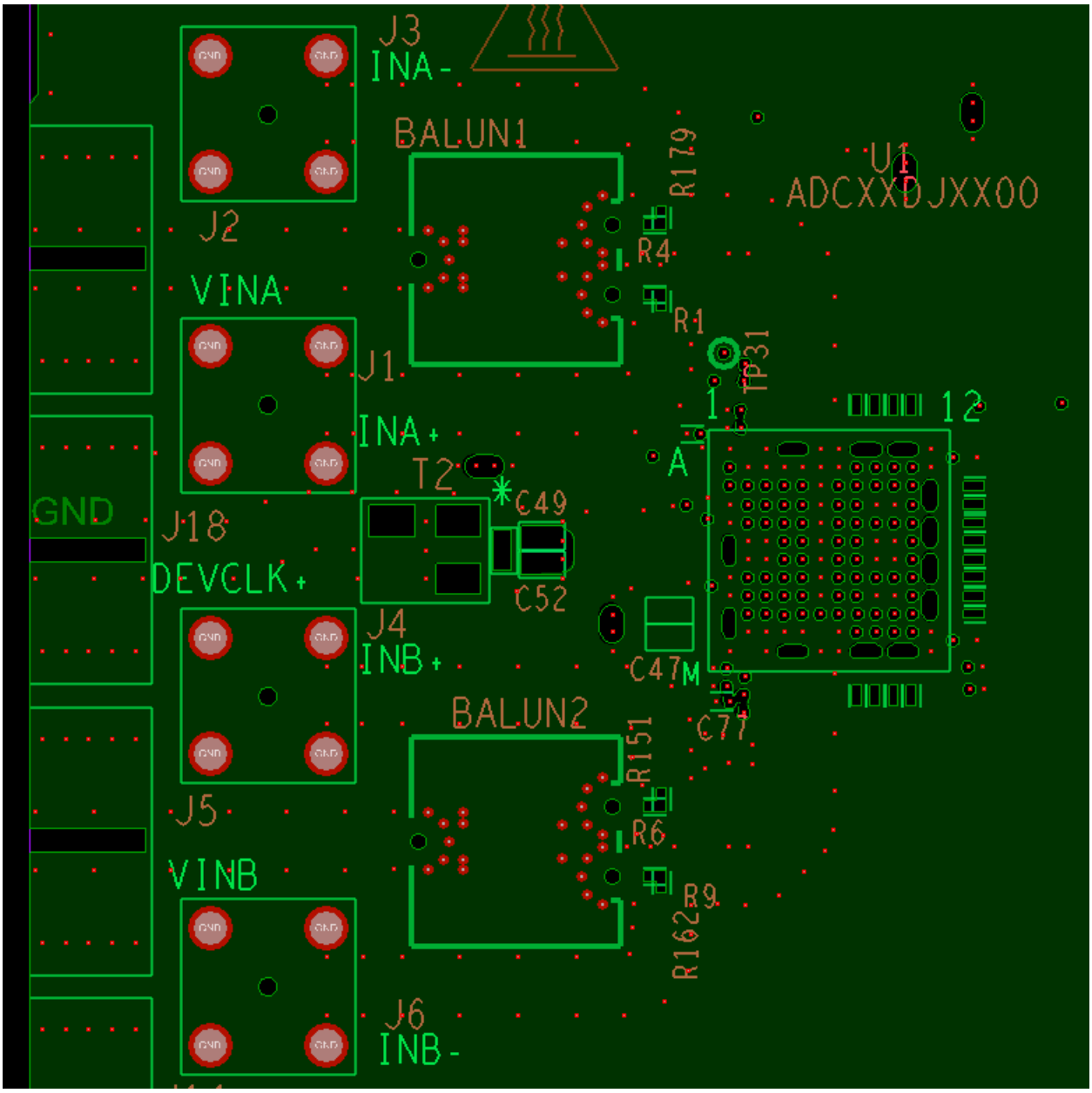


图 169. GND1 Cutouts to Optimize Impedance of Component Pads

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Layout Example (接下页)

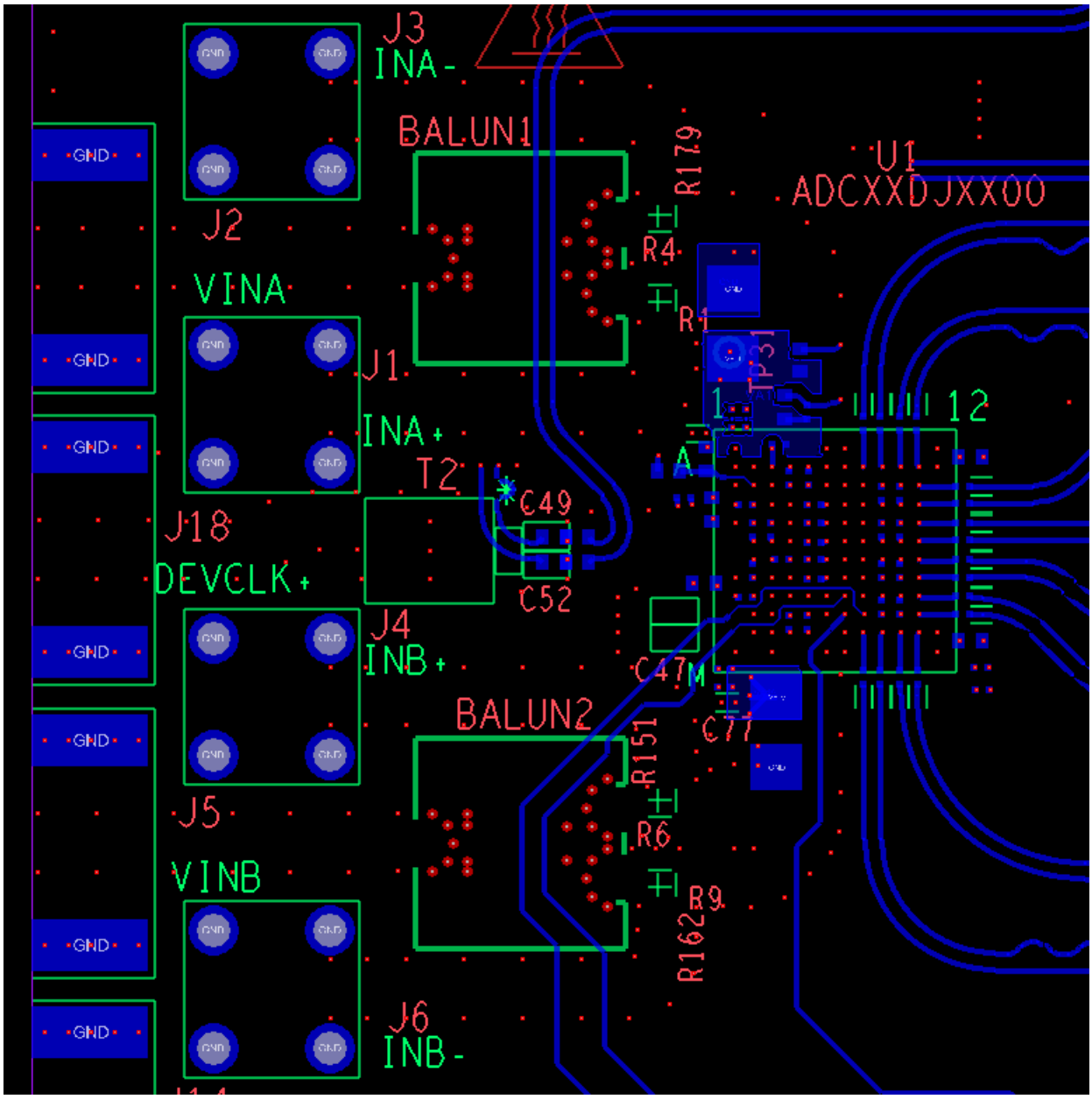


图 170. Bottom Layer Routing: Additional CLK Routing, DA4-7, DB4-7

11 器件和文档支持

11.1 器件支持

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11.1.2 开发支持

WEBENCH® 电源设计器

11.2 文档支持

11.2.1 相关文档

请参阅如下相关文档：

- 德州仪器 (TI)，*《JESD204B 多器件同步：将要求进行分解》*
- 德州仪器 (TI)，*《采用 SMBus 接口和 TruTherm™ 技术的 LM95233 双路远程二极管和本地温度传感器》*
- 德州仪器 (TI)，*《提供相位同步功能和 JESD204B 支持的 LMX2594 15GHz 宽带 PLLatinum™ 射频合成器》*
- 德州仪器 (TI)，*《具有集成型 VCO 的 LMX2592 高性能宽带 PLLatinum™ 射频合成器》*
- 德州仪器 (TI)，*《具有集成型 VCO 的 LMX2582 高性能宽带 PLLatinum™ 射频合成器》*
- 德州仪器 (TI)，*《具有双环路 PLL 且符合 JESD204B 标准的 LMK0482x 超低噪声时钟抖动消除器》*
- 德州仪器 (TI)，*《采用 2 × 2 QFN 封装且具有断续短路保护功能的 TPS6208x 3A 降压转换器》*
- 德州仪器 (TI)，*《具有集成电感器的 TPS82130 17V 输入电压、3A 降压转换器 MicroSiP™ 模块》*
- 德州仪器 (TI)，*《采用 3 x 3 QFN 封装的 TPS6213x 3V 至 17V、3A 降压转换器》*
- 德州仪器 (TI)，*《TPS7A7200 2A 快速瞬变低压降稳压器》*
- 德州仪器 (TI)，*《具有可编程软启动功能的 TPS74401 3.0A 超级 LDO》*
- 德州仪器 (TI)，*《采用 ADC12DJ3200 且适用于 L、S、C 和 X 带的直接射频采样雷达接收器参考设计》*
- 德州仪器 (TI)，*《ADC12DJ2700 评估模块》* 用户指南
- 德州仪器 (TI)，*《适用于 DSO、雷达和 5G 无线测试器的多通道 JESD204B 15GHz 时钟参考设计》*
- 德州仪器 (TI)，*《LMH5401 8GHz 低噪声、低功耗全差分放大器》*
- 德州仪器 (TI)，*《LMH6401 直流至 4.5GHz、全差分数字可变增益放大器》*
- 德州仪器 (TI)，*《具有 2.5V、2ppm/°C 内部基准的 DAC8560 16 位、超低干扰、电压输出数模转换器》*
- 德州仪器 (TI)，*《OPA70x CMOS 轨至轨 I/O 运算放大器》*
- 德州仪器 (TI)，*《LMH6559 高速闭环缓冲器》*
- 德州仪器 (TI)，*《具有双环路 PLL 的 LMK04832 超低噪声且符合 JESD204B 标准的时钟抖动清除器》*

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11.7 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ADC08DJ3200AAV	Active	Production	FCCSP (AAV) | 144	168 | JEDEC TRAY (10+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	ADC08DJ32
ADC08DJ3200AAV.A	Active	Production	FCCSP (AAV) | 144	168 | JEDEC TRAY (10+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	ADC08DJ32
ADC08DJ3200AAVT	Active	Production	FCCSP (AAV) | 144	250 | SMALL T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	ADC08DJ32
ADC08DJ3200AAVT.A	Active	Production	FCCSP (AAV) | 144	250 | SMALL T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	ADC08DJ32

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

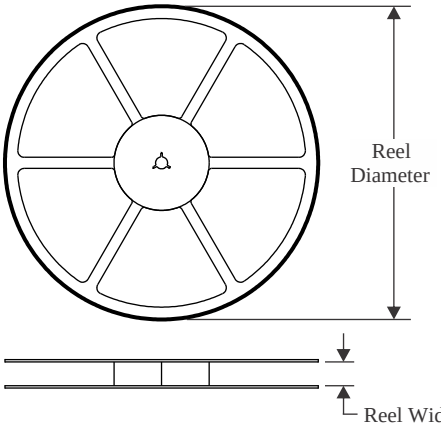
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

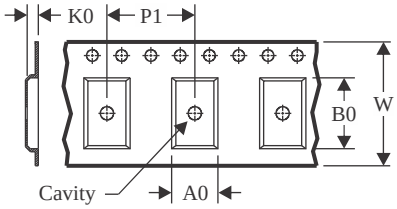
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

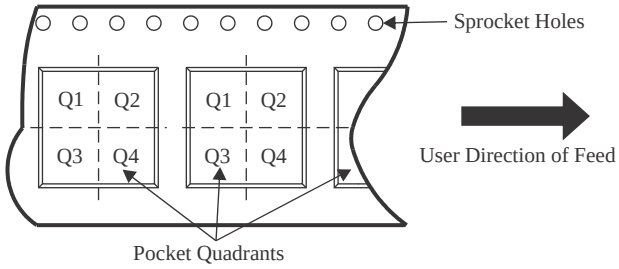


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

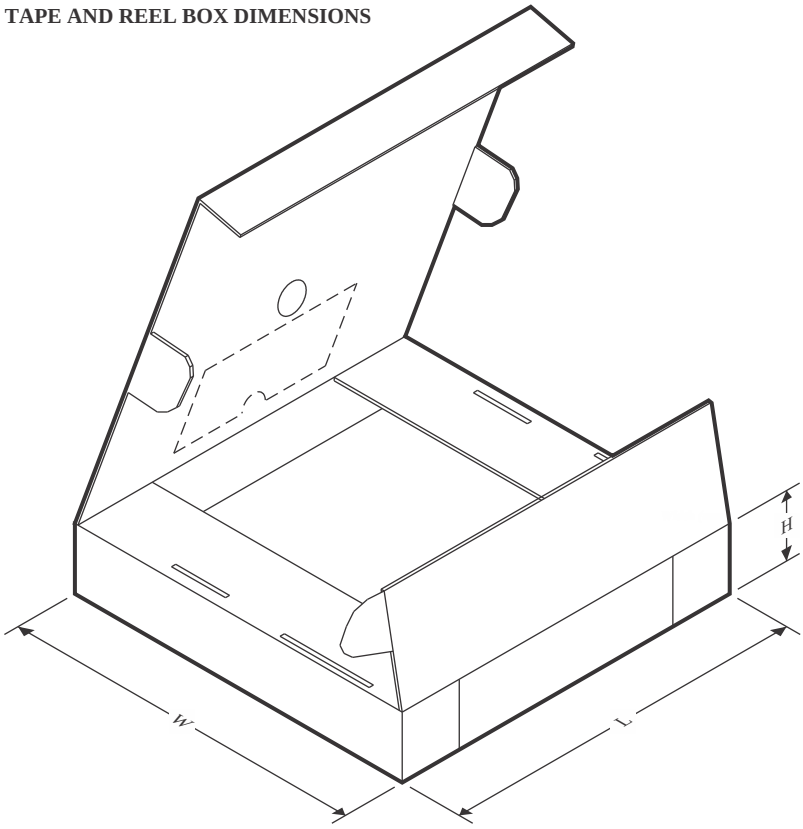
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADC08DJ3200AAVT	FCCSP	AAV	144	250	180.0	24.4	10.3	10.3	2.5	16.0	24.0	Q1

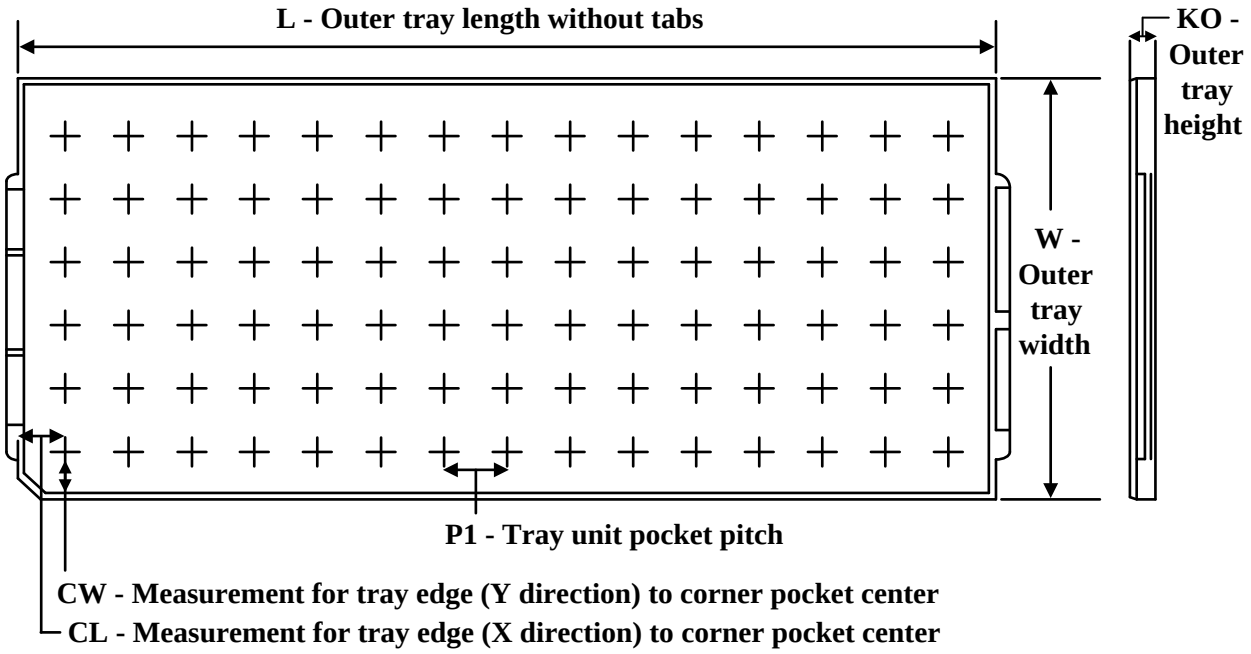
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADC08DJ3200AAVT	FCCSP	AAV	144	250	213.0	191.0	55.0

TRAY



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

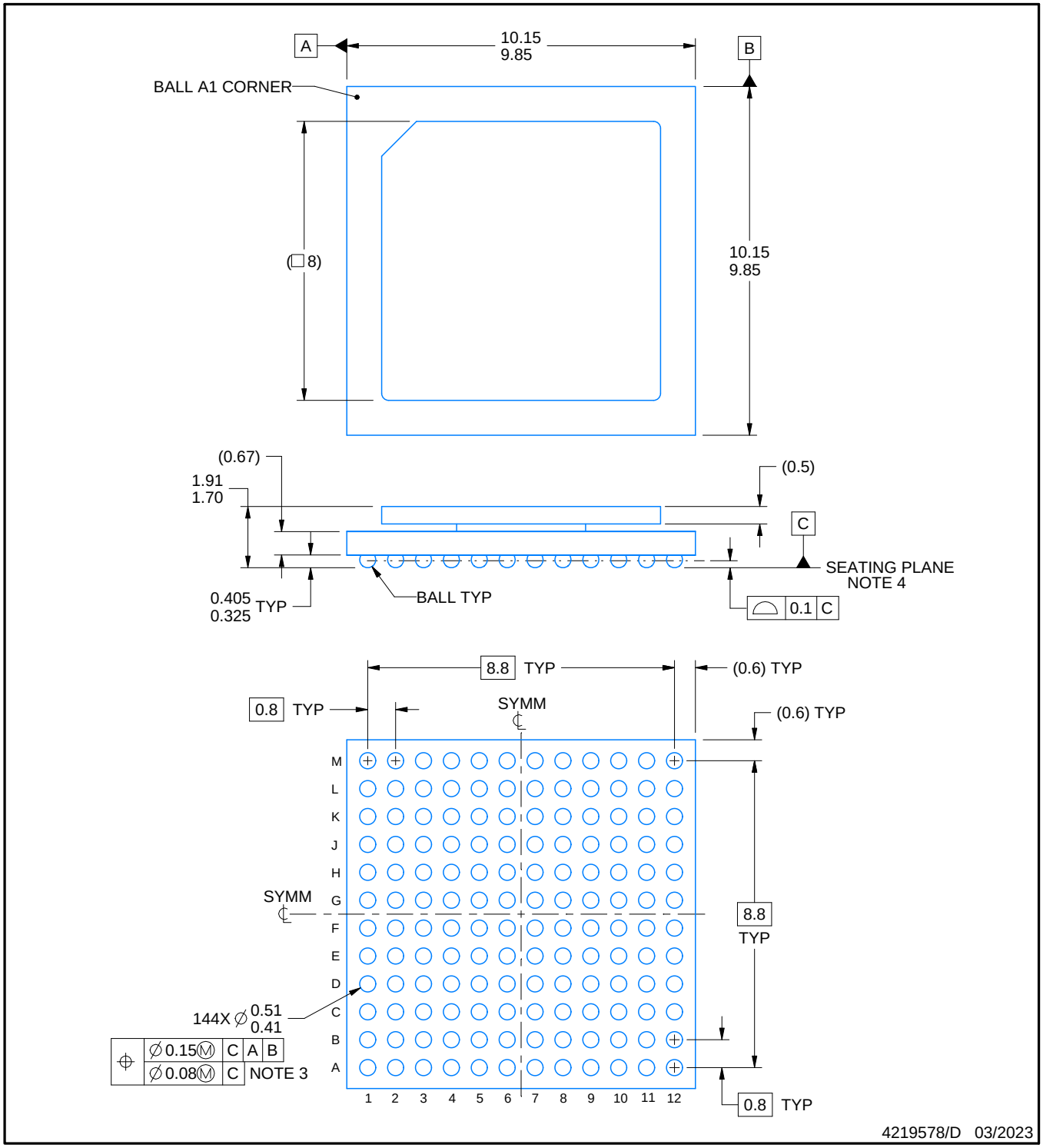
Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
ADC08DJ3200AAV	AAV	FCCSP	144	168	8 X 21	150	315	135.9	7620	14.65	11	11.95
ADC08DJ3200AAV.A	AAV	FCCSP	144	168	8 X 21	150	315	135.9	7620	14.65	11	11.95

AAV0144A

PACKAGE OUTLINE

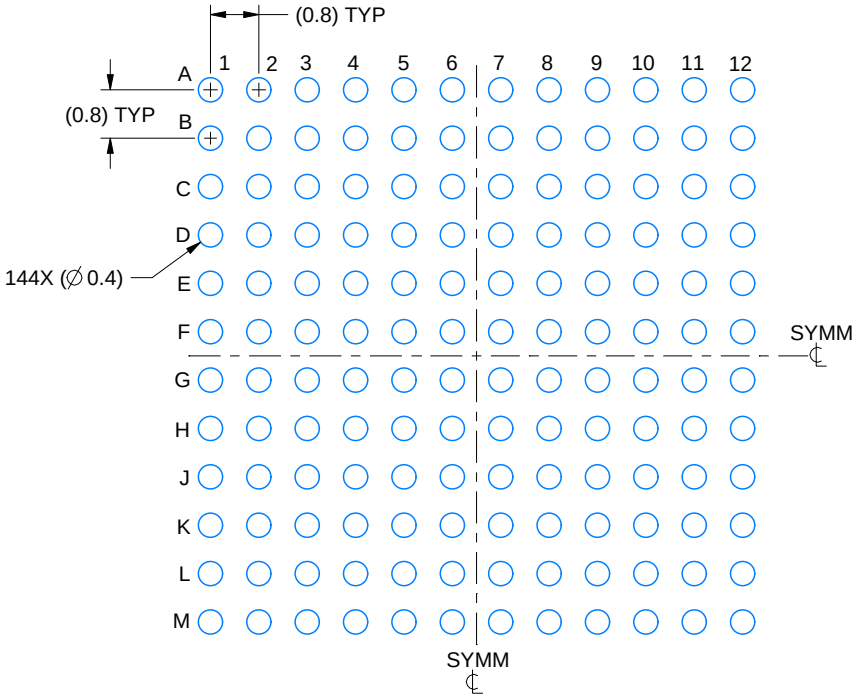
FCBGA - 1.91 mm max height

BALL GRID ARRAY

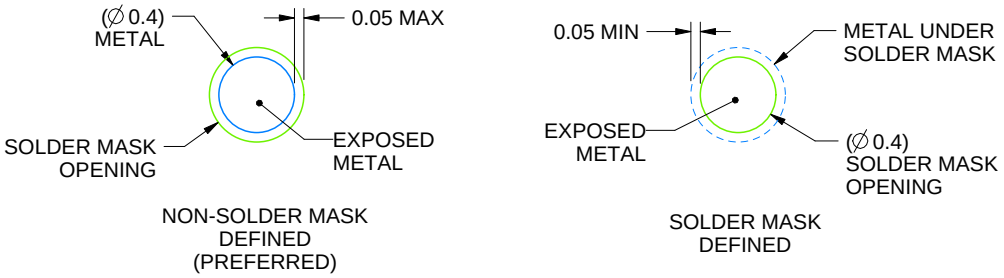


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
5. The lids are electrically floating (e.g. not tied to GND).



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

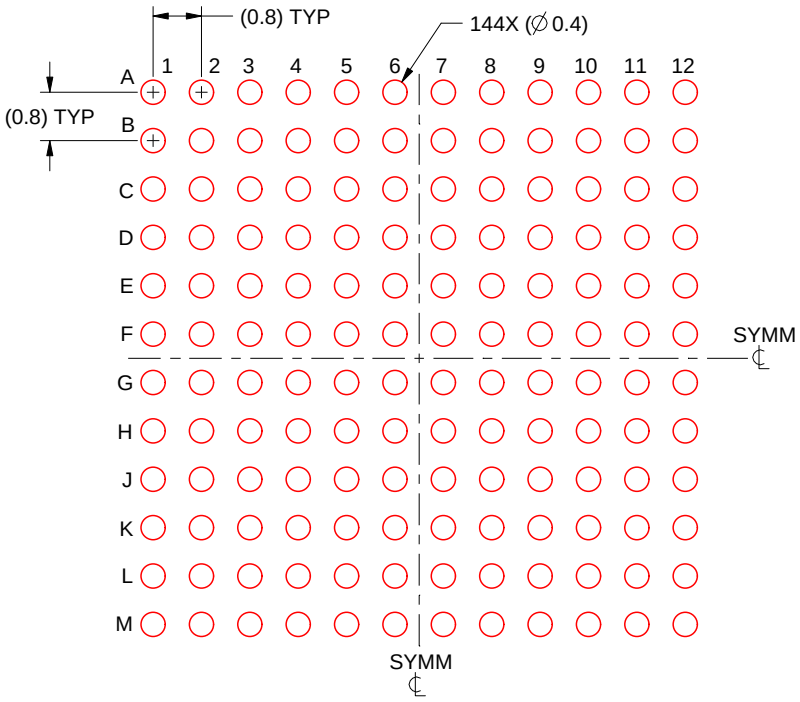


SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

6. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).



SOLDER PASTE EXAMPLE
BASED ON 0.15 mm THICK STENCIL
SCALE:8X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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